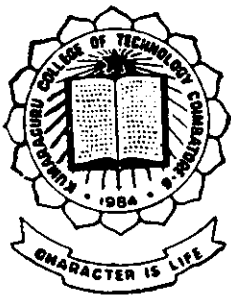


PC Based Co-Ordinate Location of a RCMT Board



Project Report

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1996 - 97

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CERTIFICATE

This is to certify that the Project Report entitled

**"PC BASED CO-ORDINATE LOCATION
OF A RCMT BOARD"**

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CERTIFICATE

THIS IS TO CERTIFY THAT THE FOLLOWING STUDENTS OF KUMARAGU COLLEGE OF TECHNOLOGY, BHARATHIYAR UNIVERSITY, COIMBATORE HAVE COMPLETED THEIR PROJECT WORK IN ITI LTD, PALAKKAD AS PART OF THEIR CURRICULAM.


1. R. ARUMUGAM
2. K. SANJITH KUMAR
3. W. JOSEPH ANAND
4. P. L. SATHISH KUMAR
5. A. SHANMUGASUNDARAM

THEY HAVE DEVELOPED AN EFFICIENT SOFTWARE TO SUPPORT ACTIVITIES OF MANUFACTURING DEFECT ANALYSER WORK STATION FOR PCB BOARDS. ALSO THE SAME SOFTWARE HAS BEEN EXTENDED TO A STEP MOTOR CONTROL FACILITY TO LOCATE THE SURFACE MOUNT COMPONENTS (SMD) AND CONVENTIONAL COMPONENTS, THEREBY RESULTING AN EFFICIENT TOOL FOR DEBUGGING OF PCB BOARDS.

THEY HAVE DEVELOPED A PC BASED STEPPER MOTOR CONTROL BOARD THE FIRST LEVEL INSERTION OF ALL TYPES OF CONVENTIONAL COMPONENTS IN PCB BOARDS.

THIS PROJECT HAS RESULTED IN DEVELOPING A VERY EFFICIENT SOFTWARE TOOL FOR THE SCORPION STATION AND ALSO A FAULT FREE SEMI-AUTOMATIC COMPONENT PLACEMENT FOR ONE TYPE OF BOARD, NAME "RCMT" USED IN PCB EXCHANGE.

PLACE : PALAKKAD
DATE : 12-03-97


12/03/97
P. SATHEESH KUMAR
DEPUTY MANAGER (QC)

GOD IS LOVE

“WHAT LIGHT IS TO THE EYES,
WHAT AIR IS TO THE LUNGS,
WHAT LOVE IS TO THE HEART,
PARENTS IS TO THE SOUL OF HUMAN.”

THIS WORK IS DEDICATED
TO OUR
RESPECTFUL & LOVABLE PARENTS,
FOR WHOM WE MEAN MORE...

(80)

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- 2)Mr. KRISHNA PRAKASH - ADMINISTRATION DEPARTMENT

Last but not the least, we like to thank all the **STAFF** of our department for providing us immense help to finish the project and to the drafting of the report.

SYNOPSIS

“It is an established fact that without a well thought-out and long term program of action, various worthwhile projects do not add up to any remarkable achievement over time”

Our project titled, “PC BASED CO-ORDINATE LOCATION OF A RCMT BOARD” is definitely the one that is well thought-out to sought-out the problems in a Printed Circuit Board. It alleviates the burden of human and also the time consuming process of component location and its first line insertion assembly of an RCMT board which plays a vital role in OCB(Control & Operation Board) exchange and add up to many achievements in the future.

The aim of this project is to develop a PC based, Coordinate locating system for an RCMT board, which can be used in multi layer PCB's used in telephone switching exchange systems. A hardware interface to the Personal Computer is designed. This provides an effective path for the control signals from the Personal Computer and the selection of an address through a address decoder.

An efficient software package in QBASIC 4.5 is developed. These programs along with the support of the stepper motor will be able to locate the co-ordinates in the RCMT board. Thus this is used in the debugging and the First Line Insertion of the board in the OCB exchange. This method has considerably decreased the time slot required for the entire testing sequence into few minutes and thereby conserves the precious of time and also reduces the fatigue of the worker and makes his work easy.

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Chapter 1
INTRODUCTION

With the technology moving at such a rapid stride, apart from new devices in electronics (high speed CPU, high speed MSI devices) even the packaging of the devices is undergoing massive changes. With the quest for making powerful devices being the driving force, the IC designers are forced to pack more functions in to their design. This leads to an increase in packing density as well as Input / Output pin counts, making the conventional leaded packaging more difficult to manufacture.

In conventional packages the components, both discrete as well as Integrated Circuits are leaded or equipped with the leads for insertion on to the PCB. These are soldered on the opposite of the component side.

But the surface mount components have leads which can be soldered on to the footprint of the PCB directly.

Some of the features of the SMT board designs are

- * With the package size much smaller, the board size is smaller compared to a through-hole component board design.
- * The package height is small so the board height is less and takes less space.
- * Due to reduced lead length, the lead inductance and capacitance are less. This leads to better high frequency characteristics.

- * Since the number of holes are reduced, the board becomes stronger and more reliable.
- * SMT based designs enable components to be mounted on board sides, thus reducing the size of the board.
- * SMT components allow automatically components to be mounted, placed and soldered, thus enabling large volume of production very easily.

This does not mean that “ALL THAT GLITTERS ARE GOLD.” There are some disadvantages, not from technology but for reasons other than that.

Some of them are,

- * SMT based designs calls for high precision and so manual artwork for PCB is very difficult.
- * Due to same reasons, use of high precision automatic placement and soldering becomes a must. In fact, hand placement assembly of SMT board consumes more time and is prone to defects.
- * The capital investment is very high and it may not be the technology for small scale operation and low volume products. But with the trend of virtual factories catching up where the company which designs a product, out-sources the product from contract manufacturing companies who have the whole assembly line and processes in place, this may become significant.

SMT devices can be differentiated among themselves on two aspects for their construction. One is the **shape** and the other is the type of **pin connection** that is provided for connectivity.

SHAPE :

Normally there are three shapes. They are rectangular shape with the pins provided on both sides of the package - on the longer side the pin count usually goes up to 28 pins. In second and third the shape of device is respectively square and rectangular with pins provided on all the sides.

PINS :

There are two most prevalent ones, one is J lead formation and the other is Gull wing formation. The third which is not prevalent is one with the Butt ends.

When we design a board three important designs should be taken to account.

Design For Manufacturability,

Design For Testability,

Design For Reliability.

When these boards are assembled using the conventional

components and SMT components it is easily prone to defects. This is also because of the 12 layer multi PCB layer available in the industry. There may be many faults like soldering faults, contact faults, short circuit faults and open faults. These defects should be analyzed and should be found out. Otherwise this may lead to rejection of the whole board. So for this purpose the nodes are injected by current and voltage and their signals are compared and the corresponding faults are found out. So a Manufacturing Defect Analyzer is used to find out a manufacturing defects, with the help of Personal Computer and the software language. The software and hardware, called as SCORPION MACHINE are used to find out manufacturing defects in Indian Telephone Industry.

The ITI industry manufacturers OCB exchanges and the Palakkad plant manufactures control racks for controlling the operation. This OCB exchange consists of many systems and one is the switching station (MCX) for connecting the incoming calls and the outgoing calls. Here comes the Function of RCMT board which is responsible for providing 64 matrix links with the subscriber at both the ends. The RCMT board has two sides, one is connected with the conventional components on one side and the SMT components on the other side. Any defects could be analyzed by a SCORPION MACHINE. But the problem is that it can give out the nail number only through which the injection logic is injected. Now the present trend of ITI is that they have an atlas containing the data base of all the boards with the the pin numbers. So far with the corresponding pin number,

they find out the X and Y co-ordinates and the components. Moreover in the first line insertion stage of conventional components they refer a database, locate the components and place it. This take considerable time and leads to the fatigue of workers.

We have created a software package using QBASIC in order to support our hardware interface. This software package has datafiles corresponding for the data available for the RCMT board. For the debugging process, as hardware we have developed an Input / Output port which provides an effective path for control signals of the Personal Computer and selection of address through address decoder and then finally getting the output data. Depending upon the data from the computer, the Demultiplexer unit or the Stepper motor unit is selected. We have also a control data by which the X and Y direction of the Stepper motor is selected. The Demultiplexer unit is connected to the LEDs which are connected to the top of the boxes for indication of selection of chips from those boxes. These Integrated Chips of the same nature are put in a box. Now when we use a first line insertion, the LED at the top of the box containing the chip to be selected glows and then the the X and Y direction brings the point to the point at which the component is to be placed. The same process is done for debugging of the boards which have the defects in the conventional and SMT components.

1.1 SOFTWARE TREND

In the fast evolving trends of modernization and reduction in time - consumption, the so called artificial brain "COMPUTER" has underlined its valuable presence. So the replacement of the time consuming and error prone manual first line insertion assembly of the PCB (RCMT4), and for debugging the fault using SCORPION MACHINE, we have designed our computer sequences in the following way.

- 1) Creating data files containing

NAIL .DAT :

It has nail number, nodes, components, X and Y co-ordinates as data.

SMT.DAT & MAN.DAT :

It has component name , Tolerance, Code, Value, X and Y co-ordinates as data.

- 2) Co-ordinating this data in a main program thereby performing the debugging operation and the first line insertion assembly.

1.2 SPECIAL FEATURES:

1.2.1) COST EFFECTIVE :

It utilizes the same Personal Computer of the SCORPION MACHINE and it adds enhancement of the program. It costs only in

thousands but when in need to change this and purchase an alternate form from FRANCE CIT it may cost lakhs of Rupees.

1.2.2) USER FRIENDLY:

The software is written in QBASIC which is the easiest language to study in a short time. More over it is easy to understand.

1.2.3) SPEEDY OPERATION:

First insertion assembly and debugging will take only 10 to 15 minutes where as manually referring the atlas, takes hours.

1.2.4) REDUCES FATIGUE

It reduces the fatigue of the worker. This is because while doing the whole process manually it involves tedious concentration which exhausts the worker easily. But, now it can be reduced to simple take and place First line Insertion Assembly.

Chapter 2
EQUIPMENT FACILITIES

2.1 SCORPION MACHINE:

Scorpion machine is designed to find faults on assembled PCB's. MDA refers to Manufacturer Defects Analyzer, its block diagram is shown in fig.(2.1). Scorpion tests indicate components in the board, the aim being to isolate and identify the manufacturing process faults such as solder defects, insertion faults and placement errors. In addition to this, the value of the individual components can be verified.

2.2 SCORPION HARDWARE:

Scorpion machine basically consists of two parts.

- 1) Stimulus unit
- 2) Measurement unit (Self Calibrating)

2.2.1 STIMULUS UNIT:

This unit uses two types of techniques

- 1) Current injection technique
- 2) Voltage injection technique

There are values of current and voltage for the typical cases and for worst cases of the components also.

2.2.2 ENVIRONMENTAL DATA:

Mains input : 115/230 V from the tolerance +6% to -10%

Frequency	: 47-63Hertz.
Power consumption	: 400 VA excluding PC
Temperature	: +10 Centigrade to 40 centigrade.
Safety Standard	: IP 20
Safety Shielding	: Class 1
Table Dimensions	: 1740 long, 700 deep, 750 high mm

2.2.3 OVER VIEW:

Standard Scorpion tester consists of certain configuration.

- 1) Controller
- 2) Test unit
- 3) Table

2.2.4 CONTROLLER:

It consists of PC of a certain configuration

PC	: IBM/AT
MEMORY	: \geq 2MB
DISK CAPACITY	: \geq 5MB
FLOPPY DRIVE	: 1.2 MB
MONITOR	: VGA
DATA INPUT	: KEYBOARD, OPERATION KEYPAD, MOUSE, BARCODE READER

PRINTER : INTERFACE PARALLEL
CLOCK : REAL TIME
OPERATING SYSTEM :DOS >=3.3

2.2.5 TEST UNIT:

Actual test unit is housed in a 19" rack. Connections out of the fixture interface is via 64 -way VG. Euracconnectors. The test unit receives DC power (only) from the PSU located in the 19" rack. It is made up of number of sub units described below.

2.2.6 TEST POINT SWITCHING MATRIX:

ARCHITECTURE : 4 POLE to every test point.
64 test points per board -maximum 32 boards.
MAXIMUM VOLTAGE : 100 v
MAXIMUM CURRENT : 0.5 A

2.2.7 TEST POINT POWER SUPPLY:

MAINS :115/230 Volts. Supply DC
+ 5 V DC / 10 A
 \pm 15 V DC / 3 A
+ 24 V DC / 2 A
+ 100 V DC / 20 mA

These are the tests points and they are to be contacted with the nails from the nail bed. For this purpose the bed of nails should be raised and lowered. A vacuum pressure of 40 cube-metered per hour is essential for this purpose. For releasing it, compressed air of same pressure could be used.

There are various fuses in the unit in order to protect the system from overcurrent. The company which manufactures this product calibrates for a period of two years. There are two types of self test in the system. These tests are used to detect the system performance. The tests involved are,

2.2.8 SYS TEST:

This test checks the memory, environment and the internal architecture of the Scorpion machine. This checks the over all performance of the system.

2.2.9 SSM TEST:

This tests all the test points which are present in the machine.

Basically the system maintains a matrix of zeros for every test point. If there is any element present in the row of the matrix, then that rows corresponding test point is faulty.

2.2.10 MEASUREMENT TECHNIQUES:

Basically measurement techniques are of two types viz.,

- 1) Two pole measurement technique
- 2) Four pole measurement technique

The difference between the two pole and four pole technique is that in case of four pole measurement the parasitic stray resistance effects are taken in to account.

2.2.11 GUARD AMPLIFIER:

This amplifier is responsible for maintaining same potential in both sides for a component to be measured.

By these techniques measurement of various components could be performed. Some of the components involved are,

2.2.12 RESISTANCE:

By injecting the current through the component and measuring the voltage across it, and it can be given by

$$R=V/I$$

V - Voltage drop.

I - Current injected and this value is tested against standard value given in the database.

2.2.13 CAPACITANCE:

Similarly Capacitance could be found out by

$$C = (\Delta t / \Delta V) I$$

2.2.14 INDUCTANCE:

The value of inductance can be given by

$$L = V T / I$$

2.2.15 RESISTANCE WITH PARALLEL CAPACITANCE:

$$V = IR(1 - e^{-t/RC})$$

2.2.16 RESISTANCE WITH PARALLELED INDUCTANCE :

$$V = IR(1 - e^{-t/RC})$$

2.2.17 CAPACITANCE WITH PARALLEL INDUCTANCE:

This could be found out by using the above formulae.

2.3 SCORPION SOFTWARE:

SCORPION SOFTWARE could be worked under DOS environment any thing greater than or equal to 3 (Refer fig.(2.2)). SCORPION banner page is the page under which we are going to work. Next is the program selection screen which used the tools from the SCORPION test unit. Program edit screen helps in editing are changing any existing format. Component screen gives the details about the components and test select

screen gives the mode of test to be selected.

The type and scope of test required for a portable board type have to be set down in a test program. A SCORPION test program consists of a sequence of test steps which are operated by a operation key pad having Stop, Start and Print buttons.

2.3 OPERATOR KEY BOARD:

- | | | |
|---------|---|--------------------------------|
| 1)START | - | To enter SCORPION from DOS |
| 2)STOP | - | Select test program from front |
| PRINT | - | Select from back |
| 3)START | - | Load highlighted test program |
| 4)START | - | Run |
| 5)START | - | Continue the test program |
| 6)STOP | - | Print Results |
| 7)STOP | - | Stop test |
| 8)STOP | - | Exit |

From DOS environment the SCORPION SOFTWARE could be invoked by, SCORPION - CC:\ SCORPION \SCORPION.CFG

Now each test step has a graphical layout which forms the basis of manual test programming. At run time a measurement result is

evaluated for each test step. For passive component one test step is usually sufficient, whereas for semiconductor component requires two or more.

Easy to programming, set up screens are on hand to enable the rapid generation of all commonly used components as well as the functions, for automatic generating contact and short circuit tests. In addition non-standard component tests are provided for general purpose voltage and current measurements. Equally easy to use and set up are the range of program control screens. These flexible and powerful features are designed to help and manage the logical flow of test program and include such capabilities as passing control codes to and fro external equipment, operated interactive routines, as well as the ability to hand over the program control inside the Operating System and receive and process the results from an external routine.

SCORPION SOFTWARE is highly user friendly and is virtually entirely graphically oriented being largely mouse driven.

2.4 STEPPER MOTOR:

Stepper motor is a system which indicates the point as a X Co-ordinate or Y Co-ordinate. The stepper motor is often considered as a digital device which converts electrical pulses into proportionate mechanical movements. Each revolution of the stepper motor's shaft is made up of series of discrete individual steps. Size of the step depends up on the design of the motor and can be as small as 1.5 mm and as large as 30 mm. The stepper

motor shaft rotation is incremental. The basic feature of the stepper motor is that upon being energized it will move and come to rest after some number of steps in strict accordance with the digital input commands provided. The stepping motor therefore allows the control of the load's velocity, distance and direction. The motor usually provides for clockwise or anti clockwise rotation. Repeatability is very good. The only system error introduced by the stepper motor is single step error which is small percentage of one step and it is generally less than 5 percentage. Most significantly, this error is non cumulative regardless of the distance traveled or the number of times repositioning takes place. Stepper is a reliable device with bearings subject to wear.

2.4.1 CONSTRUCTIONAL FEATURES :

Construction is quite simple. It consists of a slotted stator equipped with two or more individual coils, and a rotor structure that carries no winding. The classification of stepper motor are,

- 1) Permanent magnet type
- 2) Reluctance type

Presence of permanent magnet furnishes the motor with the equivalent of DC excitation. Thus when one or more of stator coils are energized, the machine behaves as a synchronous motor.

Basic construction details of the Permanent Magnet

stepper motor is illustrated in fig.(2.3) for a four pole stator and five pole rotor structure. Observe that the action of the permanent magnet on the particular orientation of the rotor structure is to magnetize each of the poles or slots at one end of the rotor with N-pole polarity and each of the poles at the other end with S-pole polarity. More over N-pole set of rotor poles is arranged to be displaced from the S-pole set of rotor poles by one half of the pole pitch and is readily evident by comparison of fig.(2.3a) & fig.(2.3b). The symmetry that exists between the stator poles and each set of rotor poles makes it apparent that each rotor pole set behaves in an identical fashion. For example, if coil A - A' is assumed to be energized to yield a north polarity at A and South pole polarity at A', then the relation between N of the Stator and S1, S2 and S5 of rotor in fig.(2.3b) corresponds exactly to that of S of the stator and N1, N2 and n% of rotor in fig.(2.3b). A similar arrangement can be made for remaining set of poles.

2.4.2 PRINCIPLE AND OPERATION:

Three types of Stepper motors are

- 1) Variable reluctance type
- 2) Permanent magnet type
- 3) Hybrid type

A stepper motor is based on the principle like magnetic poles repel and unlike poles attract. If the stator winding in fig.(2.4a) is energized so that stator A is in the north pole, stator B is the south pole and the permanent magnet rotor is positioned as shown in fig.(2.4b). A torque will be developed to position the rotor 180 degrees from its indicated position.

However, it would be impossible to determine the direction of rotation and in fact the rotor may not move at all if the forces are perfectly balanced as indicated in fig.(2.4b) additional stator poles C and D are added and energized. We are able to predict the direction of rotation of the rotor. As indicated in fig.(2.4b)the rotor's direction of rotation would be counter clockwise with the rotor aligning itself between the average south pole and average north pole as shown in fig.(2.4c).

The permanent magnet stepper motor operates by means of the interaction between the rotor magnet biasing flux and the magnetic Forces generating by the stator windings. The motor is made to rotate faster or slower by sending more or fewer pulses per second. Pulses can usually be sent up to a maximum rate of around 2,000 per second. The direction of the rotation of the Stepper motor can be conveniently reversed by merely reversing the sequence.

2.4.3 SPEED TORQUE CHARACTERISTICS:

Although torque is not a major criteria of the Stepper motor involved in our project, we study it. The Stepper motor either runs at specified speed or does not run at all. In Speed Torque characteristics as speed is increased the torque falls to a very low value. Stepper motors could be run at open loop mode. Although it is energy inefficient and it is costly it is used because it is excellent position device. A typical speed, Torque characteristics is shown in fig(2.5).

2.5 OCB EXCHANGE:

2.5.1 GENERAL DESCRIPTION:

ALCATEL 1000 E10 is the digital switching system developed by ALCATEL CIT. Multi-applications, ALCATEL 1000 E10 serves the entire range of central offices, from smallest local exchanges to largest transit gateway switches. It adapts to every type of habitat. ALCATEL 1000 E10 provides all modern communication services,

Basic Telephony

ISDN Services

Centrex

Digital Cellular

Radio Telephony and

All Intelligent Network Applications.

The ALCATEL E10 system is located at the heart of the telecommunication networks concerned. It is made up of three independent functional units.

- SUBSCRIBER ACCESS SUB SYSTEM, which carries out connection analogue and digital subscriber lines.

- CONNECTION AND CONTROL, which carries out connection and processing of calls.

- OPERATION AND MAINTENANCE, which is responsible for all functions needed by the network operating authority.

Each functional unit is equipped with the Software's which are appropriate for handling the functions for which it is responsible.

Fig.(2.6) shows the functional architecture of OCB 283

exchange. The brief explanation of the block diagram is,

- MR : Call Handler - Establishing and breaking of communications.
- TR : Subscriber and analyses data base manager, analyses, routine circuit groups , circuit and subscriber database.
- TX : Call charging and traffic measurement - Charging for communications, Observations of circuits and subscriber, charging time table and charge accounts.
- MQ : Message distributor - Distribution of messages to the PCM controller and auxiliary equipment manager, configuration of the connection subsystem.
- GX : Matrix system handler - processing of number 7 rotocol, management of statuses of no. 7 circuits, switching of subscriber digital access unit messages.
- PC : CCS7 Controller - Management of number 7 Network, defense of CCS7 protocol handler Software machines, traffic observations.
- OC : OM message router - switching of messages relating to the operation and maintenance of maintenance software.
- URM : PCM CONTROLLER - Management of channel associated circuits and of PCMs of distant CSN and CSE.
- ETA : Auxiliary Equipment Manager - Management of statuses of auxiliaries.
- COM : Matrix switch controller - establishing, supervising and breaking of connections.

- SM : Control station - System functions configuration of control stations.
- CSN : Subscriber Digital Access unit - Management of statuses of subscriber, management of subscriber digital access unit machine.
- CSE : Electronic satellite concentrator - management of statuses of subscriber, management of electronic satellite concentrator machine.
- OM : Operation and maintenance software - Operation and maintenance functions. Archival storage

ESTABLISHMENT OF LOCAL CONNECTIONS BY AN EXCHANGE:

A Subscriber, equipped with the pulse telephone set connected to local subscriber digital access unit going to a free ordinary B subscriber.

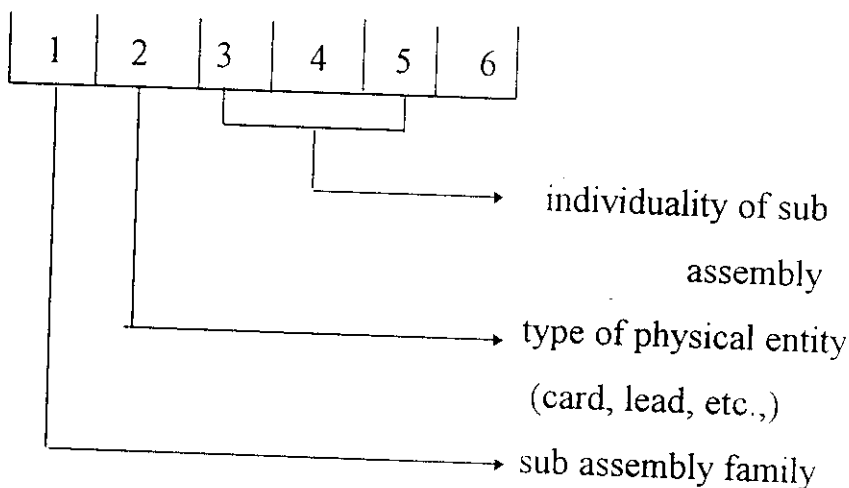
- 1) New call and transmitter on hook
- 2) Data request of calling subscriber
- 3) Sending dial tone from ETA
- 4) First digit reception
- 5) Stop sending of dial tone from ETA
- 6) Digit analysis and reception of following digits
- 7) Test and ringing of call subscriber
- 8) Sending of ring tone by common memory to see whether available or busy tone is sent to calling party
- 9) Either a available ring tone or busy tone is send to calling party from ETA
- 10) When the called party off - hook the phone stop the ring tone and send a message to ETA to cut

11) Physical connection is made available now by semi permanent connection

12) Now the charging and billing in transmitter takes place. Set a counter to increment

The second form of OCB exchange showing that some of the common sub systems i.e., having somewhat common are grouped together to be more compact.

These main assembly have sub assemblers which have racks of board which perform different types of functions, namely,



1st letter

A - Command Station.

I - Anything other than Subscriber Digital access Unit

R - Connection Network and time-base

T - Subscriber Digital access unit

2nd letter

- A - Back plane adaptation device
- B - Sub-rack
- C - Electronic Card
- E - Power supply
- F - Back plane
- L - Leads
- P - Extender
- R - Rack
- S - Plug

As our RCMT4 comes under the category connection network MCX is discussed in depth.

2.5.2 HOST SWITCHING MATRIX:

MCX is controlled by COM function. MCX is a square connection matrix with a single time stage, T, duplicated in full, which enables up to 2048 matrix links (LRs) to be connected.

A matrix link (LR) is an internal PCM, with 16 bits per channel (32 channels).

MCX can execute the following:

1) An unidirectional connection between any incoming channel and any outgoing channel. These can be as many as simultaneous connections as there are outgoing channels. It should be remembered that a connection consists of allocating the information contained within an incoming channel to an outgoing channel.

2) Connection between any incoming channel and

any M outgoing channels (Video conferencing).

3) Connection of N incoming channels belonging to one frame structure of any multiplex on to N outgoing channels which belong to the same frame structure, abiding to the integrity and sequencing of the frame received. This function is referred to as “Connection with N X 64 bits per second”.

2.5.3 SWITCHING MATRIX SYSTEM:

Role of Chaine Centrale De ConnecXion (CCX):

The switching matrix system establishes interconnections of time domain channels for local subscriber digital access units (CSNLS) and trunk control (SMT) and auxiliary equipment control stations.

Three major functions of CCX are,

1) Host switching matrix

- 16 bit switching
- Matrix of 2048 X 2048 links
- One RCMT board equal to 64 matrix storage

2) Branch selection

- selection
- Amplification
- Time distribution

3) Matrix links

- Four mega bits per second rate

2.5.4 SWITCHING MATRIX SYSTEM (CCX):

Operation of switching matrix system:

- 1) Connections are established in both the branches
- 2) Selection of active branches for a time slot is carried by comparing the outgoing time slots of each branch.
- 3) Three control bits permits the following function in each branch.
 - (a) Carrying time slot parity
 - (b) Setting by matrix, Selection of active link
 - (c) Monitoring connections on request
 - (d) Monitoring quality of Xmission on request
- 4) Five external bits are used for external utilisation.

2.5.5 HOST SWITCHING MATRIX (MCK) :

The host switching matrix is made up of two branches, A and B, and from the hardware point of view, it is made up of Matrix Control Stations (SMXs). A branch of host switching matrix contains 1 to 8

matrix control stations. ISMX station has a 2k switch. Each matrix control station receives a time signals tripled data items (8 MHz and frame synchronization) coming from the time base and following majority choice, distributes information to the exchange and to matrix link interfaces (ILRs).

Each matrix control station handles 250 incoming

matrix links and 256 outgoing matrix links, within its network liason interfaces. An output from incoming side ICRs, the LCXE links of homologous numbers and multiplied on the same positions of all the matrix control stations. Each time domain matrix is capable of handling the switching of any time slot of the 2048 incoming matrix links, to any time slot of its 256 outgoing matrix links.

2.4.6 MATRIX CONTROL STATION (SMX):

Each SMX includes,

(a) A main Multiplex Coupler (CMP) which permits two-way communication on the Main Control Station Access Multiplex (MAS) and performs the "processor" function for the Matrix Switch Controller Software Machine (MLCOM).

(b) A coupler to the time-domain matrix.

(c) Matrix Link Interfaces (ILRs) for a maximum of 256 incoming matrix links and 256 outgoing matrix links.

(d) A time-domain matrix of maximum capacity of 2048 incoming matrix links and 256 outgoing matrix links.

2.5.7 COMMAND INTERFACE PART:

The role of this is to ,

- Receive via MAS coming from command stations
- Write or Read connection matrices

- Process monitoring functions
- Transmit responses to command stations
- Interfacing with general time base

2.5.8 MATRIX LINK (LR) INTERFACE PART (RCID):

This interfaces matrix links to and for from SAB.

2.5.9 CONNECTION MATRIX PART (RCMT board):

This is the part which we are going to deal about.

The function of RCMT Board is to switch any incoming channel onto any outgoing channel.

Operations is based on use of two types of dual access memory:

2.5.10 BUFFER TYPE:

This memory allows storage of samples relating to two frames, with storage taking place at the strobe of the time base and even frame altering with odd frame in two buffers.

2.5.11 READ OUT IS FROM CONTROL MEMORY (RCMP):

Matrix has a maximum capacity of 2048 incoming matrix links on 256 outgoing matrix links, making up to 1024 LRE X256 LRS modules.

Thus RCMT board has 64 X 64 matrix link storage. Here RCMT are arranged in 32 columns and 4 rows, as shown in fig.(2.8) to obtain time domain matrix of matrix control station. Average time taken to go through one frame is 125 microseconds.

2.5.12 RCMT MATRIX BOARD:

Matrix board consists of 4, 64*64 matrices . It is on two board, on inter-aid. Access to these boards takes place at 4 Mbit/sec. Internal operating rate is 16Mhz. Inter-aid takes place on the front of the boards.

The host switching matrix handles 16 bit time slots:

- 8 Speech bits.
- 5 Free bits.
- 3 bits for protection of connections.

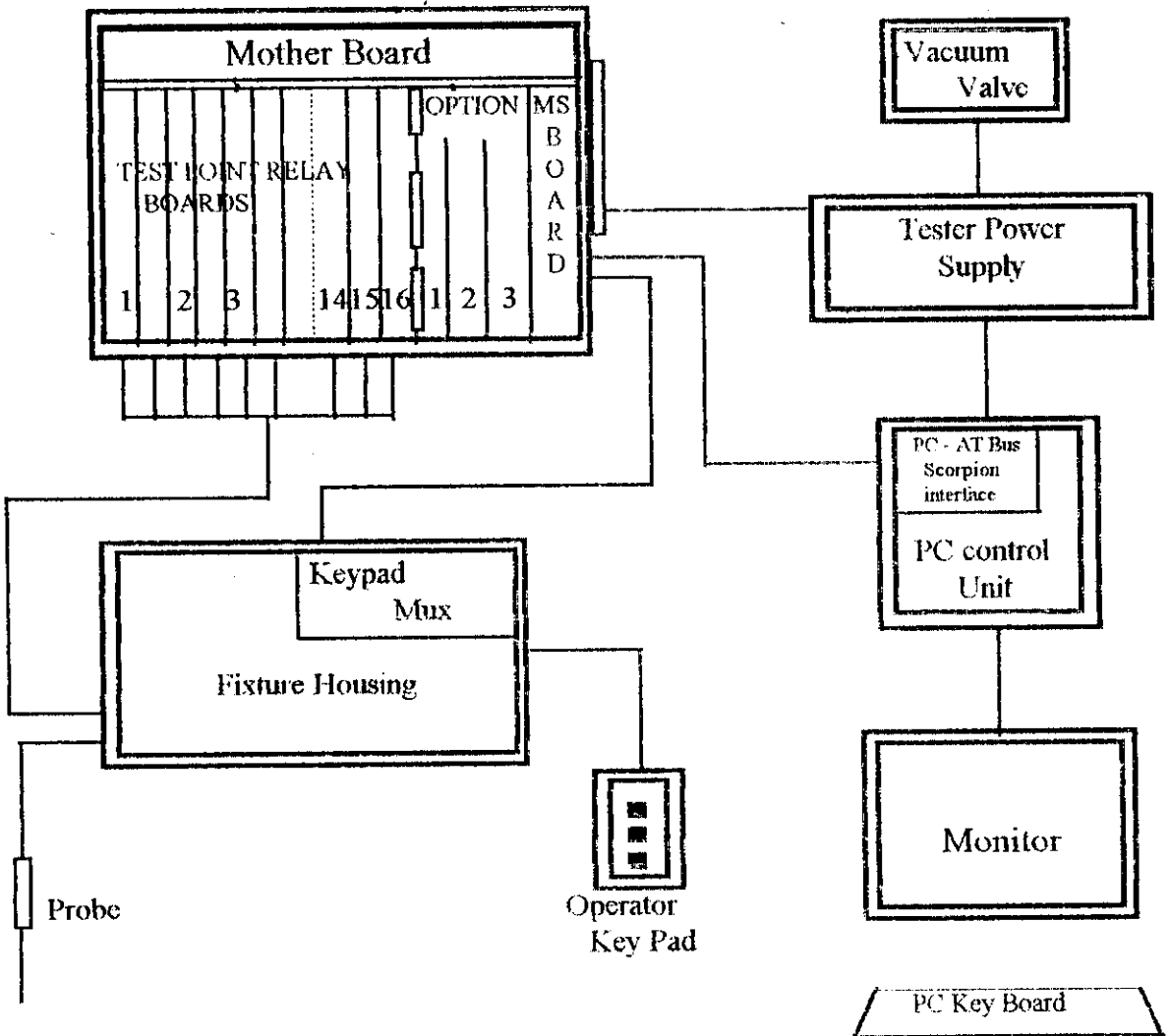


Fig.(2.1) SCORPION SYSTEM BLOCK DIAGRAM

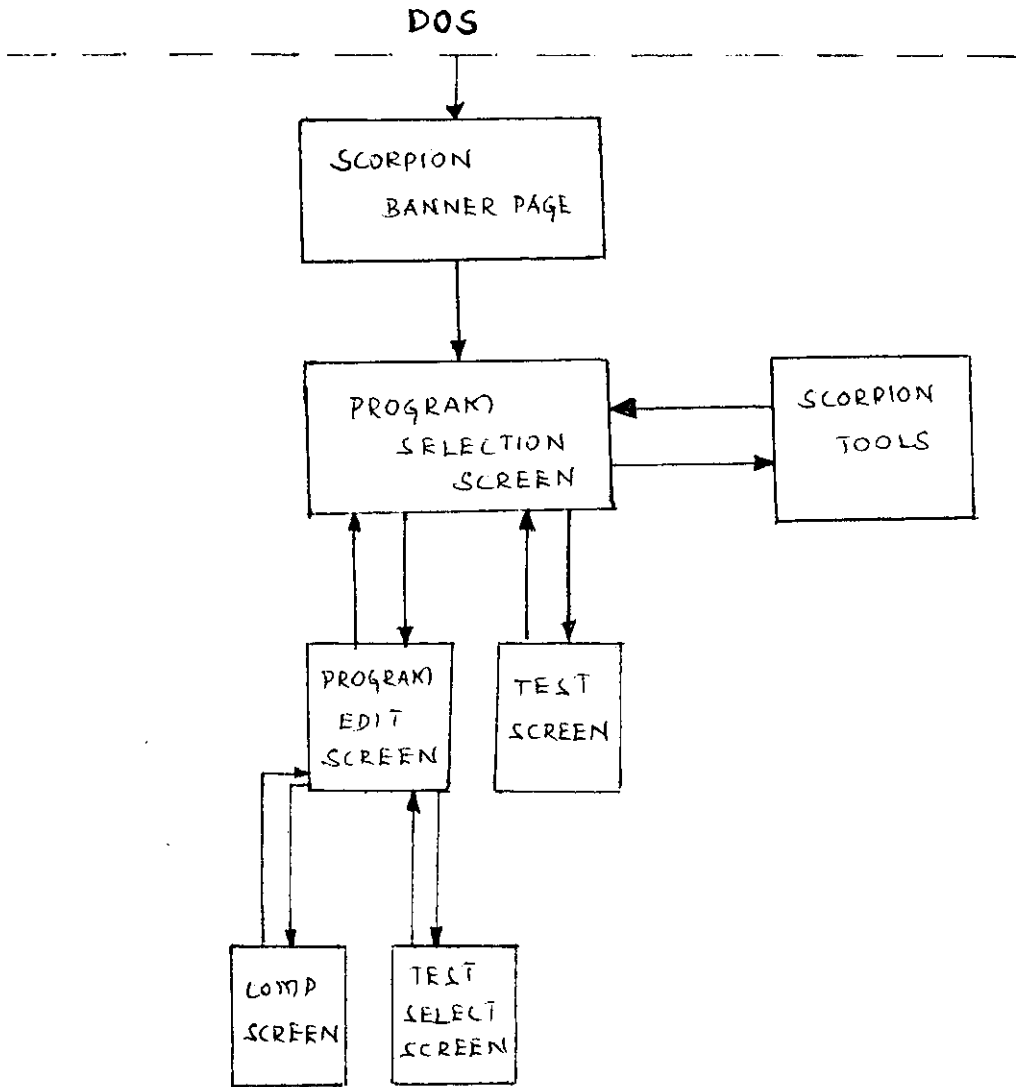


FIG. (2-2) SCORPION SOFTWARE

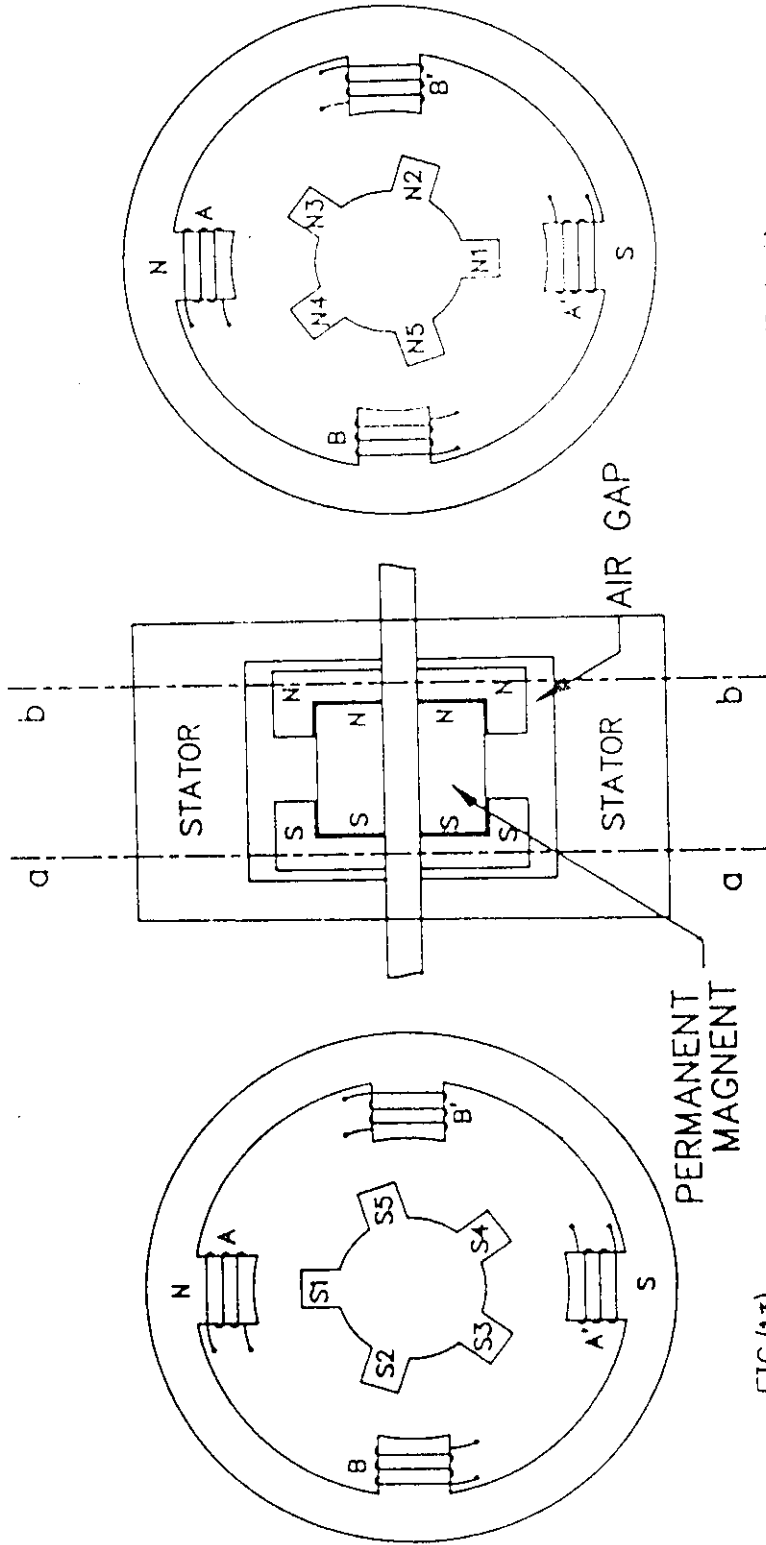
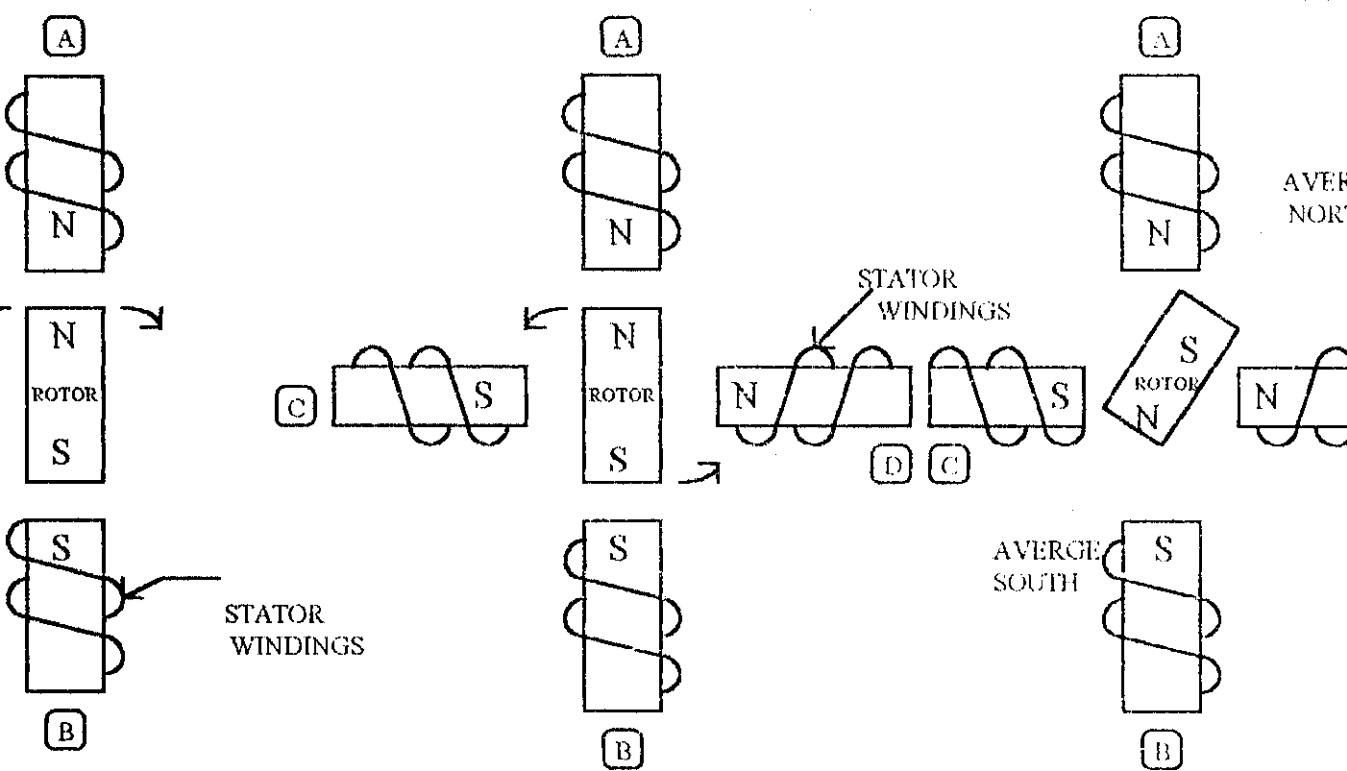


FIG (1.3)

FIG (2.3a)

FIG (2.3b)

CONSTRUCTIONAL FEATURES OF A STEPPER MOTOR



FIG(2.4a)

FIG(2.4b)

FIG(2.4c)

BASIC STEPPER MOTOR ROTATION

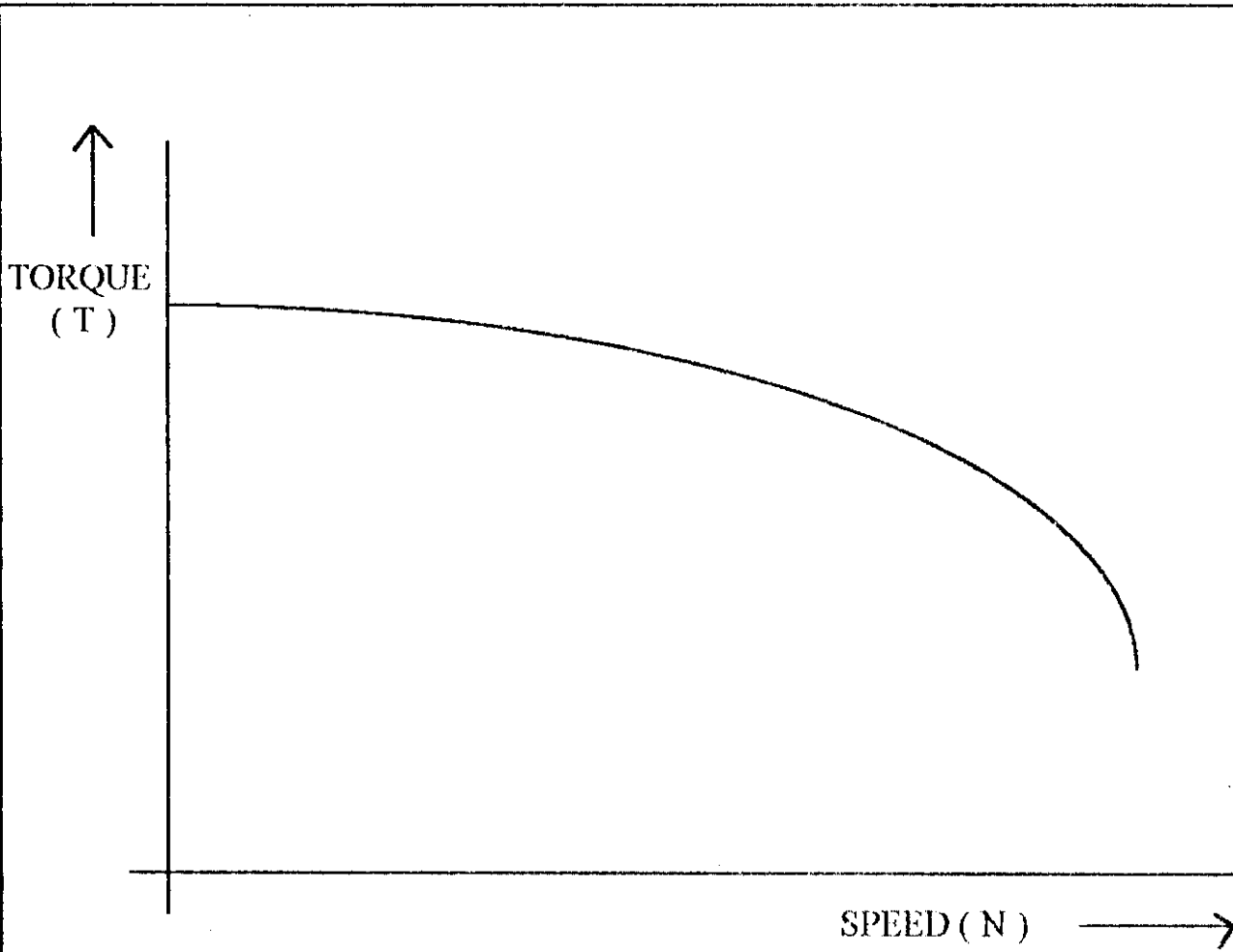


FIG.(2.5) SPEED - TORQUE CHARACTERISTICS OF A STEPPER MOTOR

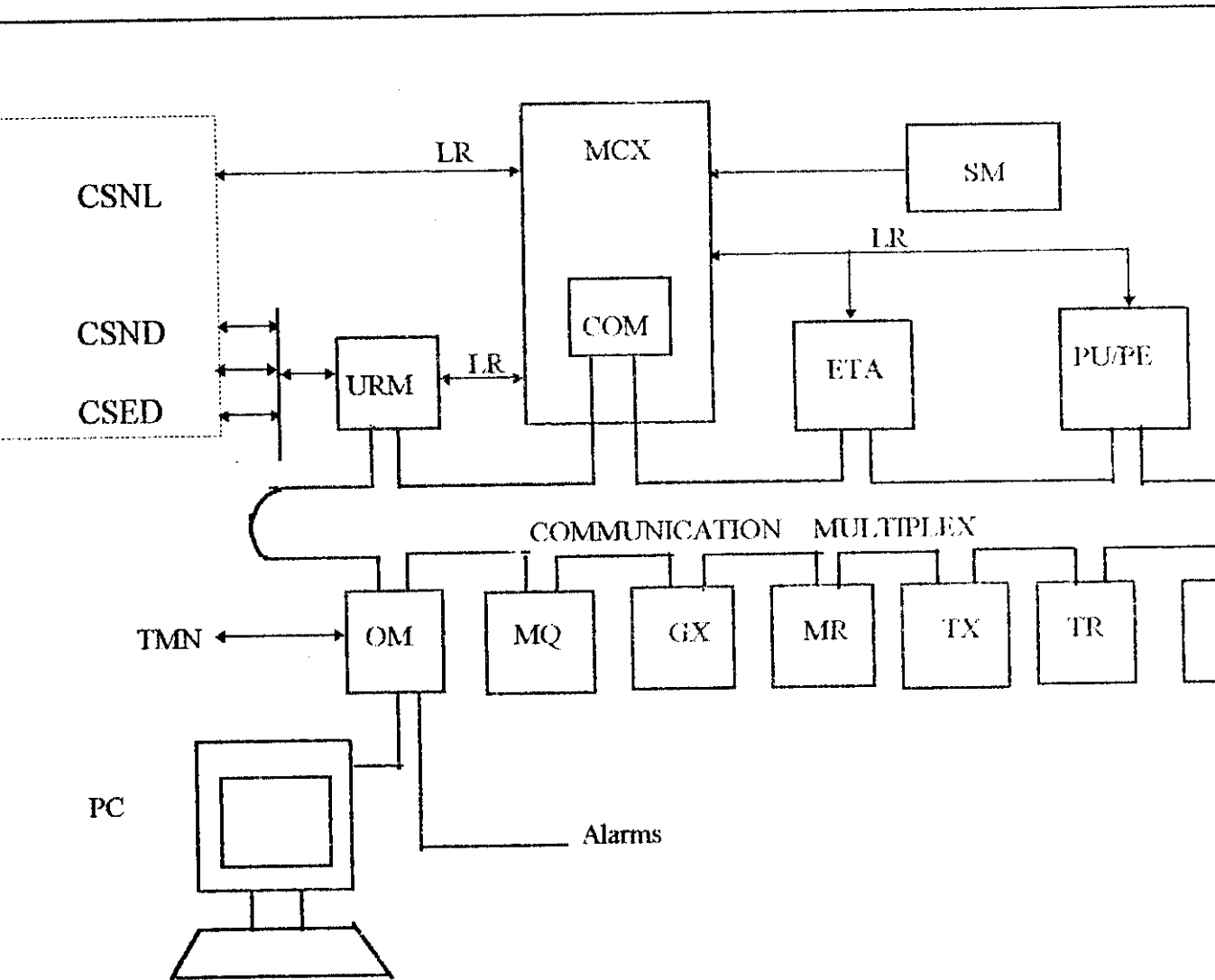


Fig.(2.6) OCB 283 F UNCTIONAL ARCHITECTURE

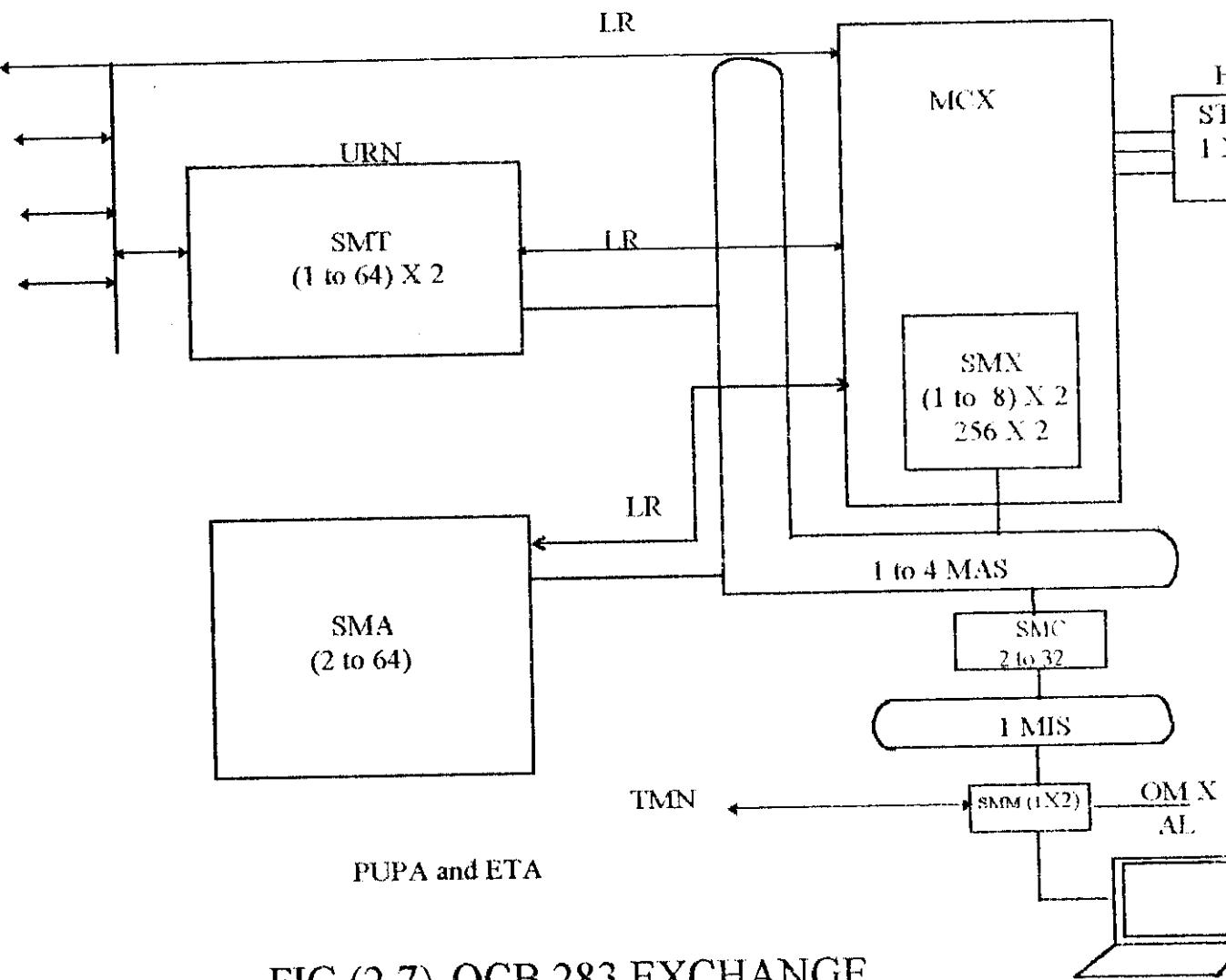


FIG.(2.7) OCB 283 EXCHANGE

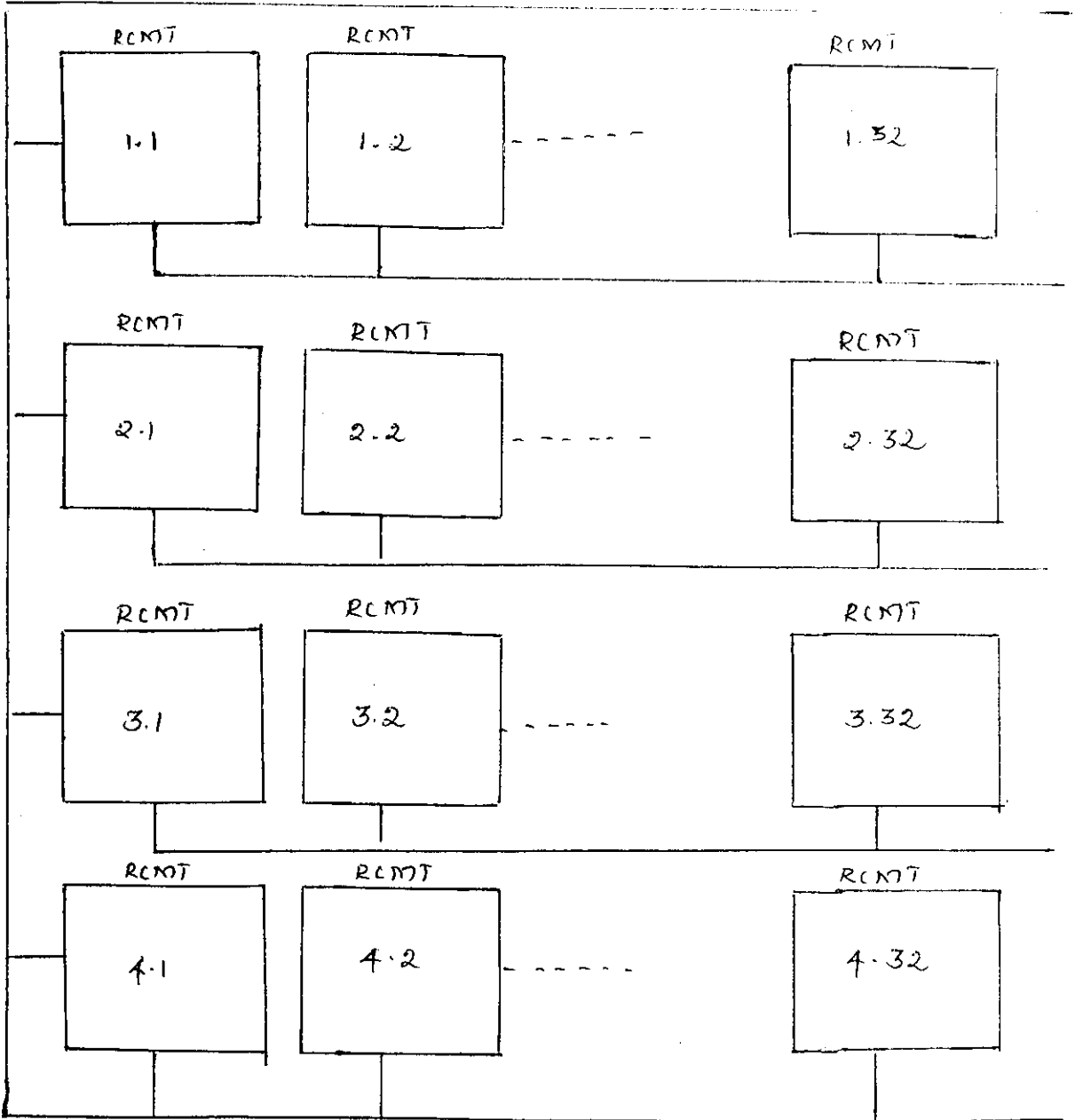


FIG. (2.8) RCMT CONTROL STATION

Chapter 3
HARDWARE

3.1 GENERAL CONFIGURATION:

The hardware is divided into two main sections. They are

- 1) I/O card connected to the personnel computer.
- 2) The multiplexed unit is responsible for selecting the components.
- 3) The hard ware interface of the stepper motor unit.

This software along with hardware peripherals could be run in the same SCORPION machine itself. The hardware part of the test machine has been simplified in favour of software. The program can thus choose the signals which may be transmitted at any given instant without any signal adversely affecting any other.

3.2 INPUT /OUTPUT CARD DESIGN:

The data bus and the address bus of the Personal Computer are used to establish interconnections between the stepper motor interface and the software for establishing the process. The buses are, resistor pad shown in fig.(3.1) which is connected to one side of the eight bit comparator which compares it with the fixed address. This fixed address is selected by using a port switch which can be connected to a zero level or a signal level and is pulled up using a resistor pad connected to 5V supply.

The main function of this address comparator is to select a address location in the address bus of the CPU. The CPU of our computer sweeps through various address locations meant for executing the

various job cycles of the computer. The gaps of memory map which points out the address have no functions to do. Our main aim is to select such a memory space in the address map to execute our testing process. For example the address 220H is selected using the port switch and is compared with the address of the input from the address bus. So that when the address 230H is scanned by the Personnel Computer, we can execute the enable signal from the computer to reach out as a signal for enabling various Integrated circuits when the comparator selects the address 220H. The AEN signal enables the bi-directional latch which connects the data bus of the computer after an active pull up to the external circuitry. This is essential because there some needs that the total interface should be taken out without actually removing the I/O card. The enable input of the transceiver is controlled by the signals from the OR gate when the address is 220H. An octal D-type flip-flop with three state output and a hex buffer with open collector high voltage output, is used to give signals, after a pulling up using a resistor pad connected to a 12 V supply, to the female connector. This connection could be taken when in future cases need to take input to the Personnel computer. An octal transceiver output is connected to a bi-directional buffer specifying the direction. Before that the D_4^{th} and D_5^{th} data lines are handed and this is given to the chip selected logic of the 74245(buffer).The other lines are passed through a D-type flip flop for a delay so that buffer selects either demultiplexer or the stepper motor interface. The demultiplexer part will be explained in details later in the chapter. Now the line D_7 determines the select logic of the buffer connected to the lines

immediately. If the level in $D_7 = 0$ then the buffer corresponding to Y directional stepper motor interface is selected and $D_7 = 1$ for the buffer corresponding the X direction.

For demultiplexer logic the data should be like ,

D_0	D_1	D_2	D_3	D_4	D_5	D_6	D_7
1/0	1/0	1/0	1/0	1/0	1/0	0	0

The stepper motor logic data should be :

D_0	D_1	D_2	D_3	D_4	D_5	D_6	D_7
1/0	1/0	1/0	1/0	1	1	1/0	1/0

3.3 DEMULTIPLEXER UNIT:

For this unit various boxes containing Integrated circuits are connected with the LIGHT EMMITTING DIODES. The light emitting diodes show the boxes for which the components to be selected. For this data from the computer is given selecting the components. The data reaches the demultiplexer unit as shown in fig.(3.2) via the date lines through the data bus. Light Emitting diodes are placed at the top of the boxes. These are ensured to the selection of the chips from the boxes. The data lines gives the data from the computer and this gives the output to the demultiplexer unit which shows the chip to be selected. The LED's connected get a low signal

and this makes it to glow. The demultiplexer unit uses the 74154 chips which has the output of 16 and when these are connected in parallel then it is possible to enhance the output number.

For example,

	D ₀	D ₁	D ₂	D ₃	D ₄	D ₅	D ₆	D ₇
R1	0	0	0	0	0	0	0	0
R2	0	0	0	0	0	0	0	1
R3	0	0	0	0	0	0	1	0
R4	0	0	0	0	0	0	1	1
R5	0	0	0	0	0	1	0	0
R6	0	0	0	0	0	1	0	1
R7	0	0	0	0	0	1	1	0
and etc.								

In our system we had used three chips and these are connected in parallel. In this system we uses 00 to select the chip number 1, 10 selects the second and the data 01 selects the third.

3.4 OPTO COUPLER:

OPTO COUPLER consists of a LIGHT EMMITTING

DIODE and opto transistor. There is an isolation between the two. This acts as a physical isolation between the two systems namely the high voltage side and low voltage side. The main advantage of MCT 2E is that it acts as a coupler or isolation between the high voltage and low voltage sides. Hence this is used in the first stage of the stepper motor interface.

3.5 INTERFACING A MICRO COMPUTER TO A STEPPER MOTOR:

A unique type of motor useful for moving things in small increments is the stepper motor. Instead of rotating smoothly around or step from one fixed position to the next. Common step sizes range from 0.9 to 30mm. Stepper motor is stepper from one position to the next by changing the currents through the fields of the motor. the two common field connections are referred to as two phase or four phase motor.

The fig.(3.3) shows a circuit which is used to interface a small four phase stepper motor. Since the IC MCT2E is used as the optocoupler. This is used because it disconnects the low voltage from the high voltage side. The fig. (3.4) shows he switching sequence to step a motor such as this clockwise, as face the motor shaft, or counter clockwise. Hence how this works. Suppose SW1 and SW2 are turned on. Turning of SW2 and turning on SW4 will use the motor to rotate one step of 1.8 degrees

clockwise. Changing to SW3 and SW2 on will cause another step. After that, changing to SW2 and SW1 on again will cause another step clockwise. You can repeat the sequence until the motor has rotated as many steps clockwise, you simply work through the switch sequence in the reverse direction. In either case the motor will be held in its last position by current through the coils. The fig.(3.5) shows the switching sequence that can be used to rotate the motor half steps 0.9 degrees clockwise and anticlockwise.

A close look at the switching sequence in the fig.(3.6) shows an interesting pattern. To take the first step clockwise from SW2 and SW1 being on. The pattern of 1's and 0's are simply rotated 1 bit position around to the right. The 1 from SW1 is rotated around into bit 4. To take the next step the switch pattern is rotated one more bit position. To step anticlockwise the switch pattern is rotated left one bit position for each step desired. Suppose that initially load 00110011 through the port to the switches. Duplicating the switching pattern from 0011 0011 will make the stepping easy. To step the motor clockwise, you just rotate this pattern right one bit position and output it. After you output one step code you must wait a few milliseconds before you output another step command, because the motor can only step so fast. Maximum stepping rates for different types of steppers vary from few 100 steps per second to several thousand steps per second. To achieve high stepping rates, the stepping rate is slowly increased to the maximum, when it is decreased as the desired number of steps is approached.

As a stepper motor steps to a new position, it tends to oscillate around the new position, before settling down. A common software technique to damp out this oscillation is to first send the patterns to step the motor towards the new position. When the motor has rotated part of the way to the new position, a word to step the motor backward is output for a short time. This is like putting the brakes on the step forward word is then sent again to complete the step to next position. The timing for the damping command must be determined experimentally for each motor and load.

3.6 PC DETAILS:

Most important part of the testing process of the component location is the personal computer. The effective interfacing of the rack of the computer and the execution of the program is the major part of our task. So it is essential to have knowledge though not in detail about various features of the computer. The I/O band which or inserted in to the I/O parts of the computer. So we must know details about the I/O part specification. The memory address map which provides a fixed address space is given below,

3.6.1 PIN ASSIGNMENTS FOR I/O CHANNEL CONNECTORS:

I/O PIN	Signal name	I/O
A1	-I/O CH CK	1
A2	SD 7	I/O
A3	SD 6	I/O
A4	SD 5	I/O

A5	SD 4	1/0
A6	SD 3	1/0
A7	SD 2	1/0
A8	SD 1	1/0
A9	SD 0	1/0
A10	-1/0 CHR DY	1
A11	AEN	0
A12	SA 19	1/0
A13	SA 18	1/0
A14	SA 17	1/0
A15	SA 16	1/0
A16	SA 15	1/0
A17	SA 14	1/0
A18	SA 13	1/0
A19	SA 12	1/0
A20	SA 11	1/0
A21	SA 10	1/0
A22	SA 9	1/0
A23	SA 8	1/0
A24	SA 7	1/0
A25	SA 6	2/0
A26	SA 5	1/0
A27	SA 4	1/0
A28	SA 3	1/0
A29	SA 2	1/0

A30	SA 1	1/0
A31	SA 0	1/0
B1	GND	ground
B2	RESET DRV	0
B3	+ 5 Vdc	Power
B4	IRQ 9	1
B5	- 5 Vdc	power
B6	DRQ 2	1
B7	- 12 Vdc	Power
B8	OVS	1
B9	+ 12 Vdc	Power
B10	GND	ground
B11	SME MW	0
B12	SME MR	0
B13	10W	1/0
B14	IOR	1/0
B15	DACK 3	0
B16	DRQ 3	1
B17	DACK 1	0
B18	DRQ 1	1
B19	Refresh	1/0
B20	CLK	0
B21	1 RQ 7	1
B22	1 RQ 6	1

B23	1 RQ 5	1
B24	1 RQ 4	1
B25	1 RQ 3	1
B26	DACK 2	0
B27	T/C	0
B28	BALE	0
B29	+ 5 Vdc	Power
B30	OSC	0
B31	GND	Ground

3.6.2 I/O CHANNEL SIGNAL DESCRIPTION

1) SA0 through SA 19 (I/O)

Address bits 0 through 19 used to address memory and I/O devices within the system. These 20 address lines allow access of 16 Mb of memory. SA0 through SA 19 are gated on the system bus when 'BALE' is high and are latched and the falling edge of BALE. these signals are generated by the microprocessor or DMA controller. They also may be driven by other microprocessors or DMA controllers that reside on the I/O channel.

2) BALE (0) (Buffered Address Latch Enable)

Address latch enable is provided by the 82288 Bus Controller and is used on the system board to latch valid addresses and memory decodes from the microprocessor. It is available to

the I/O channel as an indicator of a valid microprocessor or DMA address. Micro processor addresses SA0- SA 19 are latched within the falling edge of "BALE". "BALE" is forced high during DMA cycles.

3) SD 0 through SD 15 (I/O) (Signal Data 0 through 15)

These signals provide bus bits through 15 for one microprocessor, memory and I/O devices. D0 is LSB and D15 is the msb. All 8-bit devices on one I/O channel should use D0 through D7 for Communication to the microprocessor. The 16 bit devices will use D0 through D15. To support 8 bit drives, the data on D8 through D15 will be gated to D0 through D7 during 8-bit transfers to these devices, 16 bit microprocessor transfers to 8 bit devices will be converted to two 8 bit transfers.

4) -IOR (I/O) (Input output Read)

"-I/O Read" instructs an I/O device to drive this data on to the data bus. It may be driven by the system microprocessor or DMA controller, or by a microprocessor or DMA controller resident on one I/O channel. This signal is active low.

5) -IOW (I/O) (Input output Write)

"-I/O Write" instructs an I/O device to read the data on the data bus. It may be driven by any microprocessor or DMA controller in the system. This signal is active low.

6) AEN (0) (Addresss Enable)

“Address Enable” is used to degate the microprocessor and other devices from the I/O channel to allow DMA transfers to take place. When this line is active, the DMA controller has control of the address bus, the data bus Read command and the Write command lines.

Hex Range	Device
000 -01F	DMA controller 1, 8237 A -5.
020 - 03F	Interupt controller 1,8259A,Master.
040 - 05F	Timer, 8254.2.
060 - 06F	8042 (Key Board).
070 - 07F	Real - time clock, NMI.
080 - 09F	DMA page register, 7415612.
0A0 - 0BF	Interrupt controller 2, 82594.
0C0 - 0DF	DMA controller 2, 8237A - 5.
0F0	Clear matu coprocessor busy.
0F1	Reset matu coprocessor.
0F8 - 0FF	Matu coprocessor.
1F0 - 1F8	Fixed disk.
200 - 207	Game I/O.
278 - 27F	Parrel printer port 2.
2F8 - 2FF	Serial port 2.
300 - 31F	Prototype card.
360 - 36F	Reserved.

378 - 37F	Parallel printer port 1.
380 - 38F	SDLC, bisynchronous.
3A0 - 3AF	Bisynchronous.
3B0 - 3BF	Monochrome display and printer adapter.
3C0 - 3CF	Reserved.
3D0 - 3DF	Colour/Graphics Monitor Adapter.
3F0 - 3F7	Diskette controller.
3F8 - 3FF	Serial port 1.

3.7 PCB FABRICATION:

3.7.1 PCB FABRICATION USING SMARTWORK:

The Printed circuit Board (PCB) making is the arrangement of components in a neat, compact way on a copper clad board with circuit connections.

The various components used in PCB fabrication assembly have standard dimensions. Based on this suitable spacing is to be provided while drawing a PCB. First the circuit diagram is thoroughly studied. The size of the different components are noted down. Approximate placing of the different components are taken in preparing a PCB layout. The layout should be a compact, arranged the components neatly, spacing is

to be provided sufficiently according to the size of the components so that the leads do not break by bending or the components do not get crowded, and all the connecting lines are drawn in the board.

A rough layout for the circuit is prepared in a paper is indicating the placing of the components and lines interconnecting them. This diagram is then converted to required PCB layout with the help of SMARTWORK which is a software design producing a printout of the layout. The solder side and the component side are shown in the Figures. Then the board is fabricated by using any one of the technique used in the industry and holes are drilled to give the corresponding Printed Circuited Board. This board is then tested for the open test and the short circuit test. The Solder side and Component side layout of Input / Output card is shown in fig.(3.7) and fig.(3.8) and the same for Demultiplexer unit is shown in fig.(3.9) and fig.(3.10).

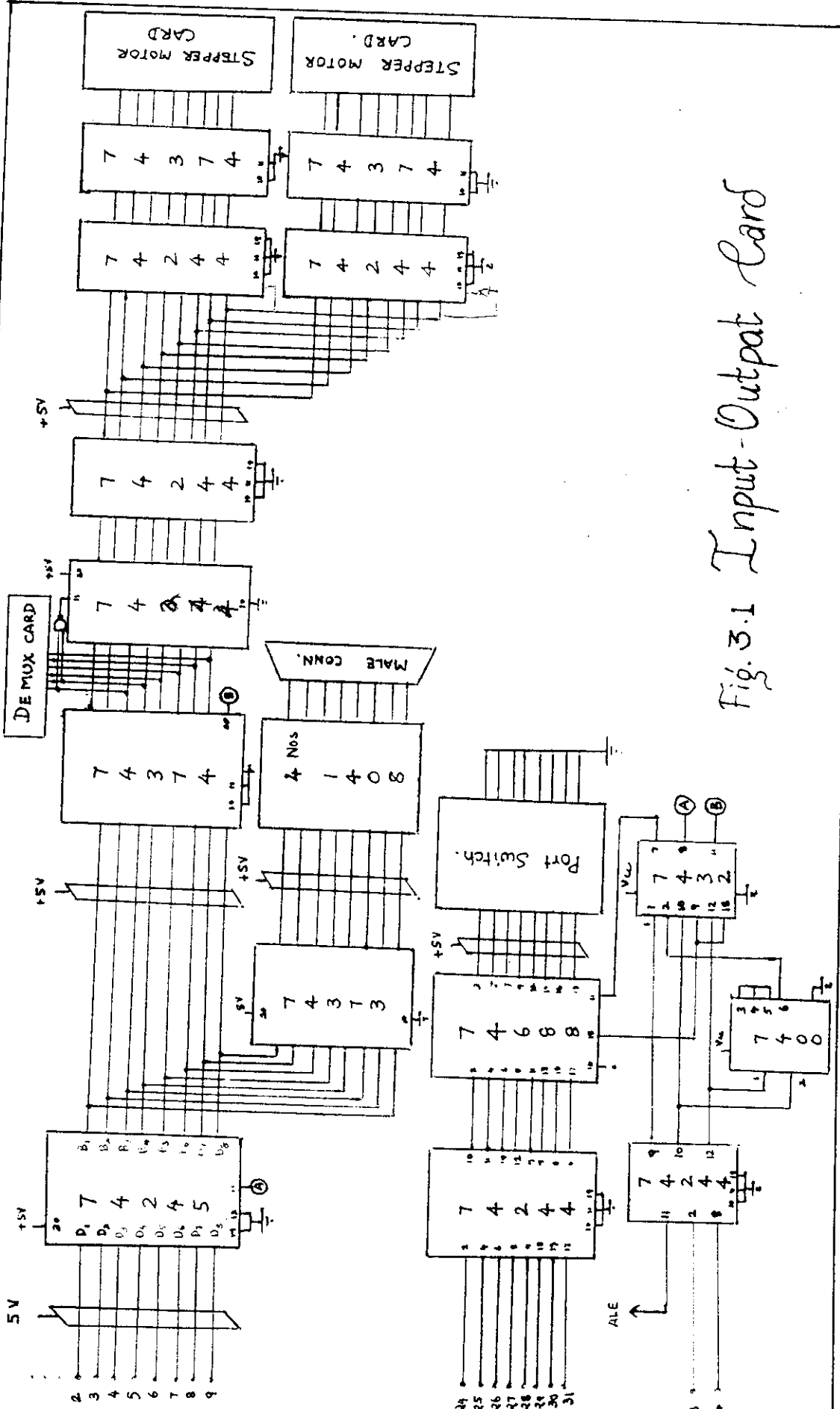


Fig. 3.1 Input-Output Card

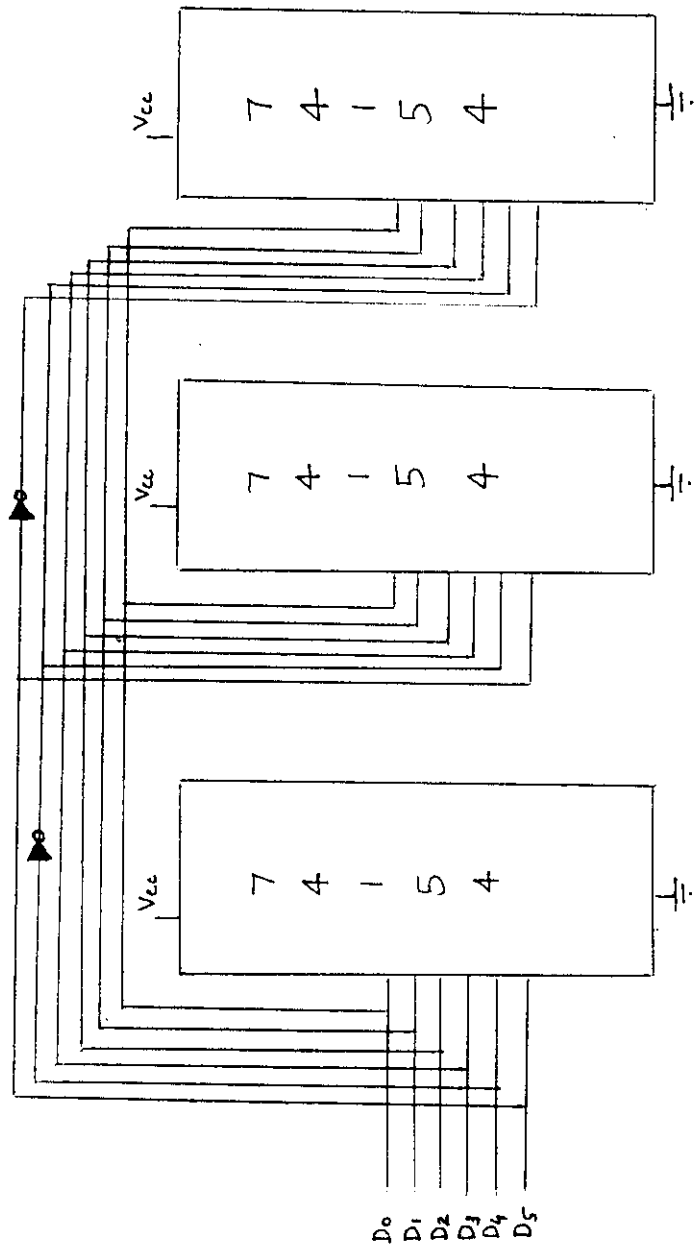


Fig 3.2 Demultiplexer Unit

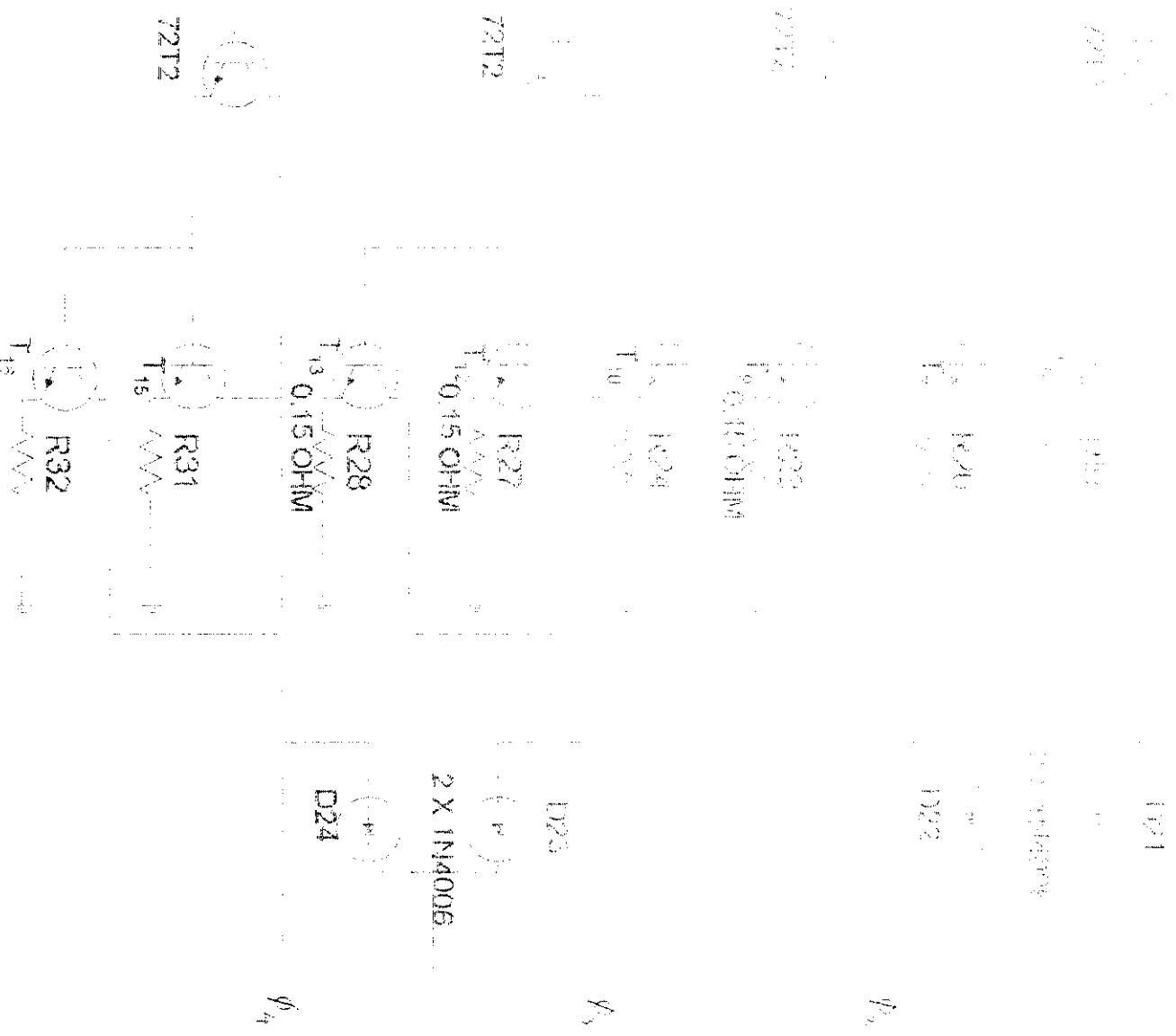


FIG (3-3) STEPPER MOTOR INTERFACE CARD

STEP	SWITCH #1	SWITCH #2
1	1	5
2	1	4
3	3	4
4	3	5
1	1	5

TO REVERS DIRECTION, READ CHART UP FROM BOTTOM

(b) SWITCHING SEQUENCE.

PHASE	1	2	3	4	5
STEP 1	ON	ON	OFF	OFF	ON
STEP 2	OFF	OFF	ON	ON	OFF
STEP 3	ON	OFF	OFF	ON	ON
STEP 4	OFF	ON	ON	ON	OFF

FIG (3.4)

(c) WAVEFORMS

← REV

STEP	PLUSE				STEP	STEP	STEP	STEP
	S1	S2	S3	S4				
1	OFF	ON	OFF	ON	1	OFF	1	OFF
2	OFF	ON	ON	OFF	2	ON	2	ON
3	ON	OFF	ON	OFF	3	ON	3	ON
4	ON	OFF	OFF	ON	4	OFF	4	OFF
5	OFF	ON	OFF	ON	5	OFF	5	OFF

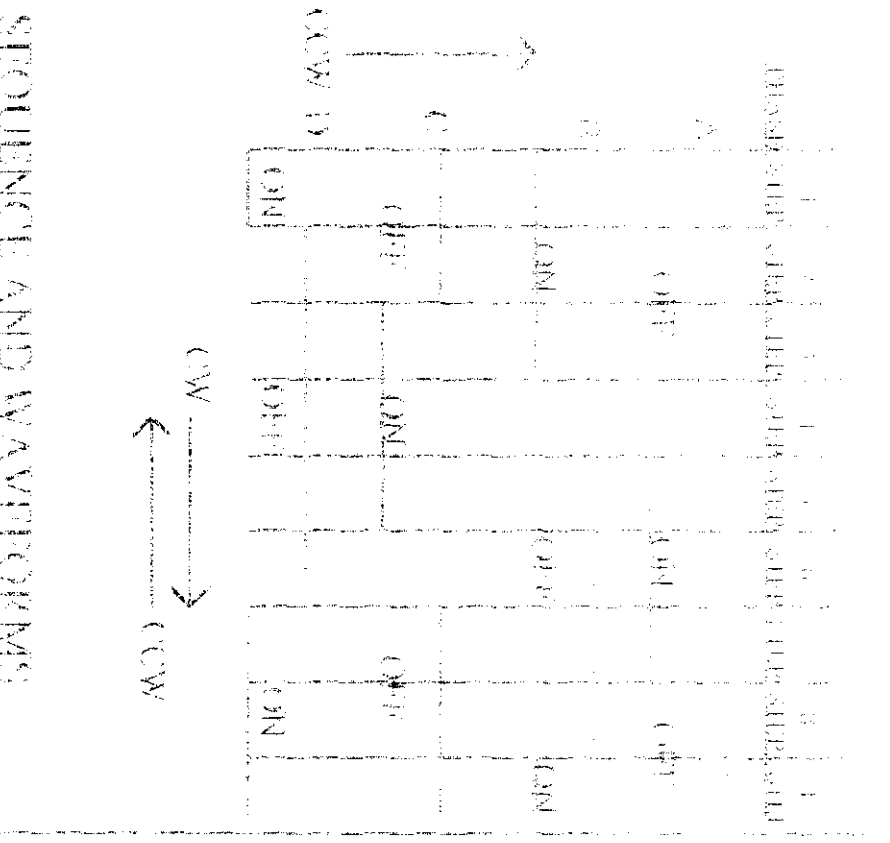
TO REVERSE DIRECTION REVERSE CURRENT THROUGH MOTOR

PLUSE 1 2 3 4 5

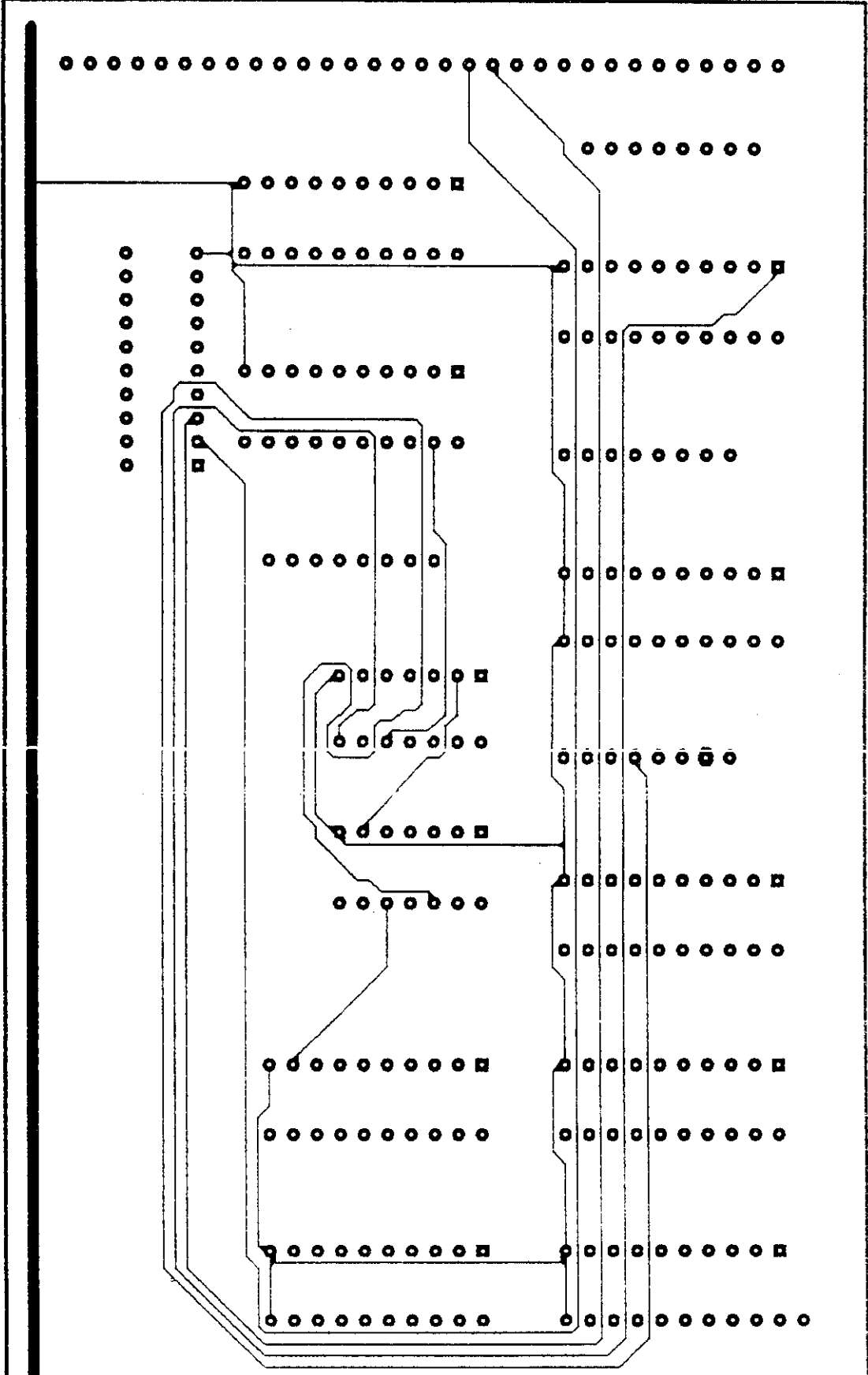
SEQUENCE AND WAVEFORMS

CW

STATE	S1	S2	S3	S4
1	OFF	ON	OFF	ON
2	OFF	ON	ON	OFF
3	OFF	ON	ON	ON
4	OFF	ON	OFF	ON
5	ON	OFF	ON	OFF
6	ON	OFF	OFF	OFF
7	ON	OFF	OFF	ON
8	OFF	OFF	OFF	ON
1	OFF	ON	OFF	ON



2X artwork
100card
V1.2
APPROXIMATELY 2.05 3.45



2X artwork

2 Mar 1997

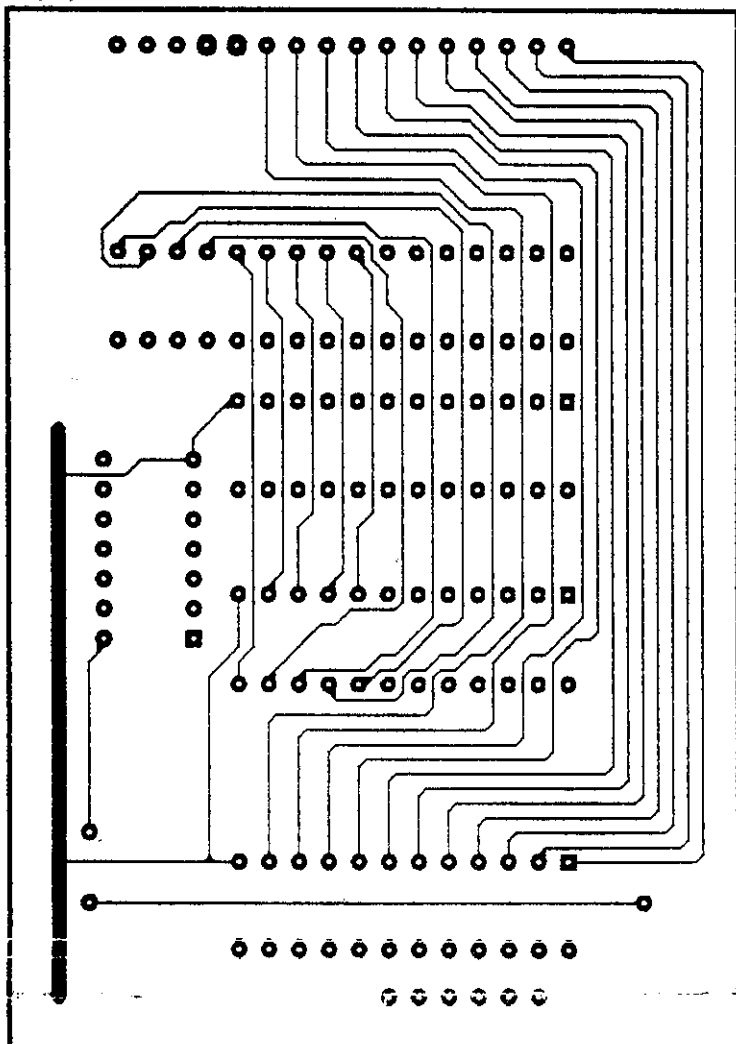
L2516-20

demux

v1.2 r2 holes: 143

component side

approximate size: 3.30 by 2.25 inches



2X artwork

2 Mar 1997

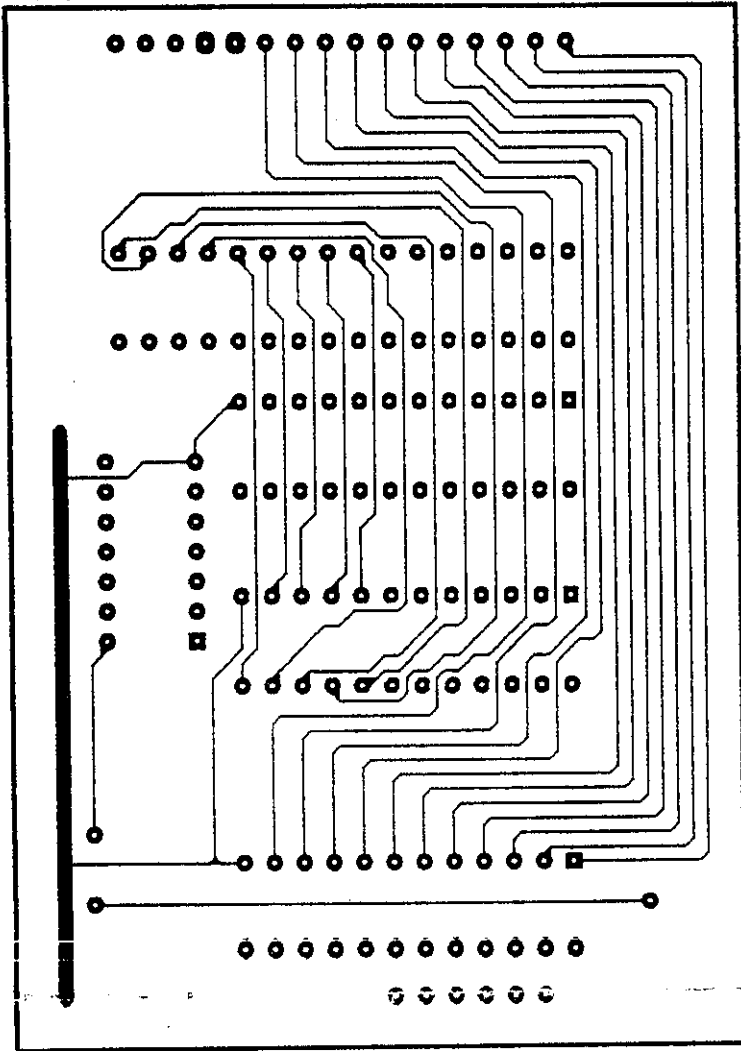
12:14:23

demux

v1.2 r2 holes: 145

component style

approximate size: 3.30 by 2.25 inches



Chapter 4
SOFTWARE

4.1 SOFTWARE DESCRIPTION:

The main structure that serves as a base for the software is the “**DATA SET**”. The data set includes the RCMT board components which has been again divided into SMT and the conventional components.

The SMT is “Surface Mounting Technology” which enhances the portability of the Printed Circuit Board(PCB). Conventional components are ordinary components that are manually assembled.

The data set consists of the Nail number, the component name, code, signal applied, tolerance, value of the component, X and Y co-ordinates of the RCMT board. The objective of the program is to get the X and Y co-ordinates when the Nail number is given as input.

4.2 MAIN PROGRAM:

The developed Software is given at the end of this Chapter. The flowchart of the main program is shown in fig.(4.1). The package is a “**Menu Driven Program**” which when started gives three options, viz., Help, Information and Continue. When the programmer needs any help as to how to go about with the program he may use this menu which entirely describes the operation of the program.

The entire information about who have written and guided to develop this software has been presented here. Also the title of the

project has been given. When 'continue menu' is retrieved the programmer could go about with the program and he might be able to locate the co-ordinates.

4.3 PROGRAM INFORMATION:

When the continue menu is entered another set of choices could be reached to get the details of the RCMT board.

The choices that is given in software are :

- 1) **Display set**
- 2) **Search and display**
- 3) **Display components**
- 4) **Insertion assembly**
- 5) **Help**
- 6) **Quit**

4.3.1 DISPLAY SET:

The flowchart for this subprogram is shown in fig.(4.2a). When this area is reached, we will be able to scroll through the data available for the SCORPION MACHINE page by page. Also , if we need to quit after any number of pages that would also be possible. The SCORPION MACHINE atlas or data sheets gives the nail number, node x and y co-ordinates.

If we call for the display set menu it will reach the

subprogram DISPLAY SET and would open a file named SANJU.DAT which consists of 1239 records and each record describes the nail number, component, signal, x coordinate and y coordinate of the RCMT board.

By this program all data could be known to us and could be displayed. As it would be running very fast it have to be read out individually. Hence, we have created a delay such that the data could be read page by page and also we can quit at any time.

4.3.2 SEARCH AND DISPLAY:

The flowchart for this subprogram is shown in fig.(4.2b).When this area is reached, we will be able to get the x and y coordinates of the RCMT board when the nail number or the component name is asked. This depends upon the user whether he want to get the information using the nail number or the component name. The co-ordinates could be located by means of a Stepper motor arrangement which is interfaced to the Personal Computer.

If we call for the search and display menu it will reach the subprogram SAD which is the search and display option. The x and y coordinate of a particular component is selected by means of entering the nail number or the component name. This is done by selecting any option in the menu, and those are,

- 1) **SELECT BY COMPONENT**
- 2) **SELECT BY NAIL**
- 3) **HELP**

4.3.3 SELECT BY NAIL:

When this is called for it will reach the subprogram SBN (Select by nail) and would open a file name SANJU.DAT. When the file opens, the nail number of reach records in that file. If both are same, displaying of co-ordinates takes place or else the data is not displayed. Unless we quit, the process of getting the co-ordinates is done.

4.3.4 SELECT BY COMPONENT:

The flowchart for this subprogram is shown in fig.(4.3a). When this program is called for, then it will reach the subprogram SBC (SELECT BY COMPONENT) and this would cause either the SMT components or the Conventional components data base would open. By entering the name of the component either SMT or Conventional it's corresponding X and Y co-ordinates could be displayed. This X and Y co-ordinates could be taken to the Stepper motor arrangement with the help of the Input / Output port via the address decoder.

4.3.5 DISPLAY COMPONENTS:

When this subprogram is called for, then it would reach the subprogram COMP (COMPONENTS) which has two options with it.

When we select, either of the option then the corresponding data base could be displayed. There is a provision for it to handle the components individually. There are two data files namely,

1) **SMT.DAT**

2) **MAN.DAT**

The first file has the data base of the Surface mounted components and the second has the data base of the Conventional components. The sub records have the name of the component, tolerance, Code used in the industry, value, X coordinate and the Y coordinate. The MAN file has also the same sub records as for the SMT components. After this, provision has been given to either continue in the same loop or to QUIT to the main program.

4.3.6 INSERTION ASSEMBLY:

The flowchart for this subprogram is shown in fig.(4.3b). When this is called for, it would reach the INST sub program and this would make the computer to open the SMT.DAT and MAN.DAT. Depending upon the application, that it whether there is a need to insert the component on the SMT side or the Conventional side the corresponding answer should be given to the program. This would cause the selection of the SMT data base or the MAN data base resulting in the insertion assembly of the component.

4.3.7 STEP X & STEP Y:

This is the subprogram which is responsible for the operation of the Stepper motor. This out ports the switching sequence of the Stepper motor and this would cause the Stepper motor to move in the X direction. The switching sequence is for the clockwise direction and the subprogram STEP Y is for the same purpose but it is the Y direction.

4.3.8 STEPS X & STEPS Y:

This is the subprogram which is responsible for the anti clockwise operation of the Stepper motor. This out ports the switching sequence of the Stepper motor and this would cause the Stepper motor to move in the X direction. The switching sequence is for the anti clockwise direction and the subprogram STEP Y is for the same purpose but it is the Y direction.

**PROGRAMS
&
FLOWCHARTS**

```

DECLARE SUB INFO ( )
DECLARE SUB HELP ( )
DECLARE SUB SBC ( )
DECLARE SUB SMTDI (NA$, k%, ELE)
DECLARE SUB CONDI (MA$, k%, ELE)
DECLARE SUB COMP ( )
DECLARE SUB DISCO ( )
DECLARE SUB INST ( )
DECLARE SUB SAD ( )
DECLARE SUB SBN ( )
DECLARE SUB DISPLAYSET ( )
CLS
SCREEN 1
  FOR N = 1 TO 59
    PP = (N - 1) * 10
    LINE (PP, 6)-(PP * 0, 9), 2, BF
    LINE (PP, 190)-(PP * 0, 193), 2, BF
    COLOR 1
  NEXT N
PETALS$ = " s16 BM50,100 M-2,-7 E2 F2 M-2,7"
COLR% = 1
  FOR I% = 0 TO 330 STEP 30
    COLR% = 3 - COLR%
    DRAW "C=" + VARPTR$(COLR%)
    DRAW "TA=" + VARPTR$(I%) + PETALS$
  NEXT I%
LOCATE 9, 25: PRINT "WELCOME"
LOCATE 12, 28: PRINT "TO "
LOCATE 15, 24: PRINT "R C M T 4"
LOCATE 18, 25: PRINT "DATABASE"
LOCATE 23, 20: PRINT "WAIT!"
  FOR k = 1 TO 1000
    FOR j = 1 TO 200
      NEXT j
    NEXT k
CLS
COLOR 13
PRINT "*****"
PRINT
PRINT "          HELP          - H"
PRINT
PRINT "          INFO          - I"
PRINT
PRINT "          CONTINUE      - C"
PRINT
PRINT "*****"
LOCATE 20, 1: INPUT "ENTER THE MENU CODE"; Z$
SELECT CASE UCASE$(Z$)
  CASE "H"
    CALL HELP

```

```

CASE "I"
  CALL INFO
CASE ELSE
END SELECT
7 CLS
  COLOR 1
  SCREEN 1
  PRINT "*****"
  PRINT
  PRINT "      DISPLAY SET                - D"
  PRINT
  PRINT
  PRINT "      SEARCH AND DISPLAY            - S"
  PRINT
  PRINT
  PRINT "      DISPLAY COMPONENTS            - C"
  PRINT
  PRINT
  PRINT "      INSERTION ASSEMBLY            - A"
  PRINT
  PRINT
  PRINT "      HELP                            - H"
  PRINT
  PRINT
  PRINT "      QUIT                            - Q"
  PRINT
  PRINT "*****"
  PRINT
  INPUT "ENTER THE MENU CODE"; C$
  PRINT
  PRINT
  CLS
  SELECT CASE UCASE$(C$)
    CASE "D"
      CALL DISPLAYSET
    CASE "S"
      CALL SAD
    CASE "A"
      CALL INST
    CASE "C"
      CALL COMP

```

```

        CASE "H"
            CALL HELP
        CASE "Q"
            GOTO 10
    END SELECT
CLS
SCREEN 1
COLOR 1
    IF x$ = "C" THEN
        GOTO 7
    ELSE
        END IF
        GOTO 7
10 CLS
    COLOR 13
        LOCATE 12, 18: PRINT "GOOD BYE"
    DO
        BEEP
        LOOP UNTIL INKEY$ <> ""
        PRINT
    CLS
END

```

```

SUB COMP
DO
COLOR 13
LOCATE 3, 15: PRINT "COMPONENTS"
LOCATE 7, 16: PRINT "DISPLAY"
LOCATE 12, 18: PRINT "SMT"
LOCATE 16, 19: PRINT "&"
LOCATE 20, 17: PRINT "MANUAL"
LOCATE 23, 1: PRINT "Press any key to continue..."
LOOP UNTIL INKEY$ <> ""
CLS
2 PRINT "*****"
PRINT
PRINT "          SELECT SMT    S"
PRINT
PRINT "          SELECT MAN    M"
PRINT
PRINT "          HELP          H"
PRINT
PRINT "*****"
PRINT
INPUT "ENTER THE MENU CODE"; ME$
CLS
IF ME$ = "H" THEN
CALL HELP
ELSE
END IF
IF ME$ = "S" THEN
ELE = 155
k% = 1
OPEN "smt.dat" FOR INPUT AS #k%
PRINT "*****"
PRINT
PRINT "          RESISTOR - 1 (10 K ) - R1"
PRINT
PRINT "          RESISTOR - 2 (3.3 K ) - R2"
PRINT
PRINT "          CAPACITOR- 1 (330 PF ) - C1"
PRINT
PRINT "          CAPACITOR- 2 ( 10 NF ) - C2"
PRINT
PRINT "          CAPACITOR- 3 (100 NF ) - C3"
PRINT
PRINT "*****"
COLOR 3
LOCATE 17, 13: INPUT "ENTER NAME"; NA$
CLS
SELECT CASE UCASE$(NA$)
CASE "R1"
CALL SMTDI(NA$, k%, ELE)

```

```

CASE "R2"
    CALL SMTDI(NA$, k%, ELE)
CASE "C1"
    CALL SMTDI(NA$, k%, ELE)
CASE "C2"
    CALL SMTDI(NA$, k%, ELE)
CASE "C3"
    CALL SMTDI(NA$, k%, ELE)
CASE ELSE
DO
    BEEP
    LOCATE 12, 15: PRINT "NO SUCH DATA"
    LOCATE 23, 1: PRINT "Press any key to continue..."
    LOOP UNTIL INKEY$ <> ""
END SELECT
CLOSE #1
ELSEIF ME$ = "M" THEN
    ELE = 201
    k% = 2
    OPEN "man.dat" FOR INPUT AS #k%
CLS
SCREEN 1
COLOR 3
PRINT
PRINT "-----"
PRINT " RESISTOR R1 (100K) R2 (220H) R3 (22H)"
PRINT " RESISTOR R4 (10K) R5 (100H) R6 (2000)"
PRINT " RESISTOR R7 (1M) R8 (120H)"
PRINT " DIODE D1 (BZX55C) D2 (IN4148)"
PRINT " RESEAU U1 (H29) U2 (H05)"
PRINT " SIL S1 S2 (H05)"
PRINT " IC.LOGIQ L1 (74AC14) L2 (74AC374)"
PRINT " IC.LOGIQ L3 (74AC00) L4 (74AC299)"
PRINT " IC.LOGIQ L5 (74AC74)"
PRINT " CI.LOGIQUE C1 (74AC244)"
PRINT " CI.LOGIQUE C2 (74ACT374)"
PRINT " GENBENGATE GE"
PRINT " COND CO"
PRINT " INDUCT IN"
PRINT " LARA ACTIV LA"
PRINT " CI.MEM CI"
PRINT " RGTR2 RG"
PRINT " IC.PREDIF IC"
PRINT "-----"
LOCATE 24, 1: INPUT "ENTER THE MENU CODE "; MA$
CLS
SELECT CASE UCASE$(MA$)
CASE "R1"
    CALL CONDI(MA$, k%, ELE)
CASE "R2"
    CALL CONDI(MA$, k%, ELE)

```

```
CASE "R3"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE "R4"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE "R5"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE "R6"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE "R7"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE "D1"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE "D2"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE "U1"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE "U2"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE "S1"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE "S2"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE "L1"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE "L2"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE "L3"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE "L4"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE "L5"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE "C1"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE "C2"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE "GE"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE "CO"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE "IN"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE "LA"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE "CI"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE "RG"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE "IC"  
    CALL CONDI(MAŞ, k%, ELE)  
CASE ELSE
```



```
SUB DISPLAYSET
```

```
COLOR 1
```

```
SCREEN 2
```

```
CLS
```

```
OPEN "sanju.dat" FOR INPUT AS #3
```

```
FOR k = 1 TO 67
```

```
PRINT "-----"
```

```
PRINT "Nailno.          comp          signal          X coord          Y
```

```
PRINT "-----"
```

```
FOR j = 1 TO 18
```

```
INPUT #3, N%, cn$, S$, x!, y!
```

```
PRINT N%, cn$, S$, x!, y!
```

```
NEXT j
```

```
LOCATE 23, 1: INPUT "Press any key to continue and Q to QUIT ";
```

```
IF UCASE$(sh$) = "Q" THEN
```

```
GOTO 17
```

```
ELSE
```

```
END IF
```

```
CLS
```

```
NEXT k
```

```
PRINT "-----"
```

```
PRINT "Nailno.          comp          signal          X coord          Y
```

```
PRINT "-----"
```

```
FOR j = 1 TO 15
```

```
INPUT #3, N%, cn$, S$, x!, y!
```

```
PRINT N%, cn$, S$, x!, y!
```

```
NEXT j
```

```
LOCATE 23, 1: PRINT "Press any key to continue "
```

```
DO
```

```
LOOP UNTIL INKEY$ <> ""
```

```
17 CLS
```

```
CLOSE #3
```

```
END SUB
```

SUB HELP

CLS

```
PRINT "1.DISPLAY SET"  
PRINT "-----"  
PRINT "  
PRINT "      By entering this area you will be "  
PRINT "  
PRINT "able to scroll through the data "  
PRINT "  
PRINT "available for the SCORPION machine"  
PRINT "  
PRINT "in groups. SCORPION machine gives "  
PRINT "  
PRINT "nail no., node, X & Y coordinates"  
LOCATE 23, 1: PRINT "Press any key to continue..."
```

DO

LOOP UNTIL INKEY\$ <> ""

CLS

```
PRINT "2.SEARCH & DISPLAY"  
PRINT "-----"  
PRINT "  
PRINT "      In this area you will be able to get"  
PRINT "  
PRINT "X & Y coordinates for the RCMT board by"  
PRINT "  
PRINT "nailno.& also the coordinates by name of"  
PRINT "  
PRINT "the components either SMT/Conventional."  
PRINT "  
PRINT "The coordinates could be located by"  
PRINT "  
PRINT "means of a stepper motor arrangement."  
LOCATE 23, 1: PRINT "Press any key to continue..."
```

DO

LOOP UNTIL INKEY\$ <> ""

CLS

```
PRINT "3.DISPLAY COMPONENTS"  
PRINT "-----"  
PRINT "  
PRINT "      When entered in this menu, SMT/"  
PRINT "  
PRINT "Conventional components are to be"  
PRINT "  
PRINT "selected. Depending on your option, the"  
PRINT "  
PRINT "respective list of components could be "  
PRINT "  
PRINT "displayed."  
LOCATE 23, 1: PRINT "Press any key to continue..."
```

DO

```

SUB INST
CLS
SCREEN 1
COLOR 4
OPEN "smt.dat" FOR INPUT AS #1
OPEN "man.dat" FOR INPUT AS #2
OPEN "sanju.dat" FOR INPUT AS #3
INPUT " SMT -S MAN -M "; y$
IF y$ = "S" THEN
  FOR I = 1 TO 155
    INPUT #1, N$, x!, y!
    IF LEFT$(UCASE$(N$), 2) = "R1" THEN
      OUT 230, 0
    ELSEIF LEFT$(UCASE$(N$), 2) = "R2" THEN
      OUT 230, 1
    ELSEIF LEFT$(UCASE$(N$), 2) = "C1" THEN
      OUT 230, 2
    ELSEIF LEFT$(UCASE$(N$), 2) = "C2" THEN
      OUT 230, 3
    ELSEIF LEFT$(UCASE$(N$), 2) = "C3" THEN
      OUT 230, 4
    END IF
    CALL STEPX(x!)
    FOR l = 1 TO 100
      FOR k = 1 TO 100
        NEXT k
      NEXT l
    CALL STEPY(y!)
    FOR l = 1 TO 100
      FOR k = 1 TO 100
        NEXT k
      NEXT l
    CALL STEPAX(x!)
    FOR l = 1 TO 100
      FOR k = 1 TO 100
        NEXT k
      NEXT l
    CALL STEPAY(y!)
    FOR l = 1 TO 100
      FOR k = 1 TO 100
        NEXT k
      NEXT l
  NEXT I
CLS
  LOCATE 10, 12: PRINT "PUT YOUR COMPONENT"
DO
LOOP UNTIL INKEY$ <> ""
  NEXT I
ELSE
  FOR I = 1 TO 249

```

```

CLS
        LOCATE 12, 10: PRINT "NO SUCH DATA"
    DO
        LOOP UNTIL INKEY$ <> ""
        END SELECT
    END IF
    CLOSE #2
CLS
        LOCATE 11, 18: PRINT "QUIT           - Y"
        LOCATE 13, 18: PRINT "CHECK AGAIN - N"
        LOCATE 20, 18: INPUT "ENTER "; D$
    IF D$ = "N" THEN
CLS
        GOTO 2
    ELSE
    END IF
END SUB

SUB SAD
    COLOR 2
    PRINT "*****"
    PRINT
    PRINT "          SELECT BY NAIL           - N"
    PRINT
    PRINT "          SELECT BY COMP           - C"
    PRINT
    PRINT "          HELP                       - H"
    PRINT
    PRINT "*****"
    PRINT
    PRINT
    INPUT "INPUT MENU CODE"; MENU$
    SCREEN 2
    SELECT CASE UCASE$(MENU$)
        CASE "N"
            CALL SBN
        CASE "C"
            CALL SBC
        CASE "H"
            CALL HELP
        CASE "Q"
            END
        CASE ELSE
            BEEP
    END SELECT
END SUB

```

```

SUB SBC
CLS
SCREEN 1
COLOR 12

INPUT " FOR SMT - S & FOR CON - M"; R$
CLS
IF R$ = "S" THEN
9 OPEN "smt.dat" FOR INPUT AS #1
LOCATE 5, 1: INPUT "ENTER THE COMP NAME"; CO$
FOR I = 1 TO 155
INPUT #1, N$, C$, V$, T$, x!, y!
IF MID$(N$, 4) = CO$ THEN
COLOR 13
CLS
LOCATE 3, 2: PRINT "COMP"
LOCATE 3, 10: PRINT MID$(N$, 4)
LOCATE 5, 2: PRINT "CODE"
LOCATE 5, 10: PRINT C$
LOCATE 7, 2: PRINT "SPEC"
LOCATE 7, 10: PRINT V$
LOCATE 9, 2: PRINT "TOLE"
LOCATE 9, 10: PRINT T$
LOCATE 11, 2: PRINT "X Cord"
LOCATE 11, 10: PRINT x!
LOCATE 13, 2: PRINT "Y Cord"
LOCATE 13, 10: PRINT y!
ELSE
END IF
NEXT I
CLOSE #1
LOCATE 20, 1: PRINT "Press any key to continue..."
DO
LOOP UNTIL INKEY$ <> ""
CLS
LOCATE 13, 18: PRINT "Quit - Q"
LOCATE 15, 18: PRINT "Check - C"
LOCATE 20, 18: INPUT "Enter - "; FC$
IF FC$ = "C" THEN
CLS
I = 1
GOTO 9
ELSE
END IF
ELSE
OPEN "man.dat" FOR INPUT AS #1
LOCATE 5, 1: INPUT "ENTER THE COMP NAME"; CO$
FOR I = 1 TO 248
INPUT #1, I$, C$, N$, V$, T$, x!, y!
IF N$ = CO$ THEN

```

```

SUB SBN
  SCREEN 1
  COLOR 3
4 OPEN "sanju.dat" FOR INPUT AS #3
  INPUT "ENTER THE NAIL NUMBER"; A%
  IF A% <= 1239 THEN
    N% = 1221
    CLS
    PRINT
    LOCATE 1, 4: PRINT "*****"
    PRINT
    LOCATE 3, 4: PRINT "Nail no      X coord      Y coord"
    LOCATE 5, 4: PRINT "*****"
    PRINT
    FOR I = 1 TO N%
      INPUT #3, B%, cn$, S$, x!, y!
      IF B% = A% THEN GOTO 20
    NEXT I
20 LOCATE 8, 5: PRINT B%: LOCATE 8, 17: PRINT x!: LOCATE 8, 30
    ELSE
    CLS
    COLOR 3
      LOCATE 12, 13: PRINT "NO SUCH DATA...!"
    END IF
    DO
    LOOP UNTIL INKEY$ <> ""
    CLOSE #3
    CLS
      LOCATE 13, 18: PRINT "QUIT      - Q"
      LOCATE 15, 18: PRINT "CHECK    - C"
      LOCATE 20, 18: INPUT "ENTER      "; F$
    IF F$ = "C" THEN
    CLS
      I = 1
      GOTO 4
    ELSE
    END IF
    CLOSE #3
END SUB

```

```

SUB CONDI (MA$, k%, ELE)
FOR I = 1 TO ELE
INPUT #k%, I$, N$, C$, T$, V$, x!, y!
IF MA$ = LEFT$(UCASE$(N$), 2) THEN
PRINT
PRINT "NAME    "; N$
PRINT
PRINT
PRINT "CODE    "; C$
PRINT
PRINT
PRINT "TOLERA "; T$
PRINT
PRINT
PRINT "VALUE  "; V$
PRINT
PRINT "X Cord "; x!
PRINT
PRINT
PRINT "Y Cord "; y!
LOCATE 20, 1: PRINT "Press any key to continue..."
DO
LOOP UNTIL INKEY$ <> ""
CLS
ELSE
END IF
NEXT I
END SUB

```

```

SUB STEPAY (x!)
FO% = x% / 100 * 2.5
FOR I = 1 TO FO%
FOR j = 1 TO 8
OUT 230, 246
OUT 230, 176
OUT 230, 252
OUT 230, 176
OUT 230, 249
OUT 230, 176
OUT 230, 243
OUT 230, 176
NEXT j
NEXT I
END SUB

```

```

SUB STEPY (y!)
  FO% = y! / 100 * 2.5
  FOR I = 1 TO FO%
    FOR j = 1 TO 8
      OUT 230, 115
      OUT 230, 48
      OUT 230, 121
      OUT 230, 48
      OUT 230, 124
      OUT 230, 48
      OUT 230, 118
      OUT 230, 48
    NEXT j
  NEXT I
DO
  LOOP UNTIL INKEY$ <> ""
END SUB

```

```

SUB STEPX (x!)
  FO% = x! / 100 * 2.5
  FOR I = 1 TO FO%
    FOR j = 1 TO 8
      OUT 230, 243
      OUT 230, 176
      OUT 230, 249
      OUT 230, 176
      OUT 230, 252
      OUT 230, 176
      OUT 230, 246
      OUT 230, 176
    NEXT j
  NEXT I
END SUB

```

```

SUB STEPAY (y!)
  FO% = y% / 100 * 2.5
  FOR I = 1 TO FO%
    FOR j = 1 TO 8
      OUT 230, 246
      OUT 230, 176
      OUT 230, 252
      OUT 230, 176
      OUT 230, 249
      OUT 230, 176
      OUT 230, 243
      OUT 230, 176
    NEXT j
  NEXT I
END SUB

```



```

SUB SMTDI (NA$, k%, ELE)
  FOR I = 1 TO ELE
    INPUT #k%, N$, C$, T$, V$, x!, y!
    IF NA$ = LEFT$(UCASE$(N$), 2) THEN
      PRINT
      PRINT "NAME           "; N$
      PRINT
      PRINT "CODE             "; C$
      PRINT
      PRINT "SIGNAL           "; S$
      PRINT
      PRINT "TOLERANCE        "; T$
      PRINT
      PRINT "VALUE            "; V$
      PRINT
      PRINT "X Coord.         "; x!
      PRINT
      PRINT "Y Coord.         "; y!
      LOCATE 20, 1: PRINT "Press any key to continue..."
    DO
      LOOP UNTIL INKEY$ <> ""
    CLS
  ELSE
    END IF
  NEXT I
END SUB

```

```

LOOP UNTIL INKEY$ <> ""
CLS
PRINT "4.INSERTION ASSEMBLY"
PRINT "-----"
PRINT "
      When entered into this menu you"
PRINT "will be able to do the FIRST LINE"
PRINT "INSERTION ASSEMBLY by means of a stepper"
PRINT "motor arrangement, which locates the"
PRINT "X & Y coordinates."
LOCATE 23, 1: PRINT "Press any key to continue..."
DO
LOOP UNTIL INKEY$ <> ""
END SUB

```

SUB INFO

```

CLS
SCREEN 1
COLOR 13
LOCATE 2, 15: PRINT ""
LOCATE 4, 15
PRINT "-----"
LOCATE 6, 10
PRINT "PROJECT WORK DONE BY"
LOCATE 8, 12
PRINT "R.ARUMUGAM"
LOCATE 10, 14
PRINT "W.JOSEPH ANAND"
LOCATE 12, 16
PRINT "K.SANJITH KUMAR"
LOCATE 14, 18
PRINT "P.L.SATHISH KUMAR"
LOCATE 16, 20
PRINT "A.SHANMUGASUNDARAM"
LOCATE 18, 14
PRINT "EXTERNAL GUIDE - Mr.P.SATHISH KUMAR"
LOCATE 20, 14
PRINT "INTERNAL GUIDE - Mrs.N.KALAIARASI B.E.,"
LOCATE 22, 10
PRINT "-----"
DO
LOOP UNTIL INKEY$ <> ""
END SUB

```

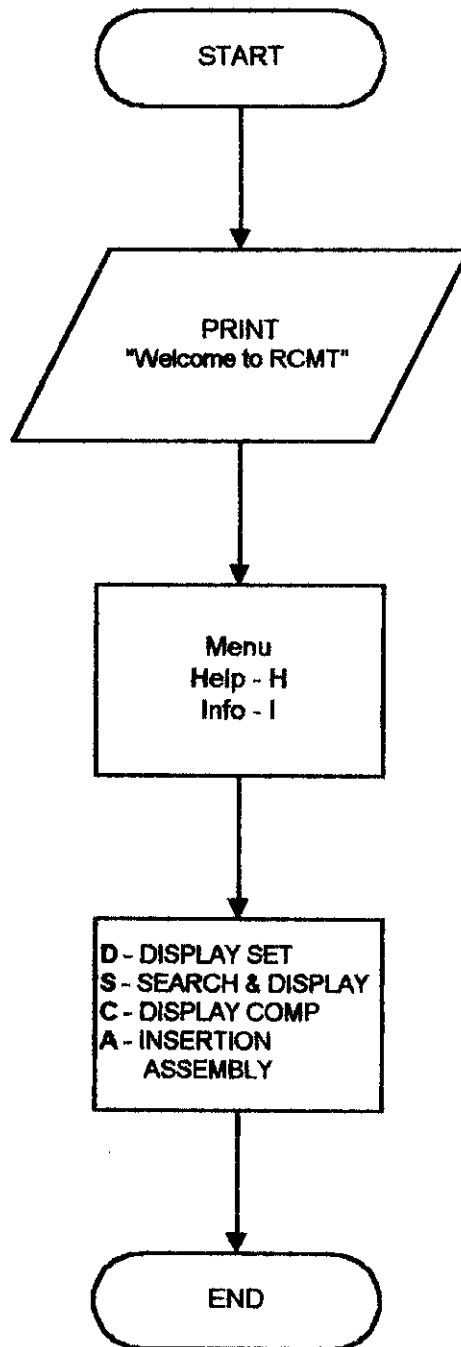
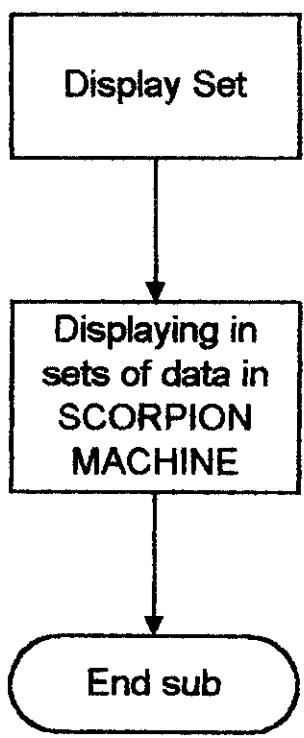


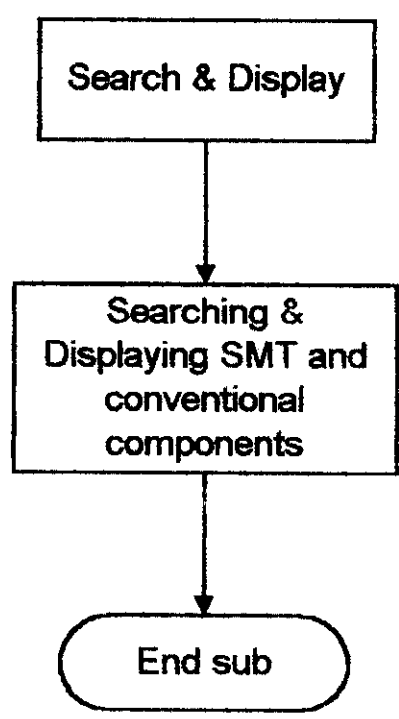
Fig.(4.1) Main program

Sub programs

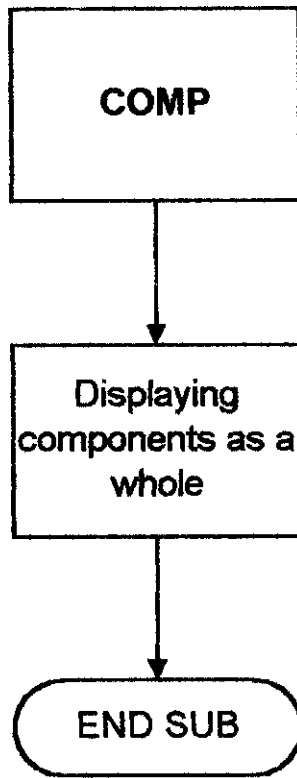
a.



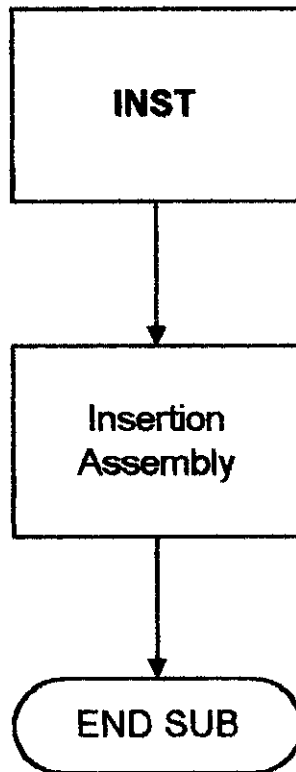
b.



a.



b.



Chapter 5
CONCLUSION

A **multipurpose test system** using Personal Computer, Input / Output card, Demultiplexer card and Stepper Motor interface card has been designed and fabricated . This system enables the location of Coordinates of RCMT board in OCB exchange quickly. A Software has been developed in QBASIC to control the functions of the test system.

The Multipurpose test system enables for performing Component Location and First Line Insertion Assembly. We modestly claim that the design meets Industrial Standards. The design which are based on digital Integrated Circuits is **quite flexible**.

During the course of development of the system, we reached a conclusion that the system developed is an **ideal tool** for the reduction of manual work. This process increases the usage and lifetime of Printed Circuit Boards (PCB) which are rejected when debugged manually. But, this is not the end of the road. Steps for **further development** of the system are also incorporated.

- 1) More user friendly, graphical oriented and **efficient package** could be developed.
- 2) **Full automation** by picking and placing using Robots.
- 3) Making testing method more simple by interfacing with the Scorpion Machine and using the **Scorpion software**.

REFERENCES

- 1) GAONKAR, "Microprocessor Architecture, programming and applications with the 8085/8080 A", Wiley Eastern Limited, New Delhi, 1992.
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- 3) STEVEN AND NAMEROFF, "QUICK BASIC the complete Reference", McGraw Hill International Editions, Newyork, 1989.
- 4) VINCENT DEL TORO, "Electrical machinery fundamentals", Prentice - Hall of India, New Delhi, 1988.
- 5) "Scorpion MDA manual",ALCATEL CIT, FRANCE.
- 6) "PC User Reference Manual",INTEL.
- 7) "OCB 283 Exchange Manual",ALCATEL CIT, FRANCE.
- 8) "PHILIPS data book", PHILIPS.
- 9) MORRIS MANO, "Digital logic and Computer Design",Prentice - Hall of India Private Ltd.,New Delhi,1995.
- 10) FLOYD, "Digital fundamentals",McGraw Hill International Editions, Newyork,1989.

APPENDIX

T54LS154 T74LS154



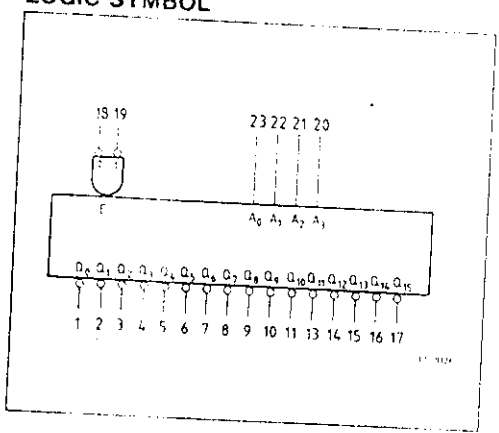
4-LINE-TO-16-LINE DECODERS/DEMULTIPLEXERS

DESCRIPTION

The T54LS/T74LS154 is a 4-line-to-16-line decoder. It provided decoding of four binary-coded inputs into one of sixteen mutually exclusive outputs when both the strobe inputs, E_1 and E_2 , are in the low state. Each of the strobe input can be used as a data input to perform the demultiplexing function by using the 4 input lines to address the output line and having the other strobe input low. When either strobe input is high, all outputs are high.

- DECODERS 4 BINARY-CODED INPUTS INTO ONE OF 16 MUTUALLY EXCLUSIVE OUTPUTS
- PERFORMS THE DEMULTIPLEXING FUNCTION BY DISTRIBUTING DATA FROM ONE INPUT LINE TO ANY ONE OF 16 OUTPUTS

LOGIC SYMBOL



PRELIMINARY DATA



B1
Plastic Package

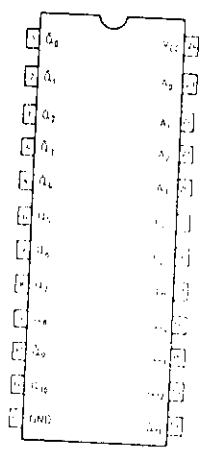


D1/D2
Ceramic Package

ORDERING NUMBERS:
T54LS154 D2
T74LS154 D1
T74LS154 B1

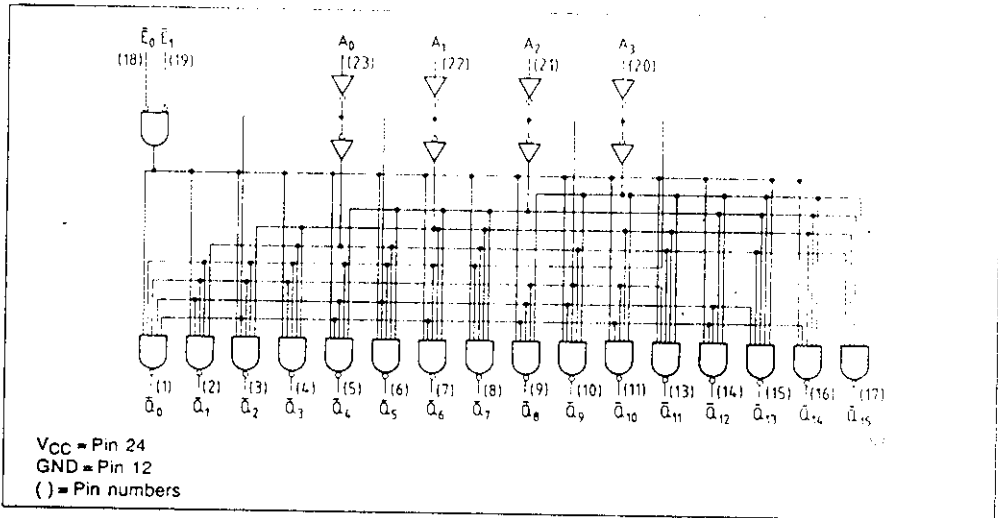
PIN CONNECTION (top view)

DUAL IN LINE



T54LS154 T74LS154

LOGIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS

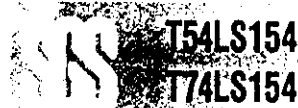
Symbol	Parameter	Value	Unit
V_{CC}	Supply Voltage	-0.5 to 7	V
V_I	Input Voltage, Applied to Input	-0.5 to 7	V
V_O	Output Voltage, Applied to Output	0 to 5	V
I_I	Input Current, Into Inputs	30 to 1	mA
I_O	Output Current, Into Outputs	50	mA

Stresses in excess of those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions in excess of those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

GUARANTEED OPERATING RANGES

Part Numbers	Supply Voltage			Temperature
	Min	Typ	Max	
T54LS154D2	4.5 V	5.0 V	5.5 V	55°C to +125°C
T74LS154XX	4.75 V	5.0 V	5.25 V	0°C to +70°C

XX = package type.



DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE

Symbol	Parameter	Limits			Test Conditions (Note 1)	Units
		Min.	Typ.	Max.		
V _{IH}	Input HIGH Voltage	2.0			Guaranteed input HIGH Voltage for all Inputs	V
V _{IL}	Input LOW Voltage	54		0.7	Guaranteed input LOW Voltage for all Inputs	V
		74		0.8		
V _{CD}	Input Clamp Diode Voltage			- 1.5	V _{CC} = MIN, I _{IN} = - 18mA	V
V _{OH}	Output HIGH Voltage	54	2.5	3.4	V _{CC} = MIN, I _{OH} = - 400μA, V _{IN} = V _{IL}	V
		74	2.7	3.4		
V _{OL}	Output LOW Voltage	54,74	0.25	0.4	I _{OL} = 4.0mA	V _{CC} = MIN, V _{IN} = 2.0V
		74	0.35	0.5	I _{OL} = 8.0mA	
I _{IH}	Input HIGH Current			20 0.1	V _{CC} = MAX, V _{IN} = 2.7V V _{CC} = MAX, V _{IN} = 7.0V	μA
I _{IL}	Input LOW Current			- 0.4	V _{CC} = MAX, V _{IN} = 0.4V	mA
I _{OS}	Output Short Circuit Current (Note 2)	- 15		- 100	V _{CC} = MAX	mA
I _{CC}	Power Supply Current (Note 3)			14	V _{CC} = MAX	mA

AC CHARACTERISTICS: T_A = 25°C

Symbol	Parameter	Limits			Test Conditions	Units
		Min.	Typ.	Max.		
t _{PLH}	Propagation Delay			36	Fig. 1	ns
t _{PHL}	Address to output			33		
t _{PLH}	Propagation Delay			30	Fig. 2	ns
t _{PHL}	Enable to output			27		

Notes:

- 1) For conditions shown as MIN or MAX, use the appropriate value specified under guaranteed operating ranges.
- 2) Not more than one output should be shorted at a time.
- 3) Measure I_{CC} with all inputs grounded and all output open.
- 4) Typical values are at V_{CC} = 5.0V, T_A = 25°C

Signetics

FAST 74F32 Gate

Quad Two-Input OR Gate
Product Specification

Logic Products

FUNCTION TABLE

INPUTS		OUTPUT
A	B	Y
L	L	L
L	H	H
H	L	H
H	H	H

H = HIGH voltage level
L = LOW voltage level

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F32	4.1ns	8.2mA

ORDERING CODE

PACKAGES	COMMERCIAL RANGE $V_{CC} = 5V \pm 10\%$; $T_A = 0^\circ C$ to $+70^\circ C$
Plastic DIP	N74F32N
Plastic SO-14	N74F32D

NOTES:

- SO package is surface-mounted micro-miniature DIP.
- For information regarding devices processed to Military Specifications, see the Signetics Military Product Data Manual.

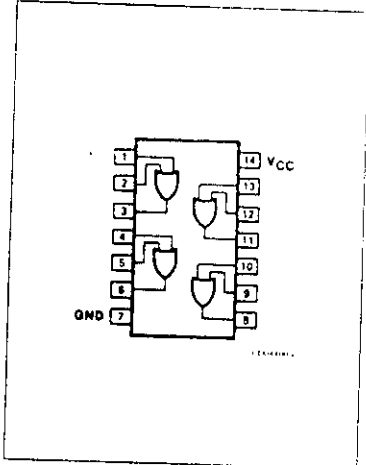
INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

PINS	DESCRIPTION	74F(U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
A, B	Inputs	1.0/1.0	20 μ A/0.6mA
Y	Outputs	50/33	1.0mA/20mA

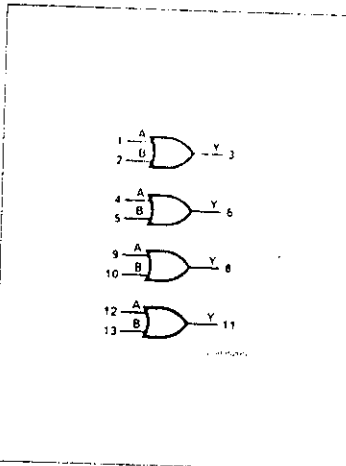
NOTE:

One (1) FAST Unit Load (U.L.) is defined as 20 μ A in the HIGH state and 0.6mA in the LOW state.

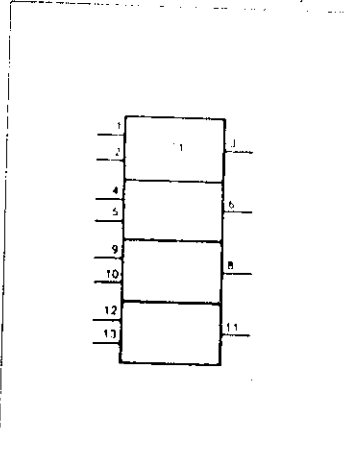
PIN CONFIGURATION



LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)



Gate

FAST 74F32

ABSOLUTE MAXIMUM RATINGS (Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted, these limits are over the operating free-air temperature range.)

PARAMETER	74F	UNIT
V _{CC} Supply voltage	0.5 to 12.0	V
V _{IN} Input voltage	0.5 to 12.0	V
I _{IN} Input current	30 to 15	mA
V _{OUT} Voltage applied to output in HIGH output state	-0.5 to +V _{CC}	V
I _{OUT} Current applied to output in LOW output state	40	mA
T _A Operating free-air temperature range	0 to 70	°C

RECOMMENDED OPERATING CONDITIONS

PARAMETER	74F			UNIT
	Min	Nom	Max	
V _{CC} Supply voltage	4.5	5.0	5.5	V
V _{IH} HIGH-level input voltage	2.0			V
V _{IL} LOW-level input voltage			0.8	V
I _{IK} Input clamp current			-18	mA
I _{OH} HIGH-level output current			-1	mA
I _{OL} LOW-level output current			20	mA
T _A Operating free-air temperature	0		70	°C

DC ELECTRICAL CHARACTERISTICS (Over recommended operating free-air temperature range unless otherwise noted.)

PARAMETER	TEST CONDITIONS ¹	74F32			UNIT	
		Min	Typ ²	Max		
V _{OH} HIGH-level output voltage	V _{CC} = MIN, V _{IH} = MAX, I _{OH} = MAX V _{IH} = MIN, I _{OH} = MIN	±10%V _{CC} 2.5			V	
V _{OL} LOW-level output voltage	V _{CC} = MIN, V _{IL} = MAX, I _{OL} = MAX V _{IL} = MIN, I _{OL} = MIN	±15%V _{CC} ±10%V _{CC}	1.4		V	
V _{IK} Input clamp voltage	V _{CC} = MIN, I _I = I _{IK}		35	0.0	V	
I _I Input clamp current at maximum input voltage	V _{CC} = MAX, V _I = 7.0V		-0.73	-1.1	mA	
I _{IH} HIGH-level input current	V _{CC} = MAX, V _I = 2.7V			100	mA	
I _{IL} LOW-level input current	V _{CC} = MAX, V _I = 0.5V		1	20	mA	
I _{OS} Short-circuit output current ³	V _{CC} = MAX, V _O = 0.0V		-0.4	-0.6	mA	
I _{CC} Supply current (total)	V _{CC} = MAX	I _{CC} H	-60	-90	mA	
		I _{CC} L	V _{IN} = 4.5V	6.1	9.0	mA
			V _{IN} = GND	10.3	15.0	mA

NOTES:

1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
2. All typical values are at V_{CC} = 5V, T_A = 25°C.
3. Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold techniques are preferred in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a HIGH output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

6

Gate

FAST

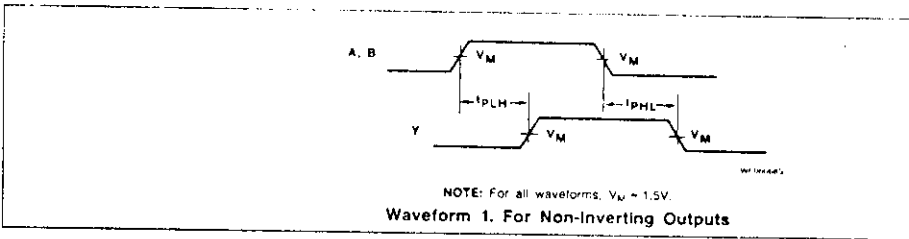
AC ELECTRICAL CHARACTERISTICS

PARAMETER	TEST CONDITIONS	74F32					
		T _A = +25°C V _{CC} = +5.0V C _L = 50pF R _L = 500Ω			T _A = 0°C to +70°C V _{CC} = +5.0V ± 10% C _L = 50pF R _L = 500Ω		
		Min	Typ	Max	Min	Max	
t _{PLH} t _{PHL}	Propagation delay A, B to Y	Waveform 1	3.0	4.2	5.6	3.0	6.6
			3.0	4.0	5.3	3.0	6.3

NOTE:

Subtract 0.2ns from minimum values for SO package.

AC WAVEFORM



TEST CIRCUIT AND WAVEFORMS

Test Circuit For Totem-Pole Outputs

DEFINITIONS

R_L = Load resistor; see AC CHARACTERISTICS for value.
 C_L = Load capacitance includes jig and probe capacitance, see AC CHARACTERISTICS for value.
 R_T = Termination resistance should be equal to Z_{OUT} of pulse generators

V_M = 1.5V
Input Pulse Definition

FAMILY	INPUT PULSE REQUIREMENTS			
	Amplitude	Rep. Rate	Pulse Width	t _{FLUX}
74F	3.0V	1MHz	500ns	25ns

TYPES SN54ALS688, SN54ALS689, SN74ALS688, SN74ALS689 8-BIT IDENTITY COMPARATORS

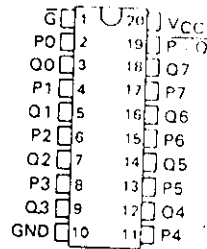
02661, JUNE 1982 REVISED (DECEMBER 1981)

- Compares Two Eight-Bit Words
- Choice of Totem-Pole or Open-Collector Outputs
- Package Options Include Both Plastic and Ceramic Chip Carriers in Addition to Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

TYPE	OUTPUT FUNCTION AND CONFIGURATION
'ALS688†	P = Q totem-pole
'ALS689	P = Q open-collector

†'ALS688 is identical to 'ALS521

SN54ALS688, SN54ALS689 ... J PACKAGE
SN74ALS688, SN74ALS689 ... N PACKAGE
(TOP VIEW)



description

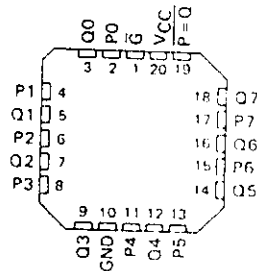
These identity comparators perform comparisons of two eight-bit binary or BCD words. The 'ALS688 and 'ALS689 provide P = Q outputs. The 'ALS688 has totem-pole outputs, while 'ALS689 has open-collector outputs.

The SN54ALS688 and SN54ALS689 are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS688 and SN74ALS689 are characterized for operation from 0°C to 70°C.

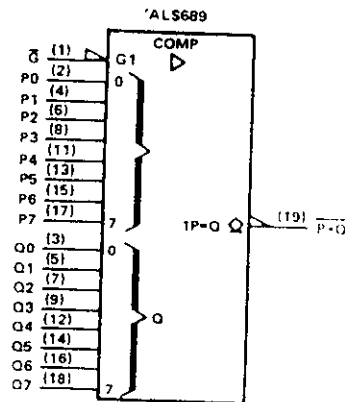
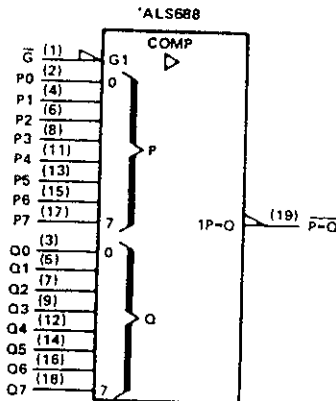
FUNCTION TABLE

INPUTS		OUTPUT
DATA	ENABLE	
P, Q	\bar{G}	P = Q
P = Q	L	L
P > Q	L	H
P < Q	L	H
X	H	H

SN54ALS688, SN54ALS689 ... FH PACKAGE
SN74ALS688, SN74ALS689 ... FN PACKAGE
(TOP VIEW)



logic symbols

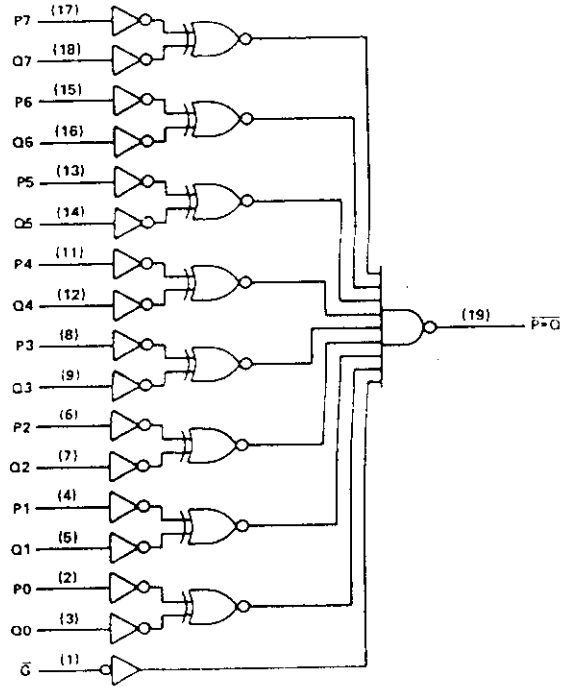


Pin numbers shown are for J and N packages.

2
ALS AND AS CIRCUITS

TYPES SN54ALS688, SN54ALS689, SN74ALS688, SN74ALS689
8-BIT IDENTITY COMPARATORS

logic diagram (positive logic)



Pin numbers shown are for J and N packages

2 ALS AND AS CIRCUITS

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC	7V
Input voltage:	7V
Off-state output voltage: *ALS689	7V
Operating free-air temperature range: SN54ALS688, SN54AS689	-55°C to 125°C
SN74ALS688, SN74AS689	0°C to 70°C
Storage temperature range	65°C to 150°C

TYPES SN54ALS688 SN74ALS688 8-BIT IDENTITY COMPARATORS WITH TOTEM-POLE OUTPUTS

recommended operating conditions

		SN54ALS688			SN74ALS688			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	1.5	5	5.5	2	5	5.5	V
V_{IH}	High-level input voltage	2						V
V_{IL}	Low-level input voltage			0.8				V
I_{OH}	High-level output current			1			1	mA
I_{OL}	Low-level output current			12			12	mA
T_A	Operating free-air temperature	55		125	0		75	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54ALS688			SN74ALS688			UNIT
		MIN	TYP ¹	MAX	MIN	TYP ¹	MAX	
V_{IK}	$V_{CC} = 4.5 \text{ V}$, $I_I = 18 \text{ mA}$			1.5			1.5	V
V_{OH}	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$, $I_{OH} = 0.4 \text{ mA}$	$V_{CC} - 2$			$V_{CC} - 2$			V
	$V_{CC} = 4.5 \text{ V}$, $I_{OH} = 1 \text{ mA}$	2.4	3.3		2.4	3.3		V
V_{OL}	$V_{CC} = 4.5 \text{ V}$, $I_{OL} = 2.5 \text{ mA}$				0.4			V
	$V_{CC} = 4.5 \text{ V}$, $I_{OL} = 12 \text{ mA}$		0.25	0.4		0.25	0.4	V
I_I	$V_{CC} = 5.5 \text{ V}$, $V_I = 7 \text{ V}$			0.1			0.1	mA
I_{IH}	$V_{CC} = 5.5 \text{ V}$, $V_I = 2.7 \text{ V}$			20			20	µA
I_{IL}	$V_{CC} = 5.5 \text{ V}$, $V_I = 0.4 \text{ V}$			0.1			0.1	mA
I_O^1	$V_{CC} = 5.5 \text{ V}$, $V_O = 2.25 \text{ V}$	30		112	30		112	mA
I_{CC}	$V_{CC} = 5.5 \text{ V}$, See Note 1		12	19		12	19	mA

¹All typical values are at $V_{CC} = 5 \text{ V}$, $I_A = 25^\circ\text{C}$.

²The output conditions have been chosen to produce a current that closely approximates one-half of the maximum current capability of the device.

NOTE 1: I_{CC} is measured with G grounded, P and Q at 4.5 V.

switching characteristics (see Note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$, $C_L = 50 \text{ pF}$, $R_L = 500 \Omega$, $T_A = \text{MIN to MAX}$				UNIT
			SN54ALS688		SN74ALS688		
			MIN	MAX	MIN	MAX	
t_{PLH}	P	$\overline{P} - \overline{Q}$	3	16	3	12	ns
t_{PHL}			5	25	5	20	
t_{PLH}	Q	$\overline{P} - \overline{Q}$	3	16	3	12	ns
t_{PHL}			5	25	5	20	
t_{PLH}	\overline{G}	$\overline{P} - \overline{Q}$	3	15	3	12	ns
t_{PHL}			5	25	5	20	

NOTE 2: For load circuit and voltage waveforms, see page 1-12.

TEXAS
INSTRUMENTS

POST OFFICE BOX 225672 • DALLAS, TEXAS 75265

2 489

FAST 74F245 Transceiver

Octal Transceiver (3-state)
Product Specification

Logic Products

FEATURES

- Octal bidirectional bus interface
- 3-State buffer outputs sink 64mA
- 15mA source current
- Outputs are placed in HI-Z state during power-off conditions

DESCRIPTION

The 'F245 is an octal transceiver featuring noninverting 3-state bus compatible outputs in both send and receive directions. The B side outputs are all capable of sinking 64mA and sourcing up to 15mA, producing very good capacitive drive characteristics. The device features an Output Enable (\overline{OE}) input for easy cascading and a Send/Receive (T/R) input for direction control. The 3-state outputs, $B_0 - B_7$, have been designed to prevent output bus loading if the power is removed from the device.

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F245	3.8ns	100mA

ORDERING CODE

PACKAGES	COMMERCIAL RANGE $V_{CC} = 5V \pm 10\%$; $T_A = 0^\circ C$ to $+70^\circ C$
Plastic DIP	N74F245N
Plastic SOL-20	N74F245D

NOTES:

1. SO package is surface-mounted micro-miniature DIP.
2. For information regarding devices processed to Military Specifications, see the Signetics Military Products Data Manual.

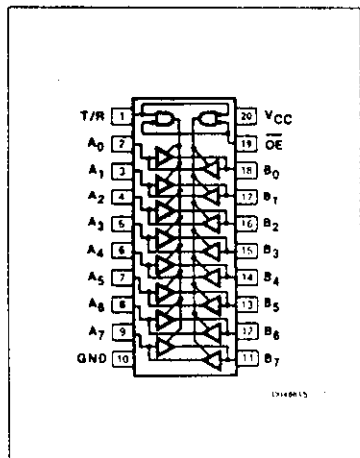
INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

PINS	DESCRIPTION	74F(U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
$A_0 - A_7$	A Port data inputs	3.5/1.0	70 μ A/0.6mA
$B_0 - B_7$	B Port data inputs	3.5/1.0	70 μ A/0.6mA
\overline{OE}	Output enable input (active LOW)	2.0/2.0	40 μ A/1.2mA
T/R	Transmit/Receive input	2.0/2.0	40 μ A/1.2mA
$A_0 - A_7$	A Port data outputs	150/40	3.0mA/24mA
$B_0 - B_7$	B Port data outputs	150/100/7	15mA/64mA

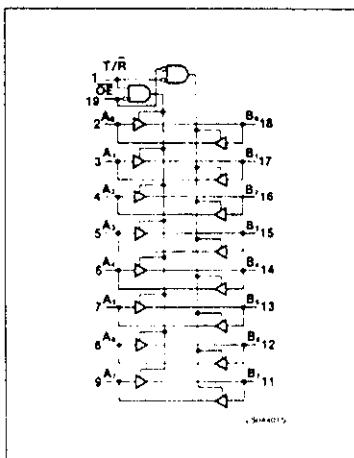
NOTE:

One (1.0) FAST Unit Load is defined as: 20 μ A in the HIGH state and 0.6mA in the LOW state.

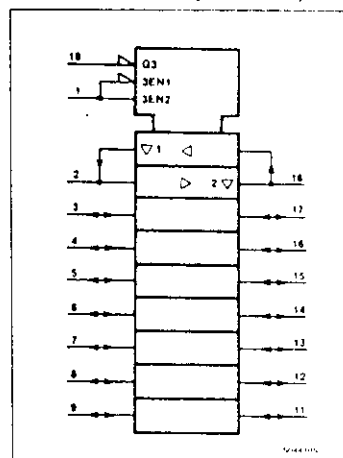
PIN CONFIGURATION



LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)



Transceiver

FAST 74F245

FUNCTION TABLE

INPUTS		INPUTS/OUTPUTS	
OE	S/R	A _n	B _n
L	L	A = B	INPUTS
L	H	INPUT	B = A
H	X	(Z)	(Z)

H = HIGH voltage level
 L = LOW voltage level
 X = Don't care
 (Z) = HIGH impedance "off" state

ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

PARAMETER		74F	UNIT
V _{CC}	Supply voltage	-0.5 to +7.0	V
V _{IN}	Input voltage	-0.5 to +7.0	V
I _{IN}	Input current	-30 to +5	mA
V _{OUT}	Voltage applied to output in HIGH output state	-0.5 to +5.5	V
I _{OUT}	Current applied to output in LOW output state	A ₀ - A ₇	48 mA
		B ₀ - B ₇	128 mA
T _A	Operating free-air temperature range	0 to 70	°C

RECOMMENDED OPERATING CONDITIONS

PARAMETER		74F			UNIT
		Min	Nom	Max	
V _{CC}	Supply voltage	4.5	5.0	5.5	V
V _{IH}	HIGH-level input voltage	2.0			V
V _{IL}	LOW-level input voltage				V
I _{IK}	Input clamp current				mA
I _{OH}	HIGH-level output current	A ₀ - A ₇			mA
		B ₀ - B ₇			mA
I _{OL}	HIGH-level output current	A ₀ - A ₇			mA
		B ₀ - B ₇			mA
T _A	Operating free-air temperature	0			°C

Transceiver

FAST 74F245

DC ELECTRICAL CHARACTERISTICS (Over recommended operating free-air temperature range unless otherwise noted.)

PARAMETER		TEST CONDITIONS ¹			74F245			UNIT
					Min	Typ ²	Max	
V _{OH}	HIGH-level output voltage	A ₀ - A ₇	V _{CC} = MIN, V _{IL} = MAX, V _{IH} = MIN	I _{OH} = -3mA	± 10%V _{CC}	2.4		V
		B ₀ - B ₇			± 5%V _{CC}	2.7	3.4	V
		B ₀ - B ₇		I _{OH} = -15mA	± 10%V _{CC}	2.0		V
					± 5%V _{CC}	2.0		V
V _{OL}	LOW-level output voltage	A ₀ - A ₇	V _{CC} = MIN, V _{IL} = MAX, V _{IH} = MIN	I _{OL} = 48mA	± 10%V _{CC}	.35	.50	V
		B ₀ - B ₇		I _{OL} = 64mA	± 5%V _{CC}	.40	.55	V
V _{IK}	Input clamp voltage	V _{CC} = MIN, I _I = I _{IK}			-0.73	-1.2	V	
I _I	Input current at maximum input voltage	OE, T/R	V _{CC} = MAX, V _I = 7.0V				100	µA
		A ₀ - A ₇ , B ₀ - B ₇	V _{CC} = 5.5V, V _I = 5.5V				1.0	mA
I _{IH}	HIGH-level input current OE and T/R only	V _{CC} = MAX, V _I = 2.7V				40	µA	
I _{IL}	LOW-level input current OE and T/R only	V _{CC} = MAX, V _I = 0.5V			-0.75	-1.2	mA	
I _{OZH} + I _{IH}	Off-state current HIGH-level voltage applied	V _{CC} = MAX, OE = 2.0V, V _I = 2.7V			0	70	µA	
I _{OZL} + I _{IL}	Off-state current LOW-level voltage applied	V _{CC} = MAX, OE = 2.0V, V _I = 0.5V				-600	µA	
I _{OS}	Short-circuit output current ³	A ₀ - A ₇	V _{CC} = MAX			-60	150	mA
		B ₀ - B ₇	V _{CC} = MAX			-100	-225	mA
I _{CC}	Supply current (total)	I _{CC1}	V _{CC} = MAX	V _{IN} = 4.5V		85	114	mA
		I _{CC2}		V _{IN} = GND		100	124	mA
		I _{CC3}		V _{IN} = OE = 4.5V		110	140	mA

NOTES:

- For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
- All typical values are at V_{CC} = 5V, T_A = 25°C.
- Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a HIGH output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

AC ELECTRICAL CHARACTERISTICS (When measured in accordance with the procedures outlined in Signetics LOGIC App Note 202, "Testing and Specifying FAST Logic.")

PARAMETER	TEST CONDITIONS	74F			74F		UNIT	
		T _A = +25°C V _{CC} = +5.0V C _L = 50pF R _L = 500Ω			T _A = 0 to +70°C V _{CC} = +5.0V ± 10% C _L = 50pF R _L = 500Ω			
		Min	Typ	Max	Min	Max		
t _{PLH} t _{PHL}	Propagation delay A _n to B _n or B _n to A _n	Waveform 1	2.5 2.5	3.5 4.0	5.5 6.0	2.5 2.5	6.5 7.0	ns
t _{PZH} t _{PZL}	Output enable time to HIGH and LOW level	Waveform 2 Waveform 3	5.0 3.5	7.0 6.5	8.5 8.0	5.0 3.5	9.5 9.0	ns
t _{PHZ} t _{PLZ}	Output disable time from HIGH and LOW level	Waveform 2 Waveform 3	3.0 2.0	4.5 4.0	6.5 6.0	3.0 2.0	7.5 7.0	ns

NOTE:

Subtract 0.2ns from minimum values for SO package.

Transceiver

FAST 74F245

DC ELECTRICAL CHARACTERISTICS (Over recommended operating free-air temperature range unless otherwise noted.)

PARAMETER		TEST CONDITIONS ¹			74F245			UNIT
					Min	Typ ²	Max	
V _{OH}	HIGH-level output voltage	A ₀ - A ₇	V _{CC} = MIN, V _{IL} = MAX, V _{IH} = MIN	I _{OH} = -3mA	± 10%V _{CC}	2.4		V
		B ₀ - B ₇			± 5%V _{CC}	2.7	3.4	V
		B ₀ - B ₇		I _{OH} = -15mA	± 10%V _{CC}	2.0		V
					± 5%V _{CC}	2.0		V
V _{OL}	LOW-level output voltage	A ₀ - A ₇	V _{CC} = MIN, V _{IL} = MAX, V _{IH} = MIN	I _{OL} = 48mA	± 10%V _{CC}	.35	.50	V
		B ₀ - B ₇		I _{OL} = 64mA	± 5%V _{CC}	.40	.55	V
V _{IK}	Input clamp voltage	V _{CC} = MIN, I _I = I _{IK}				-0.73	-1.2	V
I _I	Input current at maximum input voltage	OE, T/ \bar{R}	V _{CC} = MAX, V _I = 7.0V				100	μA
		A ₀ - A ₇ , B ₀ - B ₇	V _{CC} = 5.5V, V _I = 5.5V				1.0	mA
I _{IH}	HIGH-level input current OE and T/ \bar{R} only	V _{CC} = MAX, V _I = 2.7V				40	μA	
I _{IL}	LOW-level input current OE and T/ \bar{R} only	V _{CC} = MAX, V _I = 0.5V				-0.75	-1.2	mA
I _{OZH} + I _{IH}	Off-state current HIGH-level voltage applied	V _{CC} = MAX, OE = 2.0V, V _I = 2.7V				0	70	μA
I _{OZL} + I _{IL}	Off-state current LOW-level voltage applied	V _{CC} = MAX, OE = 2.0V, V _I = 0.5V					-600	μA
I _{OS}	Short-circuit output current ³	A ₀ - A ₇	V _{CC} = MAX			-60	150	mA
		B ₀ - B ₇				-100	-225	mA
I _{CC}	Supply current (total)	I _{CC1}	V _{CC} = MAX	V _{IH} = 4.5V		85	114	mA
		I _{CC1}		V _{IH} = GND		100	125	mA
		I _{CC2}		V _{IH} = OE = 4.5V		110	140	mA

NOTES:

- For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
- All typical values are at V_{CC} = 5V, T_A = 25°C.
- Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a HIGH output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

AC ELECTRICAL CHARACTERISTICS (When measured in accordance with the procedures outlined in Sigmetics LOGIC App Note 202, "Testing and Specifying FAST Logic.")

PARAMETER	TEST CONDITIONS	74F			74F		UNIT
		T _A = +25°C V _{CC} = +5.0V C _L = 50pF R _L = 500Ω			T _A = 0 to +70°C V _{CC} = +5.0V ± 10% C _L = 50pF R _L = 500Ω		
		Min	Typ	Max	Min	Max	
t _{PLH}	Propagation delay	2.5	3.5	5.5	2.5	6.5	ns
t _{PHL}	A _n to B _n or B _n to A _n	2.5	4.0	6.0	2.5	7.0	
t _{PZH}	Output enable time to HIGH and LOW level	5.0	7.0	8.5	5.0	9.5	ns
t _{PZL}		3.5	6.5	8.0	3.5	9.0	
t _{PHZ}	Output disable time from HIGH and LOW level	3.0	4.5	6.5	3.0	7.5	ns
t _{PLZ}		2.0	4.0	6.0	2.0	7.0	

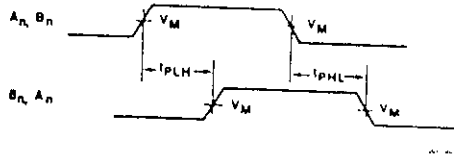
NOTE:

Subtract 0.2ns from minimum values for SO package.

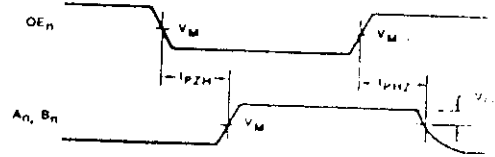
Transceiver

FAST 74F

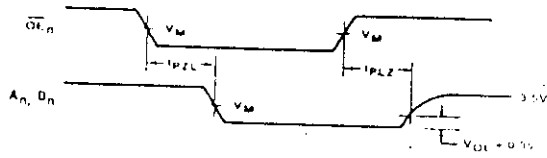
AC WAVEFORMS



Waveform 1. Propagation Delay Data To Output



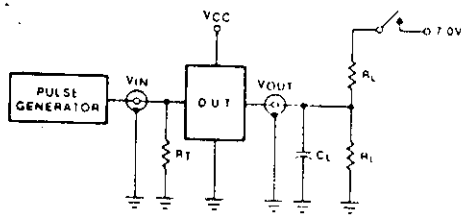
Waveform 2. 3-State Output Enable Time To HIGH Level And Output Disable Time From HIGH Level



Waveform 3. 3-State Output Enable Time To LOW Level And Output Disable Time From LOW Level

NOTE: For all waveforms, $V_M = 1.5V$

TEST CIRCUIT AND WAVEFORMS



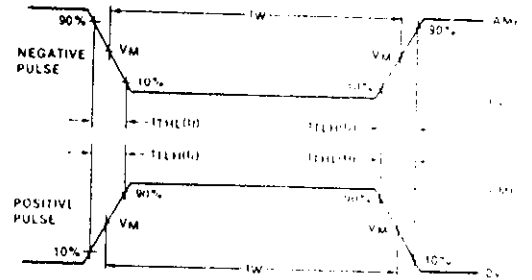
Test Circuit for 3-State Outputs

SWITCH POSITION

TEST	SWITCH
t_{PLZ}	closed
t_{PLH}	closed
All other	open

DEFINITIONS

R_L = Load resistor; see AC CHARACTERISTICS for value.
 C_L = Load capacitance includes jig and probe capacitance; see AC CHARACTERISTICS for value.
 R_T = Termination resistance should be equal to Z_{OUT} of pulse generators.



$V_M = 1.5V$
Input Pulse Definition

FAMILY	INPUT PULSE REQUIREMENTS				
	Amplitude	Rep. Rate	Pulse Width	t_r	t_f
74F	3.0V	1MHz	500ns	2.5ns	2.5ns

Signetics

FAST 74F00 Gate

Quad Two-Input NAND Gate
Product Specification

Logic Products

FUNCTION TABLE

INPUTS		OUTPUT
A	B	\bar{Y}
L	L	H
L	H	H
H	L	H
H	H	L

H = HIGH voltage level
L = LOW voltage level

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F00	3.4ns	4.4mA

ORDERING CODE

PACKAGES	COMMERCIAL RANGE $V_{CC} = 5V \pm 10\%$; $T_A = 0^\circ C$ to $+70^\circ C$
Plastic DIP	N74F00N
Plastic SO-14	N74F00D

NOTES:

- SO package is surface-mounted micro-miniature DIP.
- For information regarding devices processed to Military Specifications, see the Signetics Military Products Data Manual.

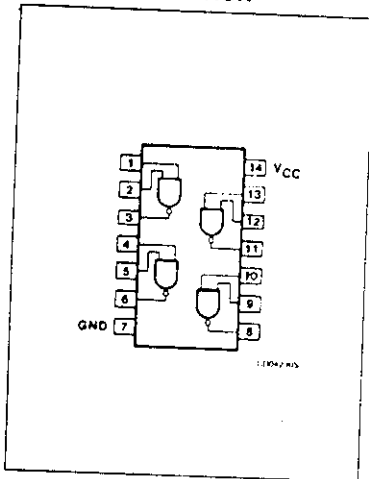
INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

PINS	DESCRIPTION	74F(U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
A, B	Inputs	1.0/1.0	20 μ A/0.6mA
\bar{Y}	Output	50/33	1.0mA/20mA

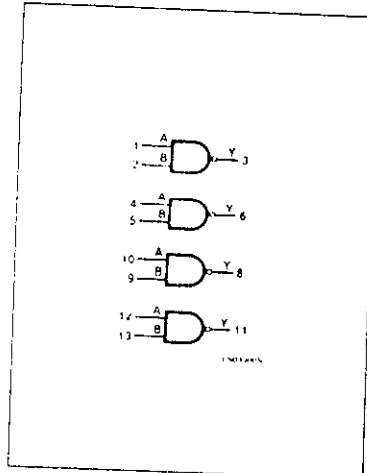
NOTE:

One (1.0) FAST Unit Load is defined as: 20 μ A in the HIGH state and 0.6mA in the LOW state.

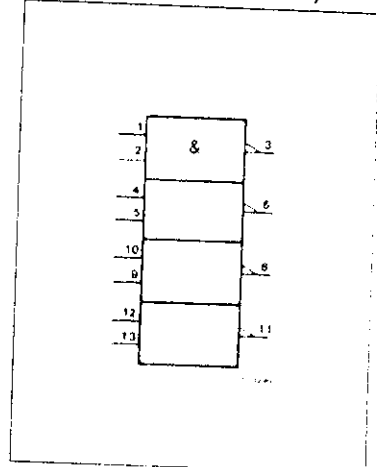
PIN CONFIGURATION



LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)



August 26, 1985

Gate

FAST 74F00

ABSOLUTE MAXIMUM RATINGS (Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

PARAMETER	74F	UNIT
V_{IN} Input voltage	-0.5 to +7.0	V
I_{IN} Input current	-30 to +5	mA
V_{OUT} Voltage applied to output in HIGH output state	-0.5 to + V_{CC}	V
I_{OUT} Current applied to output in LOW output state	40	mA
T_A Operating free-air temperature range	0 to 70	°C

RECOMMENDED OPERATING CONDITIONS

PARAMETER	74F			UNIT
	Min	Nom	Max	
V_{CC} Supply voltage	4.5	5.0	5.5	V
V_{IH} HIGH-level input voltage	2.0			V
V_{IL} LOW-level input voltage			0.8	V
I_{IK} Input clamp current			-18	mA
I_{OH} HIGH-level output current			-1	mA
I_{OL} LOW-level output current			20	mA
T_A Operating free-air temperature	0		70	°C

DC ELECTRICAL CHARACTERISTICS (Over recommended operating free-air temperature range unless otherwise noted.)

PARAMETER	TEST CONDITIONS ¹	74F00			UNIT		
		Min	Typ ²	Max			
V_{OH} HIGH-level output voltage	V_{IL} = MIN, V_{IH} = MAX, I_{OH} = MAX	+10% V_{CC}	2.5		V		
V_{OL} LOW-level output voltage	V_{IL} = MIN, V_{IH} = MAX, I_{OL} = MAX	+5% V_{CC}	2.7	0.4	V		
V_{IK} Input clamp voltage	V_{CC} = MIN, I_I = I_{IK}	+10% V_{CC}		35	V		
I_I Input current at maximum input voltage	V_{CC} = MAX, V_I = 7.0V	+5% V_{CC}		35	V		
I_{IH} HIGH-level input current	V_{CC} = MAX, V_I = 2.7V			-0.73	-1.2	µA	
I_{IL} LOW-level input current	V_{CC} = MAX, V_I = 0.5V			1	100	µA	
I_{OS} Short-circuit output current ³	V_{CC} = MAX, V_O = 0.0V			20	20	µA	
I_{CC} Supply current (total)	V_{CC} = MAX	V_{IN} = GND		-0.4	-0.6	mA	
			I_{CCH}	-60	-60	-150	mA
			I_{CCL}	1.9	2.8	8.8	10.2
		V_{IN} = 4.5V					

NOTES:

- For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the appropriate type.
- All typical values are at V_{CC} = 5V, T_A = 25°C.
- Not more than one output should be shorted at a time. For testing I_{OS} , the use of high speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a HIGH output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

Gate

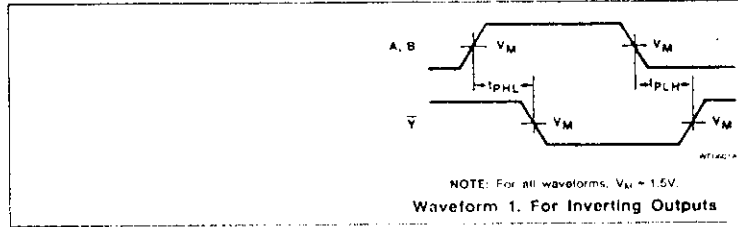
FAST 74F00

AC ELECTRICAL CHARACTERISTICS (When measured in accordance with the procedures outlined in Signetics LOGIC App Note 202 "Testing and Specifying FAST Logic")

PARAMETER	TEST CONDITIONS	74F00						UNIT
		T _A = +25°C V _{CC} = +5.0V C _L = 50pF R _L = 500Ω			T _A = 0°C to +70°C V _{CC} = +5.0V ± 10% C _L = 50pF R _L = 500Ω			
		Min	Typ	Max	Min	Max		
t _{PLH} t _{PHL}	Propagation delay A, B to \bar{Y}	Waveform 1	2.4 2.0	3.7 3.2	5.0 4.3	2.4 2.0	6.0 5.3	ns

NOTE:
Subtract 0.2ns from minimum values for SO package

AC WAVEFORM



TEST CIRCUIT AND WAVEFORMS

Test Circuit For Totem-Pole Outputs

DEFINITIONS
 R_L - Load resistor, see AC CHARACTERISTICS for value.
 C_L - Load capacitance includes jig and probe capacitance, see AC CHARACTERISTICS for value.
 R_T - Termination resistance should be equal to Z_{out} of pulse generators.

Input Pulse Definition

FAMILY	INPUT PULSE REQUIREMENTS				
	Amplitude	Rep. Rate	Pulse Width	t _{rise}	t _{fall}
74F	3.0V	1MHz	500ns	2.5ns	2.5ns

Signetics

FAST 74F08 Gate

Quad Two-Input AND Gate
Product Specification

Logic Products

FUNCTION TABLE

INPUTS		OUTPUT
A	B	Y
L	L	L
L	H	L
H	L	L
H	H	H

H = HIGH voltage level
L = LOW voltage level

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F08	4.1ns	7.1mA

ORDERING CODE

PACKAGES	COMMERCIAL RANGE $V_{CC} = 5V \pm 10\%$; $T_A = 0^\circ C$ to $+70^\circ C$
Plastic DIP	N74F08N
Plastic SO-14	N74F08D

NOTES:

- SO package is surface-mounted micro-miniature DIP.
- For information regarding devices processed to Military Specifications, see the Signetics Military Products Data Manual.

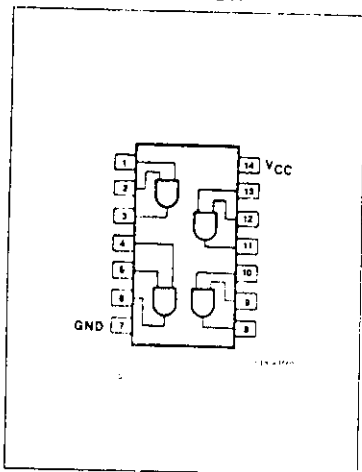
INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

PINS	DESCRIPTION	74F(U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
A, B	Inputs	1.0/1.0	20 μ A/0.6mA
Y	Outputs	50/33	1.0mA/20mA

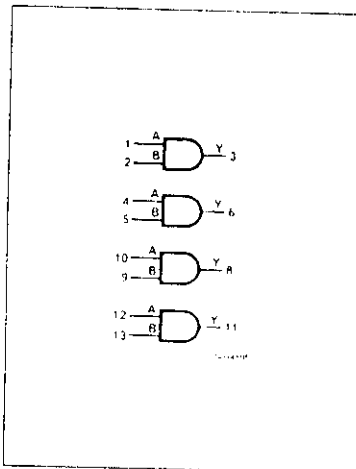
NOTE:

One (1.0) FAST Unit Load (U.L.) is defined as: 20 μ A in the HIGH state and 0.6mA in the LOW state.

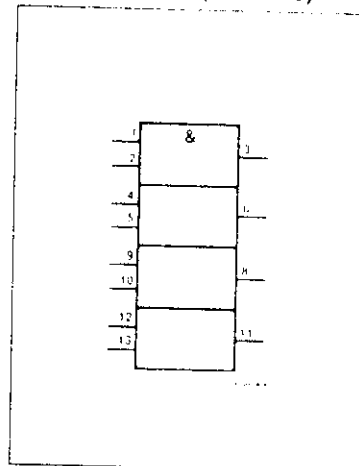
PIN CONFIGURATION



LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)



Gate

FAST 74F08

ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted, these limits are over the operating free-air temperature range.)

PARAMETER		74F	UNIT
V _{CC}	Supply voltage	0.5 to 7.0	V
V _{IN}	Input voltage	-0.5 to 7.0	V
I _{IN}	Input current	-30 to +5	mA
V _{OUT}	Voltage applied to output in HIGH output state	-0.5 to +V _{CC}	V
I _{OUT}	Current applied to output in LOW output state	-60 to +15	mA
T _A	Operating free-air temperature range	0 to 70	°C

RECOMMENDED OPERATING CONDITIONS

PARAMETER	74F			UNIT
	Min	Nom	Max	
V _{CC}	4.5	5.0	5.5	V
V _{IH}	2.0			V
V _{IL}			0.8	V
I _{IK}			-10	mA
I _{OH}			1	mA
I _{OL}			20	mA
T _A	0		70	°C

DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise specified.)

PARAMETER	TEST CONDITIONS ¹	74F08			UNIT	
		Min	Typ ²	Max		
V _{OH}	HIGH-level output voltage V _{CC} = MIN, V _{IL} = MAX, I _{OH} = MAX + 10%V _{CC}	2.4			V	
V _{OL}	LOW-level output voltage V _{CC} = MIN, V _{IL} = MAX, I _{OL} = MAX + 10%V _{CC}	0.2	0.3	0.4	V	
V _{IK}	Input clamp voltage V _{CC} = MIN, I _I = I _{IK} + 5%V _{CC}	-3.5		-5.0	V	
I _I	Input current at maximum input voltage V _{CC} = MAX, V _I = 7.0V	-0.73		-1.2	mA	
I _{IH}	HIGH-level input current V _{CC} = MAX, V _I = 2.7V	5		10	µA	
I _{IL}	LOW-level input current V _{CC} = MAX, V _I = 0.5V	-		20	µA	
I _{OS}	Short-circuit output current ³ V _{CC} = MAX, V _O = 0.0V	-60		15	mA	
I _{CC}	Supply current (total) V _{CC} = MAX	I _{CC} H	V _{IN} = 4.5V	5.5	10	mA
		I _{CC} L	V _{IN} = GND	8.6	12	mA

NOTES:

- For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the appropriate type.
- All typical values are at V_{CC} = 5V, T_A = 25°C.
- Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a HIGH output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, the tests should be performed in the order listed.

Gate

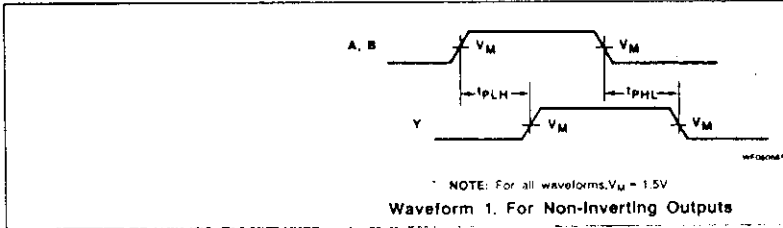
FAST 74F08

AC CHARACTERISTICS

PARAMETER	TEST CONDITIONS	74F08					UNIT	
		T _A = +25°C V _{CC} = +5.0V C _L = 50pF R _L = 500Ω			T _A = 0°C to +70°C V _{CC} = +5.0V ± 10% C _L = 50pF R _L = 500Ω			
		Min	Typ	Max	Min	Max		
t _{PLH} t _{PHL}	Propagation delay A, B to Y	Waveform 1	3.0 2.5	4.2 4.0	5.6 5.3	3.0 2.5	6.6 6.3	ns

NOTE:
Subtract 0.2ns from minimum values for SO package

AC WAVEFORM



TEST CIRCUIT AND WAVEFORMS

Test Circuit For Totem-Pole Outputs

DEFINITIONS
 R_L = Load resistor; see AC CHARACTERISTICS for value.
 C_L = Load capacitance includes jig and probe capacitance; see AC CHARACTERISTICS for value.
 R_T = Termination resistance should be equal to Z_{OUT} of pulse generators.

Input Pulse Definition

V_M = 1.5V

FAMILY	INPUT PULSE REQUIREMENTS				
	Amplitude	Rep. Rate	Pulse Width	t _{PLH}	t _{PHL}
74F	3.0V	1MHz	500ns	2.5ns	2.5ns

Signetics

Logic Products

FEATURES

- 8-bit transparent latch - 'F373
- 8-bit positive, edge-triggered register - 'F374
- 3-State output buffers
- Common 3-State output enable
- Independent register and 3-state buffer operation

DESCRIPTION

The 'F373 is an octal transparent latch coupled to eight 3-State output buffers. The two sections of the device are controlled independently by Enable (E) and Output Enable (\overline{OE}) control gates.

The data on the D inputs are transferred to the latch outputs when the Latch Enable (E) input is HIGH. The latch remains transparent to the data inputs while E is HIGH, and stores the data that is present one set-up time before the HIGH-to-LOW enable transition.

The 3-State output buffers are designed to drive heavily loaded 3-State buses, MOS memories, or MOS microprocessors. The active LOW Output Enable (\overline{OE}) controls all eight 3-State buffers independent of the latch operation.

FAST 74F373, 74F374

Latches/Flip-Flops

'F373 Octal Transparent Latch (3-State)
'F374 Octal D Flip-Flop (3-State)
Product Specification

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F373	4.5ns	35mA
74F374	6.5ns	55mA

ORDERING CODE

PACKAGES	COMMERCIAL RANGE $V_{CC} = 5V \pm 10\%$; $T_A = 0^\circ C$ to $+70^\circ C$
Plastic DIP	N74F373N, N74F374N
Plastic SOL-20	N74F373D, N74F374D

NOTES:

1. SO package is surface-mounted micro-miniature DIP.
2. For information regarding devices processed to Military Specifications, see the Signetics Military Products Data Manual.

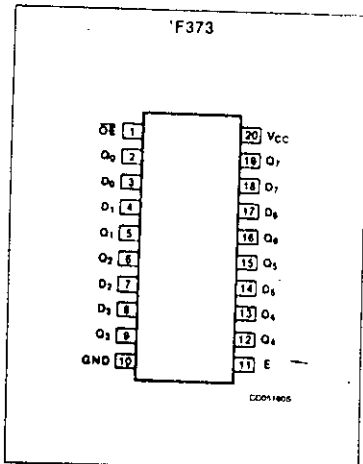
INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

PINS	DESCRIPTION	74F(U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
$D_0 - D_7$	Data inputs	1.0/1.0	$20\mu A/0.6mA$
E ('F373)	Latch enable input (active HIGH)	1.0/1.0	$20\mu A/0.6mA$
\overline{OE}	Output enable input (active LOW)	1.0/1.0	$20\mu A/0.6mA$
CP ('F374)	Clock pulse input (active rising edge)	1.0/1.0	$20\mu A/0.6mA$
$Q_0 - Q_7$	3-State outputs	150/10	$3mA/24mA$

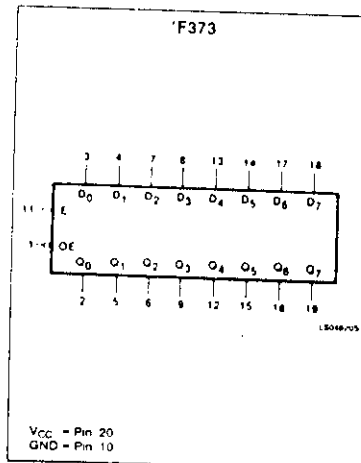
NOTE:

One (1) FAST Unit Load is defined as: $20\mu A$ in the HIGH state and $0.6mA$ in the LOW state.

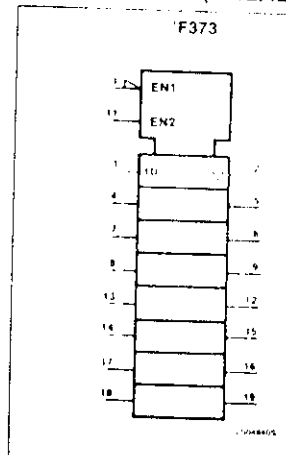
PIN CONFIGURATION



LOGIC SYMBOL



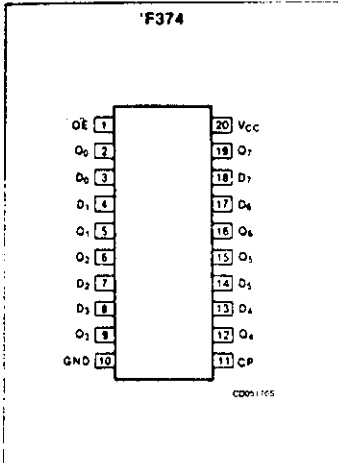
LOGIC SYMBOL (IEEE/IEC)



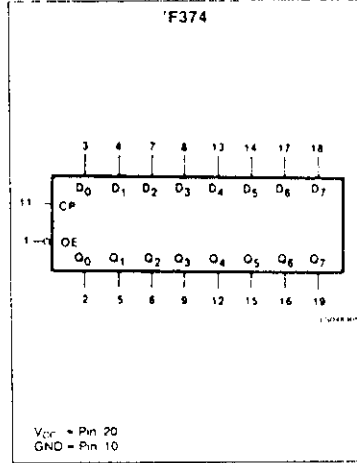
Latches/Flip-Flops

FAST 74F373, 74F374

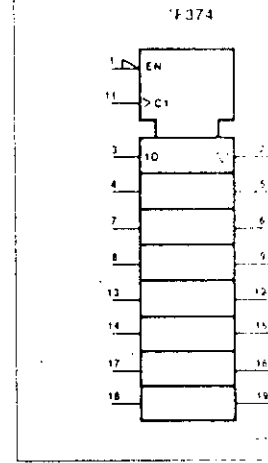
PIN CONFIGURATION



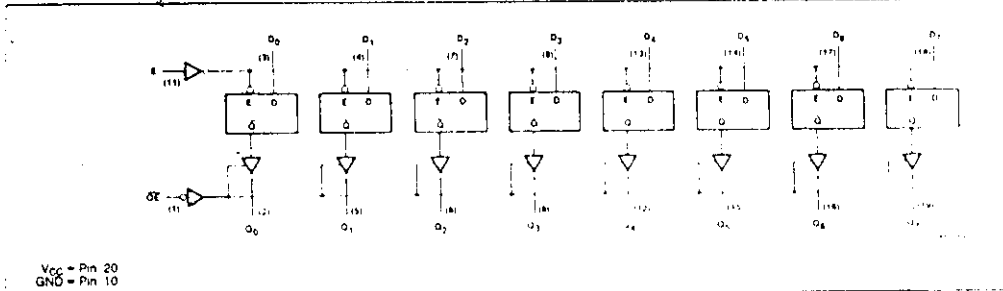
LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)

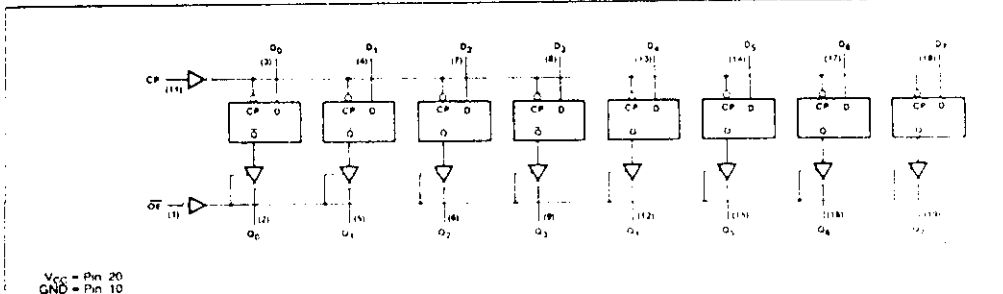


LOGIC DIAGRAM, 'F373



6

LOGIC DIAGRAM, 'F374



When \overline{OE} is LOW, the latched or transparent data appears at the outputs. When \overline{OE} is HIGH, the outputs are in the HIGH impedance "off" state, which means they will neither drive nor load the bus.

The 'F374 is an 8-bit, edge-triggered register coupled to eight 3-State output buffers. The two sections of the device are controlled

independently by the Clock (CP) and Output Enable (\overline{OE}) control gates. The register is fully edge triggered. The state of each D input, one set-up time before the LOW-to-HIGH clock transition, is transferred to the corresponding flip-flop's Q output.

The 3-State output buffers are designed to drive heavily loaded 3-State buses, MOS

memories, or MOS microprocessors. The active LOW Output Enable (\overline{OE}) controls all eight 3-State buffers independently of the register operation. When \overline{OE} is LOW, transparent data appears at the outputs. When \overline{OE} is HIGH, the outputs are in the HIGH impedance "off" state, which means they will neither drive nor load the bus.

Latches/Flip-Flops

FAST 74F373, 74F374

MODE SELECT — FUNCTION TABLE, 'F373

OPERATING MODES	INPUTS			INTERNAL REGISTER	OUTPUTS Q ₀ - Q ₇
	OE	E	D _n		
Enable and read register	L	H	X	L	L
	L	H	X	H	H
Latch and read register	L	L	l	L	L
	L	L	h	H	H
Latch register and disable outputs	H	X	X	X	(Z)
	H	X	X	X	(Z)

MODE SELECT — FUNCTION TABLE, 'F374

OPERATING MODES	INPUTS			INTERNAL REGISTER	OUTPUTS Q ₀ - Q ₇
	OE	CP	D _n		
Load and read register	L	↑	l	L	L
	L	↑	h	H	H
Load register and disable outputs	H	X	X	X	(Z)
	H	X	X	X	(Z)

H = HIGH voltage level
 h = HIGH voltage level one set-up time prior to the LOW-to-HIGH clock transition or HIGH-to-LOW E transition
 L = LOW voltage level
 X = Don't care
 l = LOW voltage level one set-up time prior to the LOW-to-HIGH clock transition or HIGH-to-LOW E transition
 (Z) = HIGH impedance "off" state
 ↑ = LOW-to-HIGH clock transition

ABSOLUTE MAXIMUM RATINGS (Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

PARAMETER		74F	UNIT
V _{CC}	Supply voltage	-0.5 to +7.0	V
V _{IN}	Input voltage	-0.5 to +7.0	V
I _{IN}	Input current	-30 to +5	mA
V _{OUT}	Voltage applied to output in HIGH output state	-0.5 to +5.5	V
I _{OUT}	Current applied to output in LOW output state	40	mA
T _A	Operating free-air temperature range	0 to 70	°C

RECOMMENDED OPERATING CONDITIONS

PARAMETER	74F			UNIT	
	Min	Nom	Max		
V _{CC}	Supply voltage	4.5	5.0	5.5	V
V _{IH}	HIGH-level input voltage	2.0			V
V _{IL}	LOW-level input voltage			0.8	V
I _{IK}	Input clamp current			-18	mA
I _{OH}	HIGH-level output current			-1	mA
I _{OL}	LOW-level output current			20	mA
T _A	Operating free-air temperature	0		70	°C

Latches/Flip-Flops

FAST 74F373, 74F374

DC ELECTRICAL CHARACTERISTICS (Over recommended operating free-air temperature range unless otherwise specified)

PARAMETER	TEST CONDITIONS ¹	74F373, 74F374			UNIT
		Min	Typ ²	Max	
V _{OH} HIGH-level output voltage	V _{CC} = MIN, V _{IL} = MAX, I _{OH} = MAX V _{IH} = MIN	± 10% V _{CC}	2.4	2.7	V
V _{OL} LOW-level output voltage	V _{CC} = MIN, V _{IH} = MAX, I _{OL} = MAX V _{IL} = MIN	± 10% V _{CC} ± 5% V _{CC}	0.35	0.5	V
V _{IK} Input clamp voltage	V _{CC} = MIN, I _I = I _{IK}		-0.70	-1.0	V
I _I Input current at maximum input voltage	V _{CC} = MAX, V _I = 7.0V			100	μA
I _{IH} HIGH-level input current	V _{CC} = MAX, V _I = 2.7V			20	μA
I _{IL} LOW-level input current	V _{CC} = MAX, V _I = 0.5V			-20	μA
I _{OZH} Off-state output current, HIGH-level voltage applied	V _{CC} = MAX, V _{IH} = MIN, V _O = 2.4V			50	μA
I _{OZL} Off-state output current, LOW-level voltage applied	V _{CC} = MAX, V _{IH} = MIN, V _O = 0.5V			-50	μA
I _{OS} Short-circuit output current ³	V _{CC} = MAX, V _O = 0.0V		-60	-150	mA
I _{CC} Supply current (total)	'F373	V _{CC} = MAX	I _{CCZ} OE = 4.5V D inputs = E = GND	30	mA
	'F374		I _{CCZ} CP = OE = 4.5V D inputs = GND	50	mA

NOTES:

- For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable pin.
- All typical values are at V_{CC} = 5V, T_A = 25°C.
- Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold test equipment is preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a HIGH output may result in the temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

Latches/Flip-Flops

FAST 74F373, 74F374

AC ELECTRICAL CHARACTERISTICS (When measured in accordance with the procedures outlined in Signetics Logic App Note 202, "Testing and Specifying FAST Logic.")

PARAMETER	TEST CONDITIONS	74F373, 'F374					UNIT
		T _A = +25°C V _{CC} = +5.0V C _L = 50pF R _L = 500Ω			T _A = 0°C to +70°C V _{CC} = +5.0V ± 10% C _L = 50pF R _L = 500Ω		
		Min	Typ	Max	Min	Max	
f _{MAX} Maximum clock frequency	'F374 Waveform 8	100			70	ns	
t _{PLH} Propagation delay E to Q _n	'F373 Waveform 1	3.0	9.0	11.5	5.0	13.0	
t _{PHL} Propagation delay D _n to Q _n	'F373 Waveform 4	3.0	5.3	7.0	3.0	7.0	
t _{PLH} Propagation delay CP to Q _n	'F374 Waveform 6	4.0	6.5	8.5	4.0	10.0	
t _{PZH} Output enable time to HIGH level	'F373 Waveform 2	2.0	5.0	11.0	2.0	12.0	
t _{PZL} Output enable time to LOW level	'F374 Waveform 3	2.0	5.6	7.5	2.0	8.5	
t _{PHZ} Output disable time from HIGH level	'F373 Waveform 2	2.0	4.5	6.5	2.0	7.5	
t _{PLZ} Output disable time from LOW level	'F374 Waveform 3	2.0	3.8	5.0	2.0	6.0	

AC SET-UP REQUIREMENTS

PARAMETER	TEST CONDITIONS	74F373, 'F374					UNIT
		T _A = +25°C V _{CC} = +5.0V C _L = 50pF R _L = 500Ω			T _A = 0°C to +70°C V _{CC} = +5.0V ± 10% C _L = 50pF R _L = 500Ω		
		Min	Typ	Max	Min	Max	
t _s (H) Set-up time, HIGH or LOW t _s (L) D _n to E	'F373 Waveform 5	2.0			2.0	ns	
t _h (H) Hold time, HIGH or LOW t _h (L) D _n to E	'F373 Waveform 5	3.0			3.0	ns	
t _w (H) Clock pulse width t _w (L)	'F374 Waveform 6	7.0			7.0	ns	
t _s (H) Set-up time, HIGH or LOW t _s (L) D _n to CP	'F374 Waveform 7	2.0			2.0	ns	
t _h (H) Hold time, HIGH or LOW t _h (L) D _n to CP	'F374 Waveform 7	2.0			2.0	ns	
t _w (H) Latch enable pulse width	'F373 Waveform 1	6.0			6.0	ns	

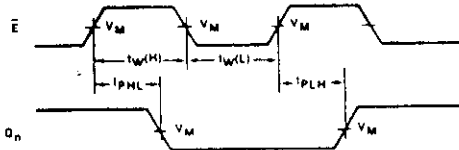
NOTE:

Subtract 0.2ns from minimum values for SO package

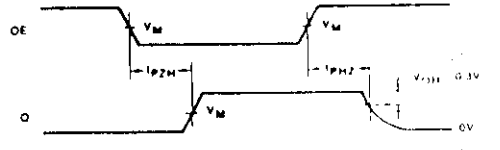
Latches/Flip-Flops

FAST 74F373, 74F374

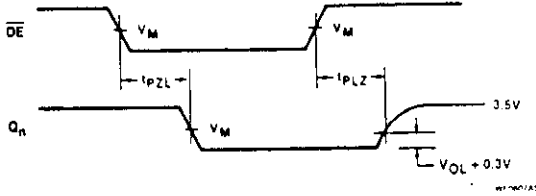
AC WAVEFORMS



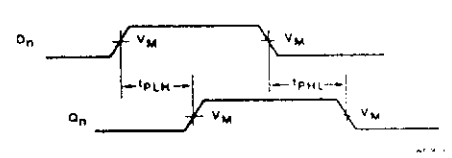
Waveform 1. Latch Enable to Output Delays and Latch Enable Pulse Width



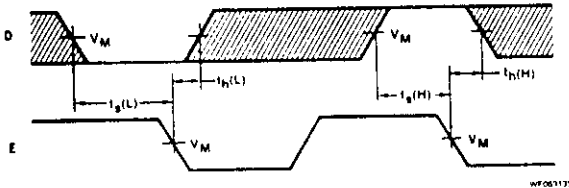
Waveform 2. 3-State Output Enable Time to HIGH Level and Output Disable Time from HIGH Level



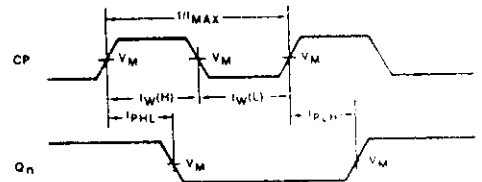
Waveform 3. 3-State Output Enable Time to LOW Level and Output Disable Time from LOW Level



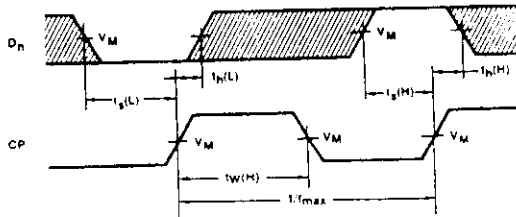
Waveform 4. Propagation Delay Data to Q Outputs



Waveform 5. Data Set-up and Hold Times



Waveform 6. Clock to Output Delays and Pulse Width



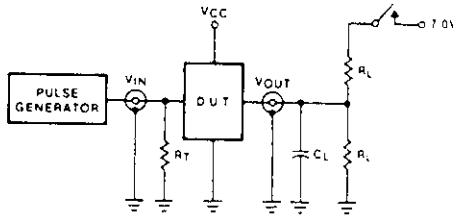
Waveform 7. Data Set-up and Hold Times

NOTE: For all waveforms, $V_M = 1.5V$.
The shaded areas indicate when the input is permitted to change for predictable output performance.

Latches/Flip-Flops

FAST 74F373, 74F377

TEST CIRCUIT AND WAVEFORMS



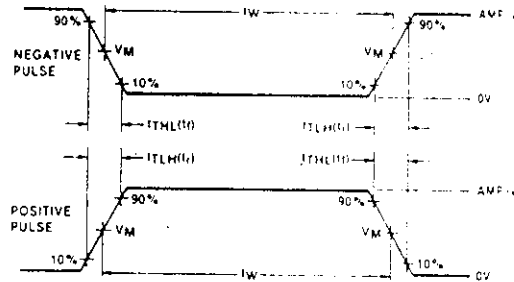
Test Circuit For 3-State Outputs

SWITCH POSITION

TEST	SWITCH
t_{PLZ}	closed
t_{PZL}	closed
All other	open

DEFINITIONS

R_L = Load resistor; see AC CHARACTERISTICS for value
 C_L = Load capacitance includes jig and probe capacitance; see AC CHARACTERISTICS for value.
 R_T = Termination resistance should be equal to Z_{OUT} of pulse generators.



$V_M = 1.5V$
Input Pulse Definition

FAMILY	INPUT PULSE REQUIREMENTS				
	Amplitude	Rep. Rate	Pulse Width	t_{PLH}	t_{PLL}
74F	3.0V	1MHz	500ns	2.5ns	2.5ns

"CI", "SRAM2KXB", "U1505", "CI.MEM", "2KX8EB", " - ", 1.8, 7.6
 "CI", "SRAM2KXB", "U1605", "CI.MEM", "2KX8EB", " - ", 1.4, 7.6
 "CI", "SRAM2KXB", "SRAM2KXB", "CI.MEM", "2KX8EB", " - ", 4.85, 9.25
 "CI", "SRAM2KXB", "SRAM2KXB", "CI.MEM", "2KX8EB", " - ", 4.4, 9.25
 "CI", "SRAM2KXB", "U0302", "CI.MEM", "2KX8EB", " - ", 8, 11.5
 "CI", "SRAM2KXB", "U0402", "CI.MEM", "2KX8EB", " - ", 7.6, 11.5
 "CI", "SRAM2KXB", "U0502", "CI.MEM", "2KX8EB", " - ", 6.7, 11.5
 "CI", "SRAM2KXB", "U0602", "CI.MEM", "2KX8EB", " - ", 6.3, 11.5
 "CI", "SRAM2KXB", "U1302", "CI.MEM", "2KX8EB", " - ", 3, 11.5
 "CI", "SRAM2KXB", "U1402", "CI.MEM", "2KX8EB", " - ", 2, 11.5
 "CI", "SRAM2KXB", "U1502", "CI.MEM", "2KX8EB", " - ", 1.8, 11.5
 "CI", "SRAM2KXB", "U1602", "CI.MEM", "2KX8EB", " - ", 1.3, 11.5
 "CI", "SRAM2KXB", "U0901", "CI.MEM", "2KX8EB", " - ", 5.2, 12.6
 "CI", "SRAM2KXB", "U1001", "CI.MEM", "2KX8EB", " - ", 4.8, 12.6
 "CI", "SRAM2KXB", "U0305", "CI.MEM", "2KX8EB", " - ", 8, 7.6
 "CI", "SRAM2KXB", "U0405", "CI.MEM", "2KX8EB", " - ", 7.6, 7.6
 "CI", "SRAM2KXB", "U0505", "CI.MEM", "2KX8EB", " - ", 6.7, 7.6
 "CI", "SRAM2KXB", "U0605", "CI.MEM", "2KX8EB", " - ", 6.3, 7.6
 "L4", "AC299", "U0105", "IC.LOGIQ", "74AC299", " - ", 8.8, 7.6
 "L4", "AC299", "U0205", "IC.LOGIQ", "74AC299", " - ", 8.4, 7.6
 "L1", "AC14", "U1805", "IC.LOGIQ", "74AC14", " - ", .35, 7.4
 "LA", "LARIOP", "U0705", "LARA.ACTIV", "30NS", " 5% ", 5.9, 7.4

"C2", "ACT374", "U1406", "CI.LOGIQUE", "74ACT374", " - ", 2.5, 9.4
"C2", "ACT374", "U1506", "CI.LOGIQUE", "74ACT374", " - ", 1.8, 9.4
"C2", "ACT374", "U1606", "CI.LOGIQUE", "74ACT374", " - ", 1.3, 9.4
"R6", "RESISTOR", "R214", "RESISTOR", "200 O", " 5% ", .4, 6.6
"R4", "RESISTOR", "R212", "RESISTOR", "10 K", " 5% ", .3, 6.6
"D2", "DIODE", "D200", "DIODE", "1N4148", " - ", .2, 6.6
"R3", "RESISTOR", "R603", "RESISTOR", "22H", " 5% ", 3.6, 8.25
"R3", "RESISTOR", "R602", "RESISTOR", "22H", " 5% ", 3.6, 8.15
"R3", "RESISTOR", "R612", "RESISTOR", "22H", " 5% ", 3.6, 8.05
"R3", "RESISTOR", "R611", "RESISTOR", "22H", " 5% ", 3.6, 7.95
"R3", "RESISTOR", "R605", "RESISTOR", "22H", " 5% ", 3.6, 7.85
"R3", "RESISTOR", "R604", "RESISTOR", "22H", " 5% ", 3.6, 7.75
"R3", "RESISTOR", "R601", "RESISTOR", "22H", " 5% ", 3.6, 7.65
"R3", "RESISTOR", "R600", "RESISTOR", "22H", " 5% ", 3.6, 7.55
"R3", "RESISTOR", "R609", "RESISTOR", "22H", " 5% ", 3.6, 7.45
"R3", "RESISTOR", "R607", "RESISTOR", "22H", " 5% ", 3.6, 7.35
"R3", "RESISTOR", "R236", "RESISTOR", "22H", " 5% ", 3.6, 7.25
"R3", "RESISTOR", "R235", "RESISTOR", "22H", " 5% ", 3.6, 7.15
"R3", "RESISTOR", "R233", "RESISTOR", "22H", " 5% ", 5.8, 8.35
"R3", "RESISTOR", "R234", "RESISTOR", "22H", " 5% ", 5.8, 8.25
"R3", "RESISTOR", "R237", "RESISTOR", "22H", " 5% ", 5.8, 8.15
"R3", "RESISTOR", "R226", "RESISTOR", "22H", " 5% ", 5.8, 8.05
"R8", "RESISTOR", "R228", "RESISTOR", "120H", " 5% ", .5, 8.3
"R8", "RESISTOR", "R227", "RESISTOR", "120H", " 5% ", .4, 8.3
"R7", "RESISTOR", "R213", "RESISTOR", "1M", " 5% ", .3, 8.3
"R3", "RESISTOR", "R229", "RESISTOR", "22H", " 5% ", 5.3, 9.1
"R3", "RESISTOR", "R230", "RESISTOR", "22H", " 5% ", 5.2, 9.1
"R3", "RESISTOR", "R231", "RESISTOR", "22H", " 5% ", 4.1, 9.1
"R3", "RESISTOR", "R232", "RESISTOR", "22H", " 5% ", 4, 9.1
"R3", "RESISTOR", "R800", "RESISTOR", "22H", " 5% ", 5.4, 9.9
"R3", "RESISTOR", "R806", "RESISTOR", "22H", " 5% ", 5.2, 9.9
"R3", "RESISTOR", "R801", "RESISTOR", "22H", " 5% ", 4.1, 9.9
"R3", "RESISTOR", "R807", "RESISTOR", "22H", " 5% ", 4, 9.9
"R3", "RESISTOR", "R809", "RESISTOR", "22H", " 5% ", 3.9, 9.9
"R3", "RESISTOR", "R810", "RESISTOR", "22H", " 5% ", 5.9, 11.1
"R3", "RESISTOR", "R804", "RESISTOR", "22H", " 5% ", 5.5, 11.2
"R3", "RESISTOR", "R805", "RESISTOR", "22H", " 5% ", 3.1, 11.2
"R3", "RESISTOR", "R811", "RESISTOR", "22H", " 5% ", 3.5, 11.2
"R3", "RESISTOR", "R812", "RESISTOR", "22H", " 5% ", 3.5, 11.8
"R3", "RESISTOR", "R803", "RESISTOR", "22H", " 5% ", 5.3, 13
"R3", "RESISTOR", "R802", "RESISTOR", "22H", " 5% ", 5.3, 12.3
"R3", "RESISTOR", "R610", "RESISTOR", "22H", " 5% ", 5.5, 7.6
"R3", "RESISTOR", "R606", "RESISTOR", "22H", " 5% ", 5.45, 7
"GE", "CAPACITOR", "C200", "GENSENGATE", "63V 470NF", " - ", .4, 8.75
"CI", "SRAM2KXB", "U1305", "CI.MEM", "2KX8EB", " - ", 3.2, 7.6
"CI", "SRAM2KXB", "U1405", "CI.MEM", "2KX8EB", " - ", 2.8, 7.6

"CN", "DS26C32C", "U1508", "CI.INTERF", "DS26C32C", " - ", 1.8, 3.9
 "CN", "DS26C32C", "U1608", "CI.INTERF", "DS26C32C", " - ", 1.4, 3.9
 "CN", "DS26C32C", "U1708", "CI.INTERF", "DS26C32C", " - ", 1, 3.9
 "CN", "DS26C32C", "U1808", "CI.INTERF", "DS26C32C", " - ", .6, 3.9
 "S1", "V12", "V12", "SIL", "3.3 KOHMS", " - ", 8.95, 5.4
 "R5", "RESISTOR", "R403", "RESISTOR", "100H", " 5% ", .6, 4.85
 "RG", "RGTR0", "RGTR0", "RGTR2", " - ", " - ", 8, 5.1
 "RG", "RGTR1", "RGTR1", "RGTR2", " - ", " - ", 6.2, 5.1
 "R3", "RESISTOR", "R1103", "RESISTOR", "22H", " 5% ", 4.95, 5.65
 "R3", "RESISTOR", "R1104", "RESISTOR", "22H", " 5% ", 4.95, 5.55
 "R3", "RESISTOR", "R1105", "RESISTOR", "22H", " 5% ", 4.95, 5.45
 "R3", "RESISTOR", "R1106", "RESISTOR", "22H", " 5% ", 4.95, 5.35
 "R3", "RESISTOR", "R1020", "RESISTOR", "22H", " 5% ", 4.95, 5.25
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 "R3", "RESISTOR", "R1014", "RESISTOR", "22H", " 5% ", 4.95, 5.05
 "R3", "RESISTOR", "R1013", "RESISTOR", "22H", " 5% ", 4.95, 4.95
 "R5", "RESISTOR", "R402", "RESISTOR", "100H", " 5% ", 4.95, 4.85
 "R1", "RESISTOR", "R406", "RESISTOR", "100K", " 5% ", 4.95, 4.75
 "R1", "RESISTOR", "R407", "RESISTOR", "100K", " 5% ", 4.95, 4.65
 "R3", "RESISTOR", "R1100", "RESISTOR", "22H", " 5% ", 4.35, 5.65
 "R3", "RESISTOR", "R702", "RESISTOR", "22H", " 5% ", 4.35, 5.55
 "R3", "RESISTOR", "R701", "RESISTOR", "22H", " 5% ", 4.35, 5.45
 "R3", "RESISTOR", "R1019", "RESISTOR", "22H", " 5% ", 4.35, 5.35
 "R3", "RESISTOR", "R1016", "RESISTOR", "22H", " 5% ", 4.35, 5.25
 "R3", "RESISTOR", "R1017", "RESISTOR", "22H", " 5% ", 4.35, 5.15
 "R3", "RESISTOR", "R1018", "RESISTOR", "22H", " 5% ", 4.35, 5.05
 "R5", "RESISTOR", "R400", "RESISTOR", "100H", " 5% ", 4.35, 4.85
 "R1", "RESISTOR", "R404", "RESISTOR", "100K", " 5% ", 4.35, 4.75
 "R1", "RESISTOR", "R405", "RESISTOR", "100K", " 5% ", 4.35, 4.65
 "RG", "RGTR2", "RGTR2", "RGTR2", " - ", " - ", 3.1, 5.1
 "RG", "RGTR3", "RGTR3", "RGTR2", " - ", " - ", 1.2, 5.1
 "R5", "RESISTOR", "R401", "RESISTOR", "100H", " 5% ", .6, 4.85
 "S1", "V11", "V11", "SIL", "3.3 KOHMS", " - ", .2, 5.2
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 "L2", "AC374", "U0206", "CI.LOGIQ", "74AC374", " - ", 8.4, 9.4
 "C2", "AC374", "U0306", "CI.LOGIQUE", "74ACT374", " - ", 8, 9.4
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 "C2", "AC374", "U0606", "CI.LOGIQUE", "74ACT374", " - ", 6.3, 9.4
 "L2", "AC374", "U0706", "CI.LOGIQ", "74AC374", " - ", 5.9, 9.4
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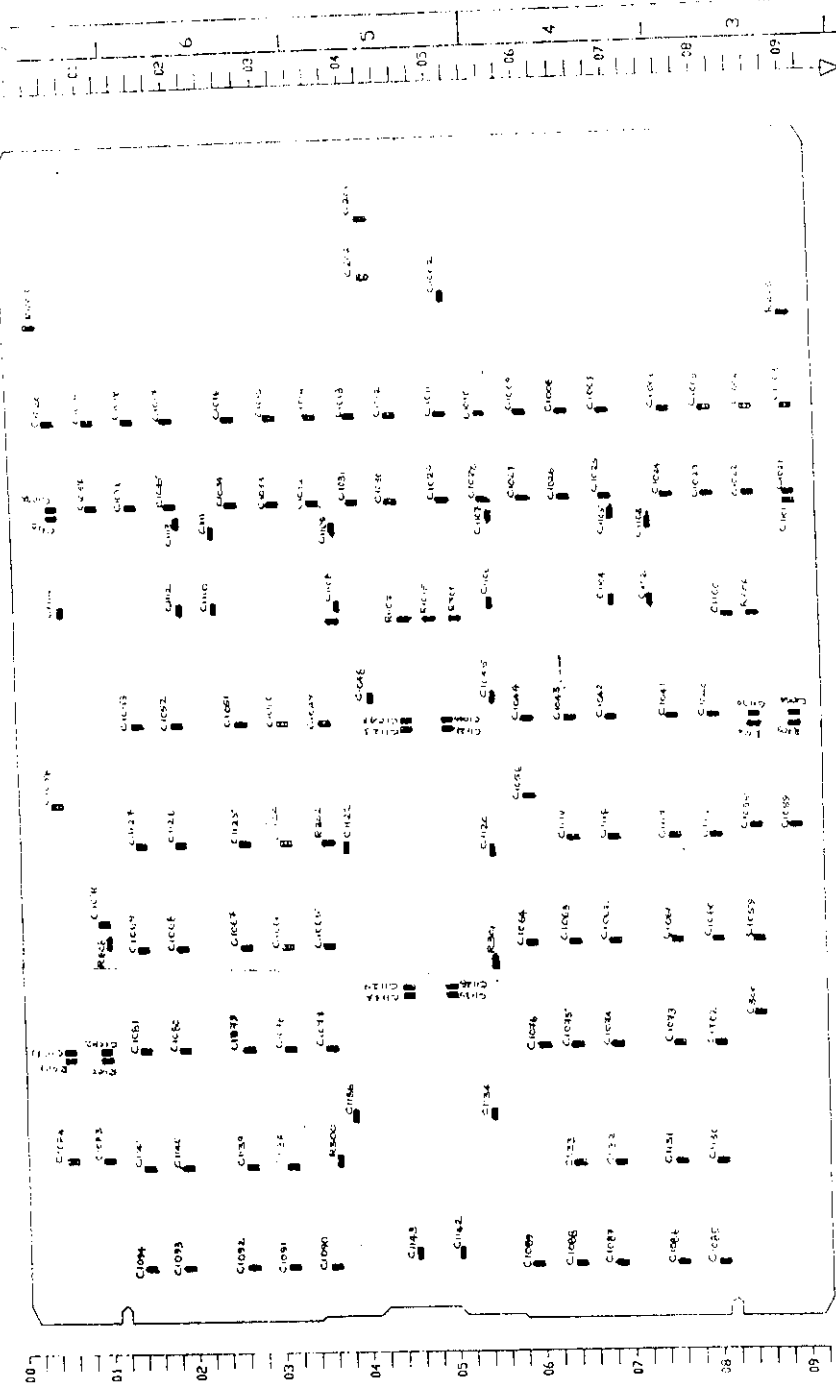
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 "CO", "CAPACITOR", "C1000", "COND", "16V 220UF", " - ", 8.4, 1
 "IN", "INDUCTOR", "L100", "INDUCT", "14UH", " 20% ", 8.3, .75
 "R4", "RESISTOR", "R209", "RESISTOR", "10K", " 5% ", 8.7, .9
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 "R4", "RESISTOR", "R211", "RESISTOR", "10K", " 5% ", 8.7, 1.1
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 "C1", "AC244", "U0109", "CI.LOGIQUE", "74AC244", " - ", 8.8, 2.85
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 "S1", "V13", "V13", "SIL", "3.3 KOHM", " - ", 4.6, 2.85
 "L2", "AC374", "U1009", "CI.LOGIQUE", "74AC374", " - ", 4.4, 2.85
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 "L2", "AC374", "U1209", "CI.LOGIQUE", "74AC374", " - ", 3.6, 2.85
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 "C1", "AC244", "U1809", "CI.LOGIQUE", "74AC244", " - ", .6, 2.85
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 "S2", "V15", "V15", "SIL H05", "8X10K", " - ", 4.6, 3.9
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 "CN", "DS26C32C", "U1408", "CI.INTERF", "DS26C32C", " - ", 2.8, 3.9

SPECIMEN COPY OF DATA FILES OF A RCMT BOARD

INDEX	NAME	CODE	VALUE	TOLERANCE	X	Y
"U1"	"RESISTOR"	"RR1000"	"RESEAU", "H29 5X0.047K"	" - "	8.3	1.7
"U1"	"RESISTOR"	"RR1001"	"RESEAU", "H29 5X0.047K"	" - "	8.1	1.7
"U1"	"RESISTOR"	"RR1002"	"RESEAU", "H29 5X0.047K"	" - "	7.7	1.7
"U1"	"RESISTOR"	"RR1003"	"RESEAU", "H29 5X0.047K"	" - "	7.5	1.7
"U1"	"RESISTOR"	"RR1004"	"RESEAU", "H29 5X0.047K"	" - "	7.3	1.7
"U1"	"RESISTOR"	"RR1005"	"RESEAU", "H29 5X0.047K"	" - "	6.9	1.7
"U1"	"RESISTOR"	"RR1006"	"RESEAU", "H29 5X0.047K"	" - "	6.7	1.7
"U1"	"RESISTOR"	"RR1007"	"RESEAU", "H29 5X0.047K"	" - "	6.5	1.7
"U1"	"RESISTOR"	"RR1008"	"RESEAU", "H29 5X0.047K"	" - "	6.3	1.7
"U1"	"RESISTOR"	"RR1009"	"RESEAU", "H29 5X0.047K"	" - "	6.1	1.7
"U1"	"RESISTOR"	"RR1010"	"RESEAU", "H29 5X0.047K"	" - "	5.9	1.7
"U1"	"RESISTOR"	"RR1011"	"RESEAU", "H29 5X0.047K"	" - "	5.7	1.7
"U1"	"RESISTOR"	"RR1012"	"RESEAU", "H29 5X0.047K"	" - "	5.5	1.7
"U1"	"RESISTOR"	"RR1013"	"RESEAU", "H29 5X0.047K"	" - "	5.3	1.7
"L1"	"AC14"	"AC14"	"IC.LOGIQ", "74AC14"	" - "	4.9	1.7
"U1"	"RESISTOR"	"RR1100"	"RESEAU", "H29 5X0.047K"	" - "	3.95	1.7
"U1"	"RESISTOR"	"RR1101"	"RESEAU", "H29 5X0.047K"	" - "	3.75	1.7
"U1"	"RESISTOR"	"RR1102"	"RESEAU", "H29 5X0.047K"	" - "	3.55	1.7
"U1"	"RESISTOR"	"RR1103"	"RESEAU", "H29 5X0.047K"	" - "	3.35	1.7
"U1"	"RESISTOR"	"RR1104"	"RESEAU", "H29 5X0.047K"	" - "	3.15	1.7
"U1"	"RESISTOR"	"RR1105"	"RESEAU", "H29 5X0.047K"	" - "	2.95	1.7
"U1"	"RESISTOR"	"RR1106"	"RESEAU", "H29 5X0.047K"	" - "	2.75	1.7
"U1"	"RESISTOR"	"RR1107"	"RESEAU", "H29 5X0.047K"	" - "	2.55	1.7
"U1"	"RESISTOR"	"RR1108"	"RESEAU", "H29 5X0.047K"	" - "	2.35	1.7
"U1"	"RESISTOR"	"RR1109"	"RESEAU", "H29 5X0.047K"	" - "	2	1.7
"U1"	"RESISTOR"	"RR1110"	"RESEAU", "H29 5X0.047K"	" - "	1.7	1.7
"U1"	"RESISTOR"	"RR1111"	"RESEAU", "H29 5X0.047K"	" - "	1.45	1.7
"U1"	"RESISTOR"	"RR1112"	"RESEAU", "H29 5X0.047K"	" - "	1.2	1.7
"U1"	"RESISTOR"	"RR1113"	"RESEAU", "H29 5X0.047K"	" - "	1	1.7
"R3"	"RESISTOR"	"R1108"	"RESISTANCE", "22H"	" 5% "	4.4	2.1
"R3"	"RESISTOR"	"R1107"	"RESISTANCE", "22H"	" 5% "	4.4	2
"R3"	"RESISTOR"	"R1101"	"RESISTANCE", "22H"	" 5% "	4.4	1.9
"R2"	"RESISTOR"	"R202"	"RESISTANCE", "220H"	" 5% "	4.4	1.6
"R3"	"RESISTOR"	"R205"	"RESISTANCE", "22H"	" 5% "	4.4	1.5
"R4"	"RESISTOR"	"R201"	"RESISTANCE", "10K"	" 5% "	4.4	1.4
"R3"	"RESISTOR"	"R204"	"RESISTANCE", "22H"	" 5% "	4.4	1.3
"R4"	"RESISTOR"	"R200"	"RESISTANCE", "10K"	" 5% "	4.4	1.2
"R2"	"RESISTOR"	"R203"	"RESISTANCE", "220H"	" 5% "	4.4	1.1
"R3"	"RESISTOR"	"R1009"	"RESISTANCE", "22H"	" 5% "	.5	2.1
"R3"	"RESISTOR"	"R1010"	"RESISTANCE", "22H"	" 5% "	.5	2
"R3"	"RESISTOR"	"R1011"	"RESISTANCE", "22H"	" 5% "	.5	1.9

1 1.570
 2 1.580
 3 1.590
 4 1.600
 5 1.610
 6 1.620
 7 1.630
 8 1.640
 9 1.650
 10 1.660
 11 1.670
 12 1.680
 13 1.690
 14 1.700
 15 1.710
 16 1.720
 17 1.730
 18 1.740
 19 1.750
 20 1.760
 21 1.770
 22 1.780
 23 1.790
 24 1.800
 25 1.810
 26 1.820
 27 1.830
 28 1.840
 29 1.850
 30 1.860
 31 1.870
 32 1.880
 33 1.890
 34 1.900
 35 1.910
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 37 1.930
 38 1.940
 39 1.950
 40 1.960
 41 1.970
 42 1.980
 43 1.990
 44 2.000
 45 2.010
 46 2.020
 47 2.030
 48 2.040
 49 2.050
 50 2.060
 51 2.070
 52 2.080
 53 2.090
 54 2.100
 55 2.110
 56 2.120
 57 2.130
 58 2.140
 59 2.150
 60 2.160
 61 2.170
 62 2.180
 63 2.190
 64 2.200
 65 2.210
 66 2.220
 67 2.230
 68 2.240
 69 2.250
 70 2.260
 71 2.270
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 83 2.390
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 86 2.420
 87 2.430
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 91 2.470
 92 2.480
 93 2.490
 94 2.500
 95 2.510
 96 2.520
 97 2.530
 98 2.540
 99 2.550
 100 2.560

ORIGINS
LONDON



RESISTANCE
RESISTOR
 CONDENSATEUR
CAPACITOR
 TRANSISTOR
TRANSISTOR

Capacitance
Resistors
Diodes

ED DATE	02	92-03-31
CHANGE NOTE	APPR. AUTH'D. JVA	
ORIGINAL LAYOUT	EQUIPEMENT DE CARTE RCMT4	
RCMT4	RCMT4	
AAC001036702HD EF	1/2	1

R2-BE001/01

ITI PROFILE

ITI LIMITED, PALAKKAD is engaged in the production of electronic switching exchanges of capacity varying from 256 to 20,000 lines. Presently, the unit is engaged in the production of digital trunk automatic exchanges namely E10B and OCB - 283 in collaboration with ALCATEL FRANCE. The total capacity of the unit has gone up to one million lines per annum.

Quality of the product has been considerably good. The uncompromising attitude to quality has fetched ITI, PALAKKAD the coveted self certification scheme for DTAX AND ISO - 9002 certification for IRQS, Mumbai. Over this year, the unit has grown to become one of the world class manufacturing plant, with the state of art FUJI SMT assembly time. PCB plant has the capacity to produce 1,44,000 square meters of PCB's per annum.